

Compal Confidential

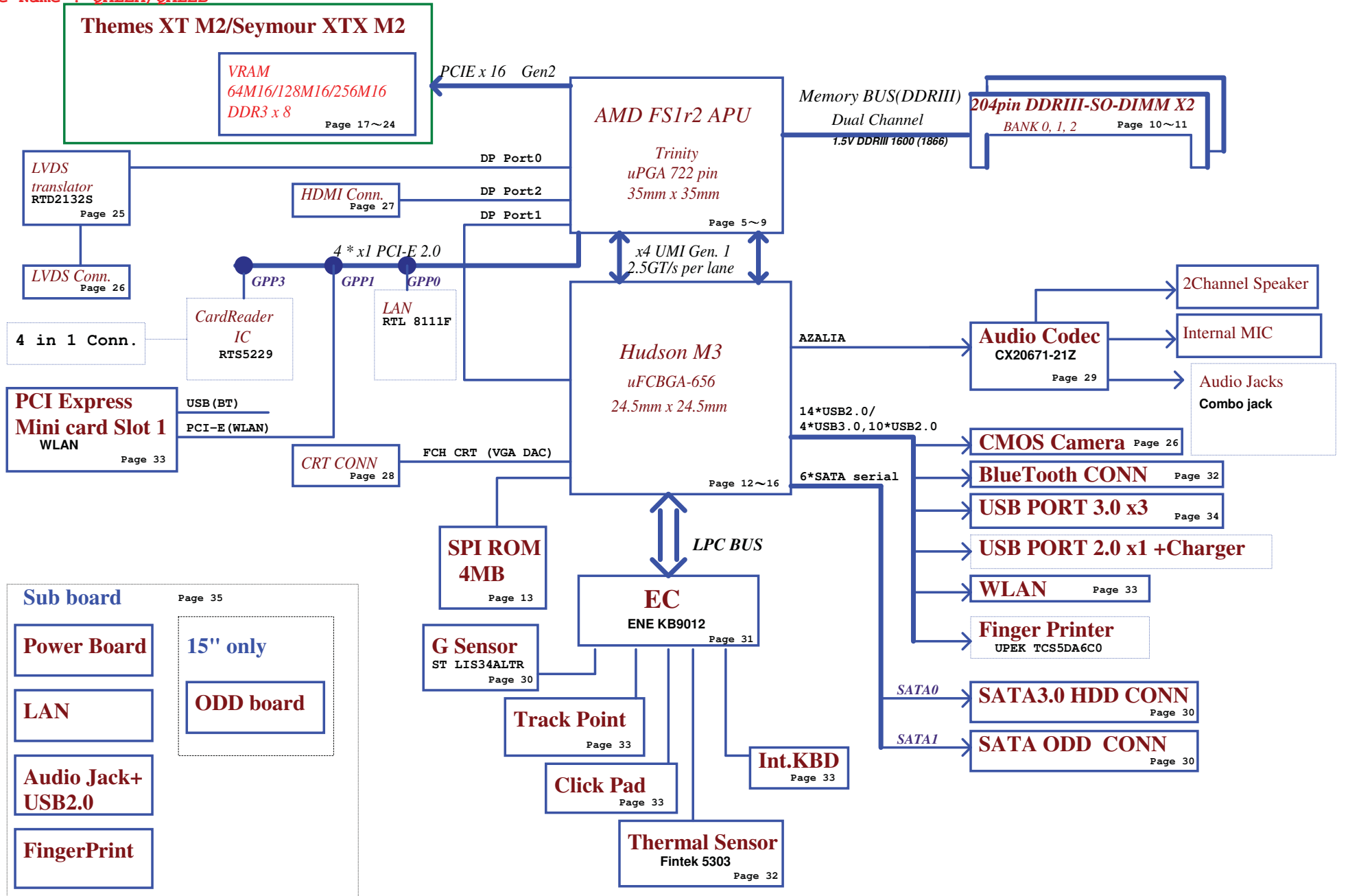
QALEA/QALEB Schematics Document

AMD APU Trinity FS1r2 + FCH Hudson-M3 + GPU Seymour XTX/Thames XT

2012-01-16

REV: 0.4

Security Classification	Compal Secret Data		Title		<i>Compal Electronics, Inc.</i>	
Issued Date	2011/04/18	Deciphered Date	2015/07/08	Cover Page		Rev
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.				Size	Document Number	0.4
				Date:	Monday, January 16, 2012	Sheet 1 of 50



<http://hobi-elektronika.net>

Security Classification		Compal Secret Data		Title	
Issued Date	2011/04/18	Deciphered Date	2015/07/08	Compal Electronics, Inc.	
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.				Size	Rev
				B	0.4
				Date:	Monday, January 16, 2012
				Sheet	2 of 50
				Block Diagrams	
				LA-8121P	

Voltage Rails

Power Plane	Description	S0	S3	S5
VIN	Adapter power supply (19V)	N/A	N/A	N/A
B+	AC or battery power rail for power circuit.	N/A	N/A	N/A
+APU_CORE	Core voltage for APU	ON	OFF	OFF
+APU_CORE_NB	Voltage for On-die VGA of APU	ON	OFF	OFF
+1.5V	1.5V power rail for APU VDDIO and DDR	ON	ON	OFF
+0.75VS	0.75V switched power rail for DDR terminator	ON	OFF	OFF
+1.2VS	1.2V (VDDR, VDDP) switched power rail for APU	ON	OFF	OFF
+2.5VS	2.5V for APU VDDA	ON	OFF	OFF
+1.1VALW	1.1V switched power rail for FCH	ON	ON	ON*
+1.1VS	1.1V switched power rail for FCH	ON	OFF	OFF
+1.5VS	1.5V switched power rail	ON	OFF	OFF
+VGA_CORE	0.95-1.2V switched power rail	ON	OFF	OFF
+1.5VGS	1.5V switched power rail	ON	OFF	OFF
+1.8VGS	1.8V switched power rail	ON	OFF	OFF
+1.0VGS	1.0V switched power rail for VGA	ON	OFF	OFF
+3VALW	3.3V always on power rail	ON	ON	ON*
+3VS_WLAN	3.3V power rail for WLAN	ON	OFF	OFF
+3VS	3.3V switched power rail	ON	OFF	OFF
+5VALW	5V always on power rail	ON	ON	ON*
+5VS	5V switched power rail	ON	OFF	OFF
+VSB	VSB always on power rail	ON	ON	ON*
+RTCVCC	RTC power	ON	ON	ON

Note : ON* means that this power plane is ON only with AC power available, otherwise it is OFF.

FCH Hudson-M2/3 SATA Port List

SATA0	HDD
SATA1	ODD
SATA2	NC
SATA3	NC
SATA4	NC
SATA5	NC

Comal PCIE Port List

		PCIE0	LAN
APU	PCIE1	WLAN	
	PCIE2	NC	
	PCIE3	Card Reader	
FCH	PCIE0	NC	
	PCIE1	NC	
	PCIE2	NC	
	PCIE3	NC	

FCH Hudson-M2/3 USB Port List

USB1.1	
Port0	NC
Port1	NC
USB2.0	
Port0	USB2.0 Port
Port1	NC
Port2	NC
Port3	NC
Port4	NC
Port5	WLAN
Port6	CMOS
Port7	FP
Port8	BT
Port9	NC
Port10	USB 3.0
Port11	USB 3.0
Port12	USB 3.0
Port13	NC

EC SM Bus1 address

EC SM Bus2 address

Device	Address	HEX	Device	Address	HEX
Smart Battery	0001-011xb	15H	F75303 (DDR,VRAM,CPUCORE)	1001-101xb	9AH
			SB-TSI	1001-100xb	98H
			Seymour XTX	1000-0010b	82H
			LVDS translator		

BOM Structure

UMA@ : UMA only
 DIS@ : DIS muxluss
 PX40@ : PX4.0 Support
 PX50@ : PX5.0 Support
 CMOS@ : USB camera

CONN@ : ME components
 X76@, H2G@, S2G@ : VRAM

Tha@ : Thames VGA
 Sey@ : Seymour VGA

BOM option and stencil

SDV:
 CMOS@/DIS@/PX40@/SEY@ + X76@

PJ201, PJ401, PJ502, PJ503, PJ504, PJ601, PJ603, PJ604,
 PJ701, PJ702, PJ703, PJ704, J1, J2301, J2401, J2402, J2403
 PJ402, PJ403, PJ501, PJ602, PJ801, PJ802, PJ803, PJ804, PJ805

FCH SMB0

(FCH_SMB0)

Device	Address	HEX
DDR DIMM1 (FCH_SMB0)	1001-000xb	90
DDR DIMM2 (FCH_SMB0)	1001-001xb	92
WLAN (FCH_SMB0)		
Security ROM		

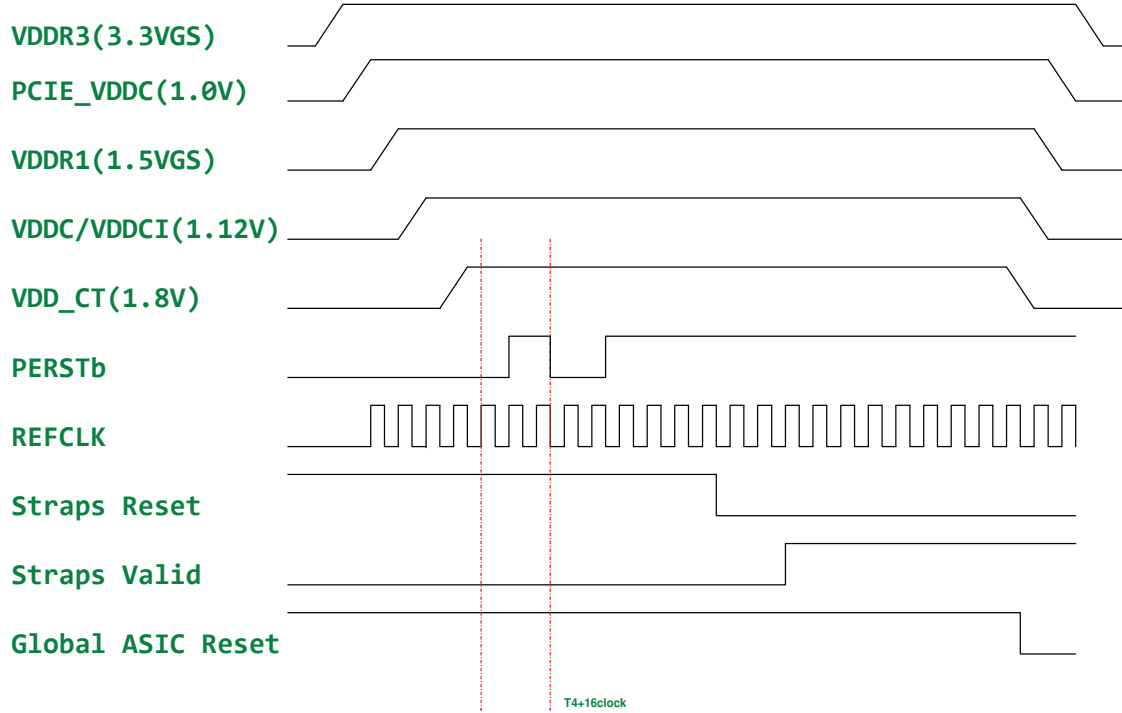
Stencil Memo

<http://hobi-elektronika.net>

Security Classification	Compal Secret Data		Title	
Issued Date	2011/04/18	Deciphered Date	2015/07/08	Compal Electronics, Inc.
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.				Notes List
Size B	Document Number	Date:	Monday, January 16, 2012	Rev 0.4
	LA-8121P	Sheet	3	of 50

Power-Up/Down Sequence

- All the ASIC supplies, except for VDDR3, must fully reach their respective nominal voltages within 20 ms of the start of the ramp-up sequence, though a shorter ramp-up duration is preferred. There is no timing requirement on the ramp up of VDDR3 relative to other power rails.
- The external pull-up resistors on the DDC/AUX signals (if applicable) should ramp up before or after both VDDC and VDD_CT have ramped up.
- VDDC and VDD_CT should not ramp up simultaneously. For example, VDDC should reach 90% before VDD_CT starts to ramp up (or vice versa).
- For power down, reversing the ramp-up sequence is recommended.



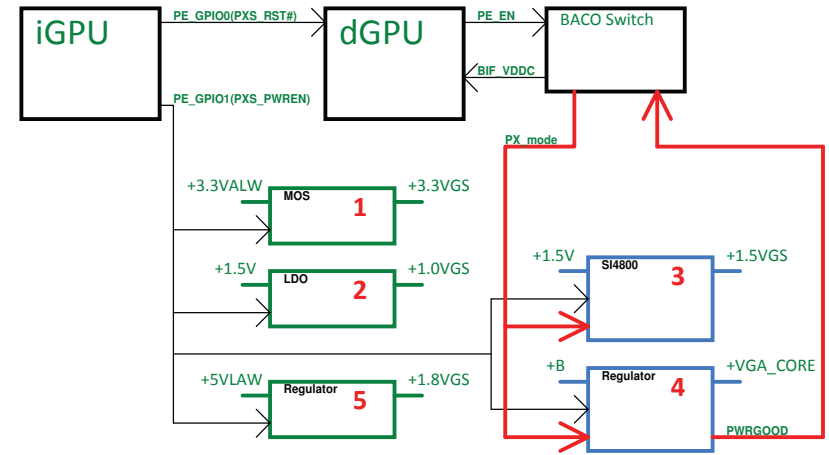
Without BACO option :

PE_GPIO0 : Low -> Reset dGPU ; High -> Normal operation
 PE_GPIO1 : Low -> dGPU Power OFF ; High -> dGPU Power ON

BACO option :

PE_GPIO0 : High -> Normal operation (dGPU is not reset on BACO mode)
 PE_GPIO1 : Low -> dGPU Power OFF ; High -> dGPU Power ON (always High)

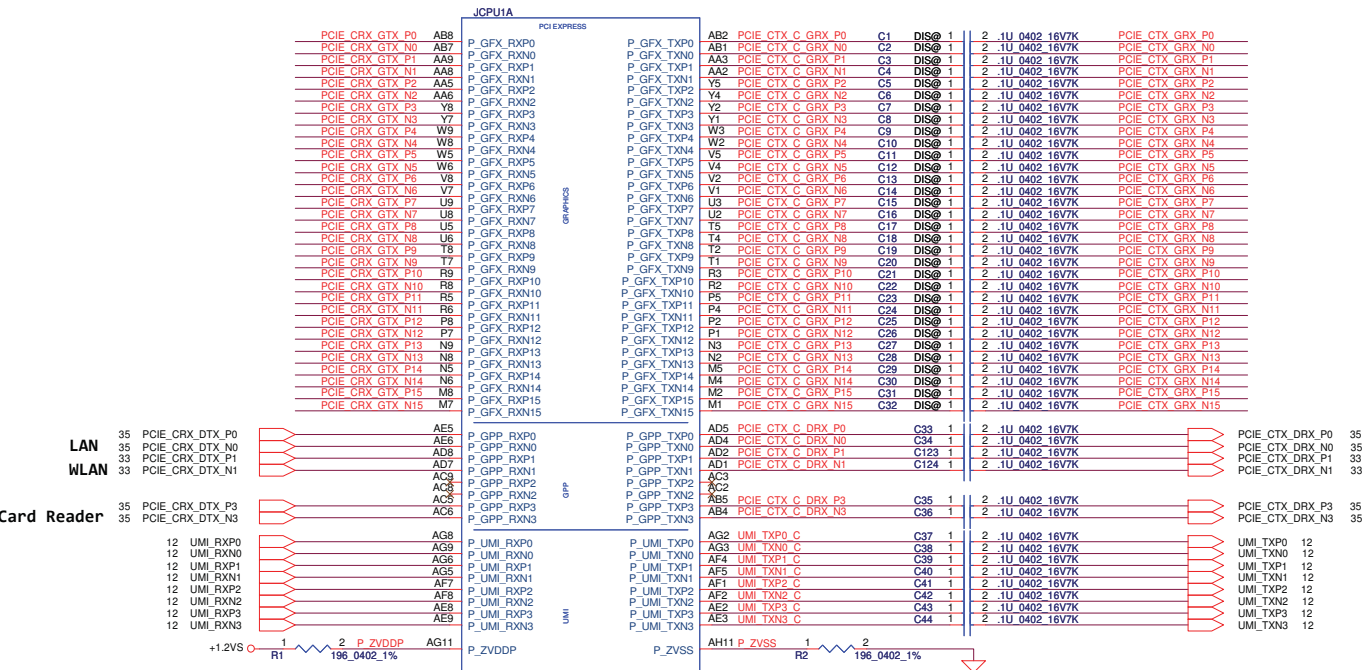
dGPU Power Pins	Voltage	PX 3.0	BACO Mode	Max current
PCIE_PVDD, PCIE_VDDR, TSVDD, VDDR4, VDD_CT, DPE_PVDD, DP[F:E]_VDD18, DP[D:A]_PVDD, DP[D:A]_VDD18, AVDD, VDD1D1, A2VDDQ, VDD2D1, DPLL_PVDD, MPV18, and SPV18	1.8V	OFF	ON	1679mA
DP[F:E]_VDD10, DP[D:A]_VDD10, DPLL_VDDC, and SPV10	1.0V	OFF	ON	775mA
PCIE_VDDC	1.0V	OFF	ON	1.1A
VDDR3	3.3V	OFF	ON	60mA
BIF_VDDC (current consumption = 55mA@1.0V, in BACO mode)	Same as VDDC	OFF	ON Same as PCIE_VDDC	70mA
VDDR1	1.5V	OFF	OFF	1.2A
VDDC/VDDCI	TBD	OFF	OFF	28



Security Classification		Compal Secret Data		Compal Electronics, Inc.	
Issued Date	2011/04/18	Deciphered Date	2015/07/08	Title	dGPU Block Diagram
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.				Document Number	LA-8121P
Date:	Monday, January 16, 2012	Sheet	4	of	50

17 PCIE_CRX_GTX_P0[0..15]
17 PCIE_CRX_GTX_N0[0..15]

PCIE_CTX_GRX_P0[0..15] 17
PCIE_CTX_GRX_N0[0..15] 17



LAN 35 PCIE_CRX_DTX_P0
35 PCIE_CRX_DTX_N0
33 PCIE_CRX_DTX_P1
33 PCIE_CRX_DTX_N1

WLAN 35 PCIE_CRX_DTX_P3
35 PCIE_CRX_DTX_N3

Card Reader 12 UMI_RXP0
12 UMI_RXN0
12 UMI_RXP1
12 UMI_RXN1
12 UMI_RXP2
12 UMI_RXN2
12 UMI_RXP3
12 UMI_RXN3

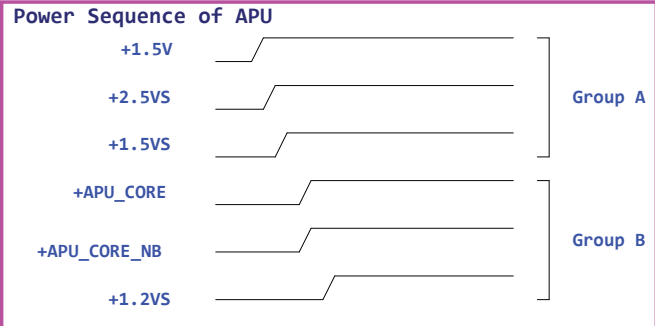
PCIE_CTX_DRX_P0 35
PCIE_CTX_DRX_N0 35
PCIE_CTX_DRX_P1 33
PCIE_CTX_DRX_N1 33

PCIE_CTX_DRX_P3 35
PCIE_CTX_DRX_N3 35

UMI_TXP0 12
UMI_TXN0 12
UMI_TXP1 12
UMI_TXN1 12
UMI_TXP2 12
UMI_TXN2 12
UMI_TXP3 12
UMI_TXN3 12

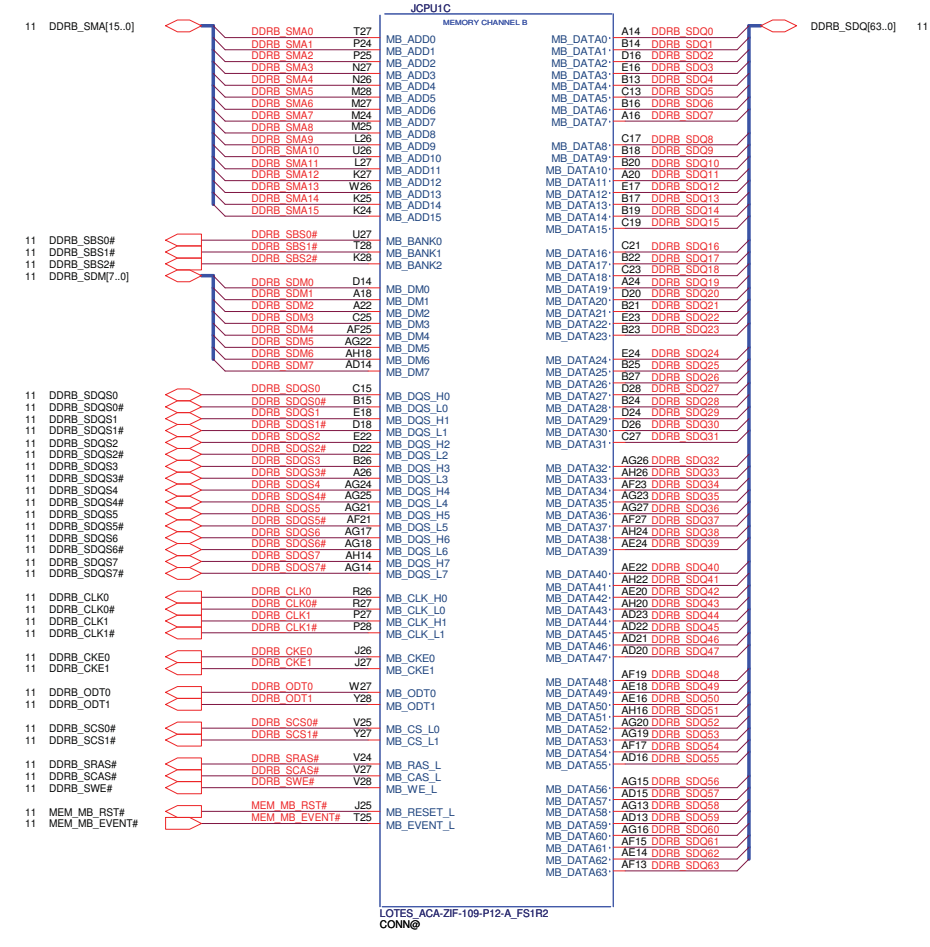
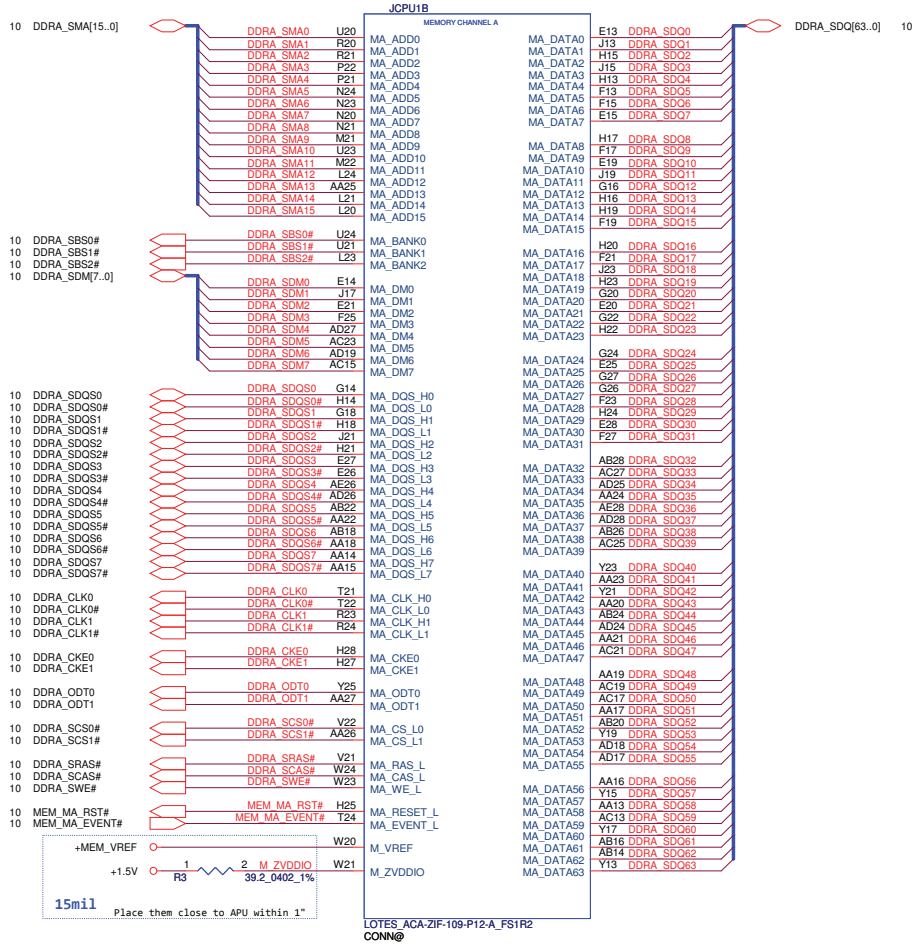


LOTES_ACA-ZIF-109-P12-A_FS1R2
CONN@



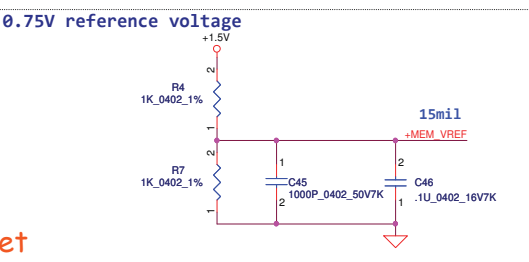
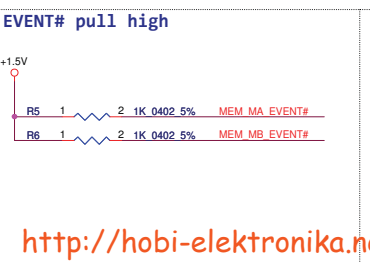
<http://hobi-elektronika.net>

Security Classification	Compal Secret Data		Title	
Issued Date	2011/04/18	Deciphered Date	2015/07/08	Compal Electronics, Inc.
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.				Size Custom
Date: Monday, January 16, 2012				Rev 0.4
Sheet 5 of 50				LA-8121P



LOTES_ACA-ZIF-109-P12-A_FS1R2 CONN@

LOTES_ACA-ZIF-109-P12-A_FS1R2 CONN@



<http://hobi-elektronika.net>

Security Classification		Compal Secret Data		Title	
Issued Date		2011/04/18		Deciphered Date	
		2015/07/08		2015/07/08	
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.					
Date: Monday, January 16, 2012				Sheet 6 of 50	

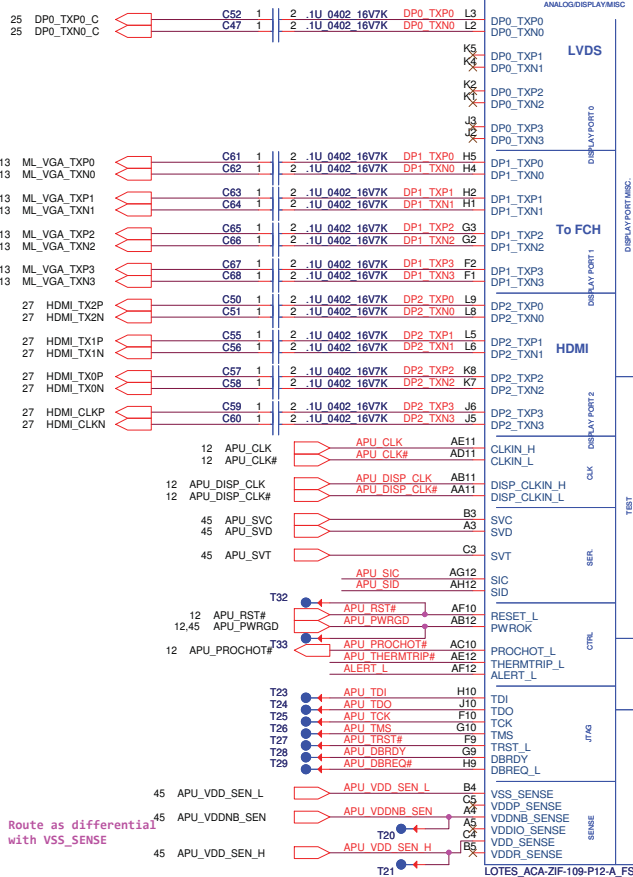
Compal Electronics, Inc.

FS1R2 DDRIII Memory I/F

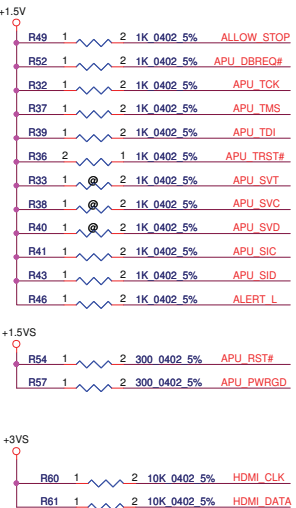
LA-8121P

Rev 0.4

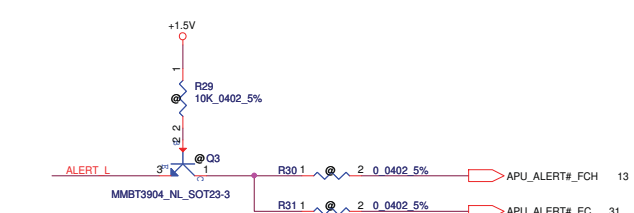
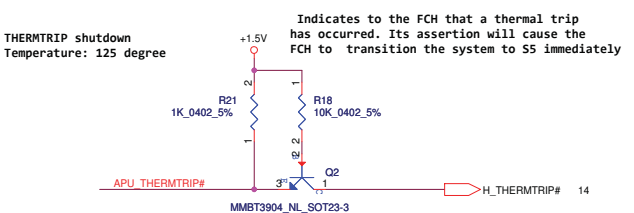
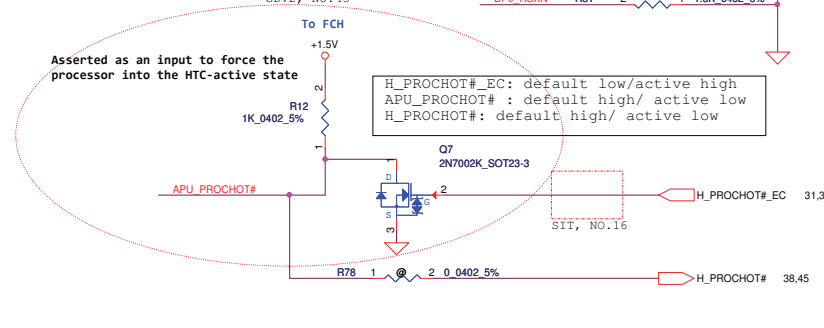
Place near APU



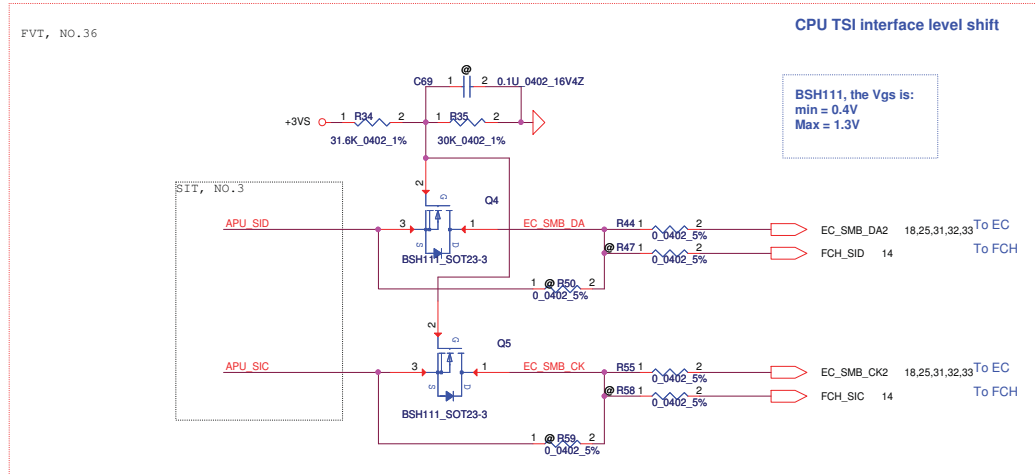
Route as differential with VSS_SENSE



Aux signal are re-configured as I2C signals for DDC. APU AUX pin are 3.3V tolerant. Do not use 10K resistor value for pull up.



CPU TSI interface level shift



Security Classification		Compal Secret Data	
Issued Date	2011/04/18	Deciphered Date	2015/07/08
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.			

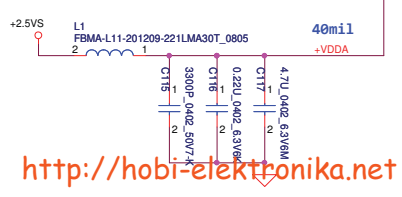
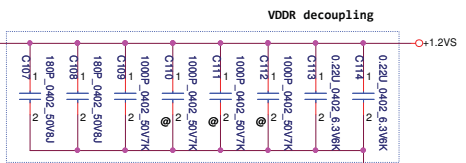
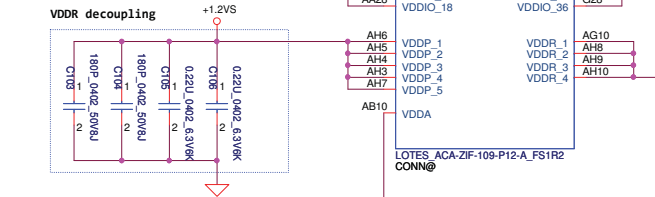
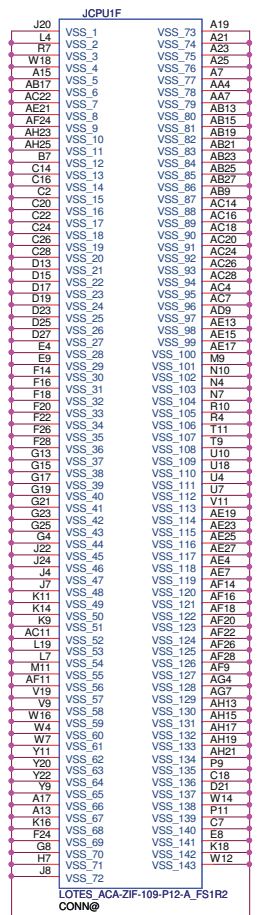
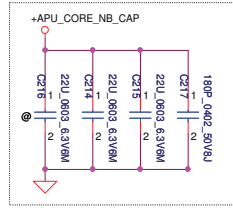
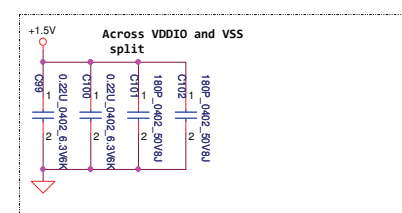
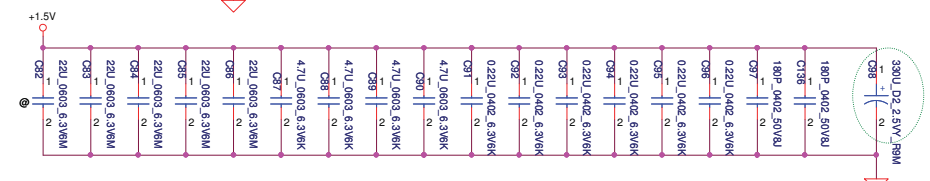
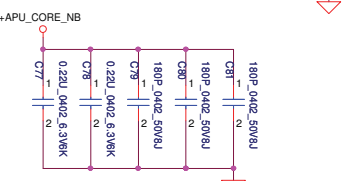
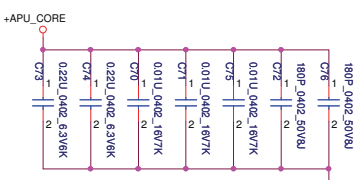
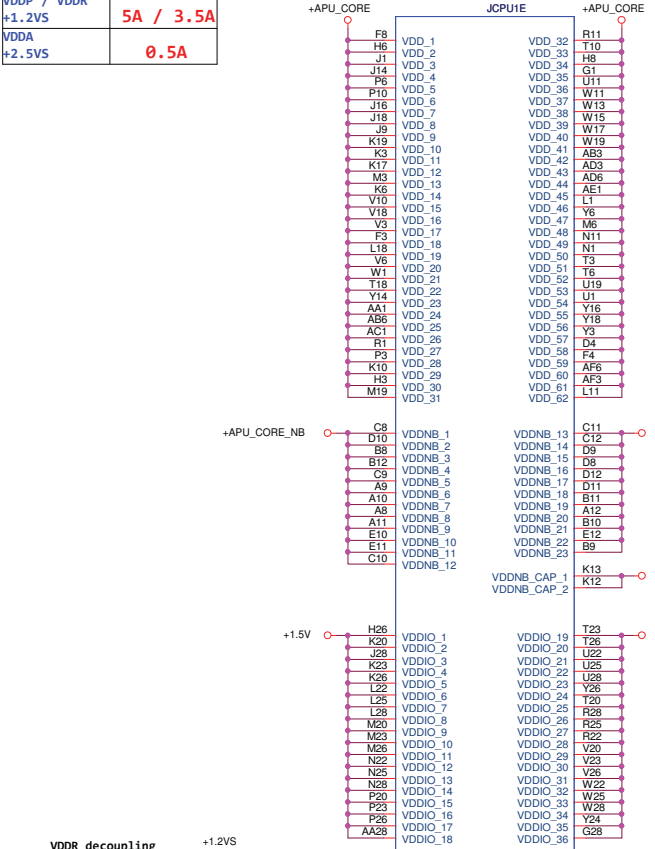
Compal Electronics, Inc.

FS1r2_Display/MISC/HDT

LA-8121P

Monday, January 16, 2012

Power Name	Consumption
VDD +APU_CORE	60A
VDDNB +APU_CORE_NB	44A
VDDIO +1.5V	3.2A
VDDP / VDDR +1.2VS	5A / 3.5A
VDDA +2.5VS	0.5A



Demo Board Capacitor

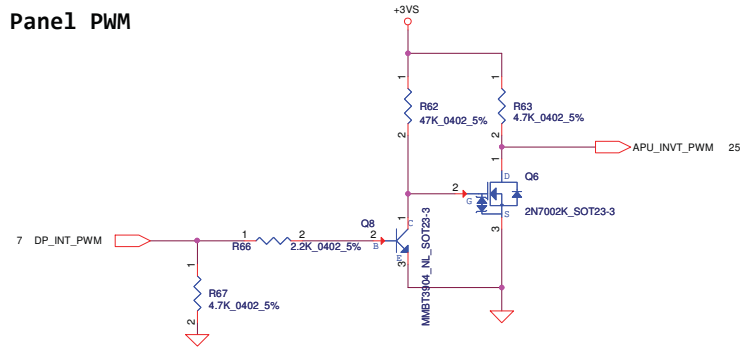
APU_CORE	CORE_NB	CORE_NB_CAP	VDDIO_SUS (CPU side)
22uF x 10	22uF x 2	22uF x 2	22uF x 4
0.22uF x 2	10uF x 1	180pF x 1	4.7uF x 4
0.01uF x 3	0.22uF x 2		0.22uF x 6 + 2(split)
180pF x 2	180pF x 3		180pF x 1 + 2(split)

VDDP	VDDR	VDDA	VDDIO_SUS (DIMM x2)
0.22uF x 2	0.22uF x 2	4.7uF x 1	100uF x 2
180pF x 2	1nF x 4	0.22uF x 1	0.1uF x 12
	180pF x 2	3.3nF x 1	

<http://hobi-elekttronika.net>

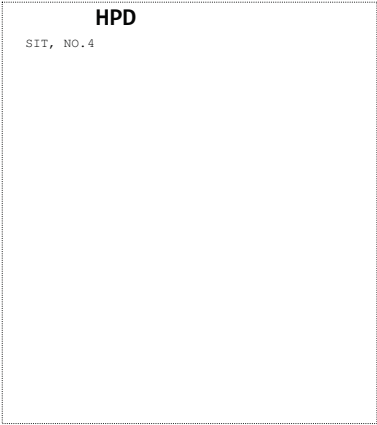
Security Classification		Compal Secret Data		Title	
Issued Date	2011/04/18	Deciphered Date	2015/07/08	FS1r2_PWR/GND	
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.					
Size	Document Number	Date		Rev	
Custom	LA-8121P	Monday, January 16, 2012		8 of 50	

Panel PWM

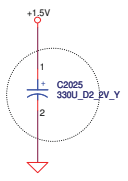
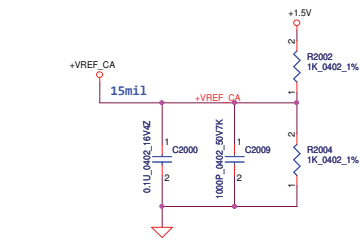
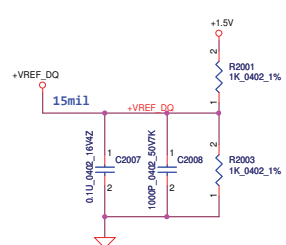
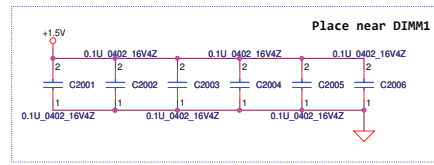
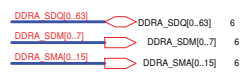
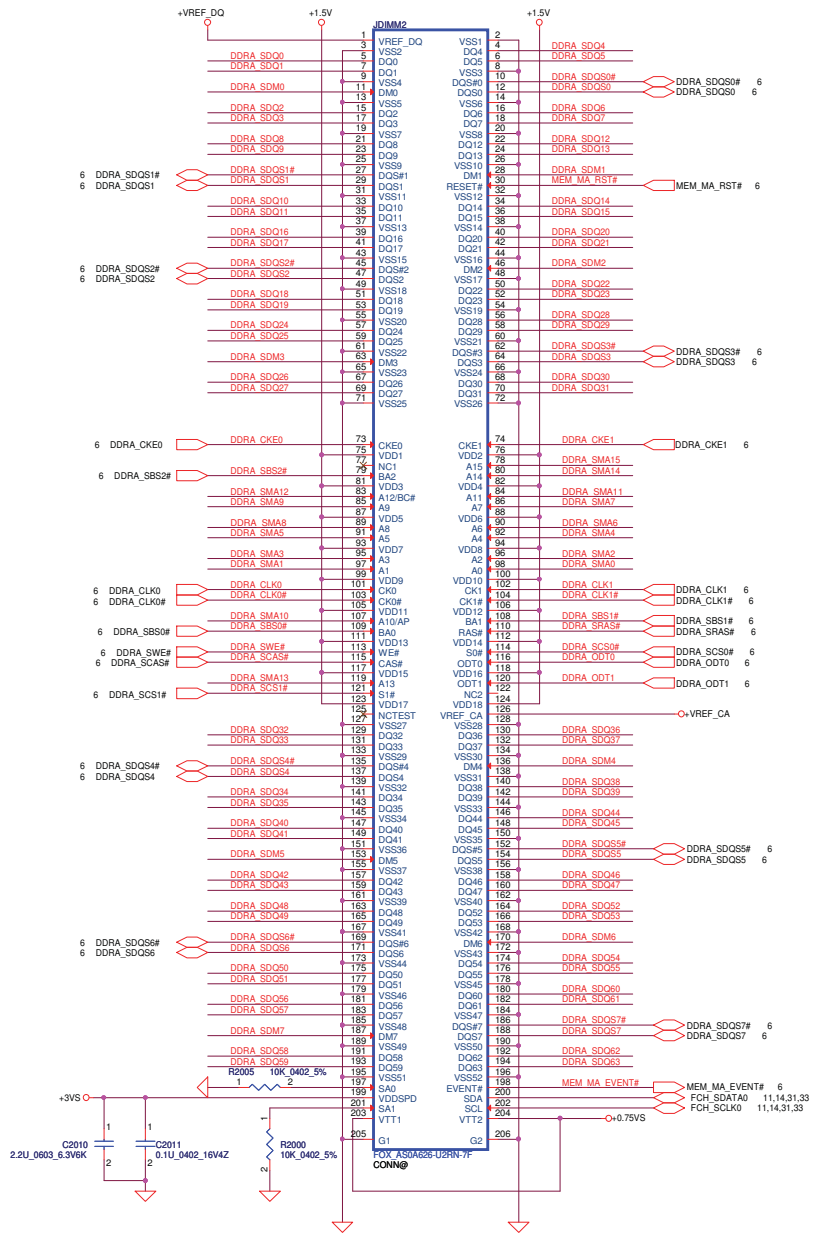


HPD

SIT, NO.4



Security Classification	Compal Secret Data			Compal Electronics, Inc. Title: FS1r2 Signal Level Shifter	
Issued Date	2011/04/18	Deciphered Date	2015/07/08		
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.				Document Number: LA-8121P Date: Monday, January 16, 2012	Rev: 0.4 Sheet: 9 of 50



Reverse H:5.2mm

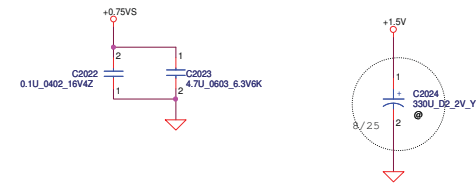
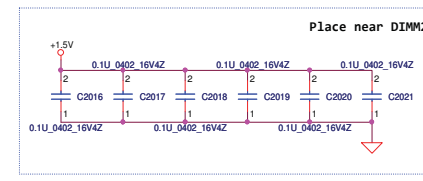
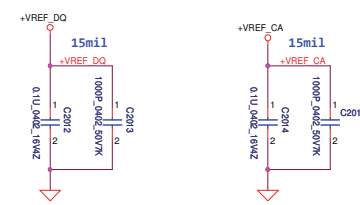
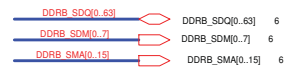
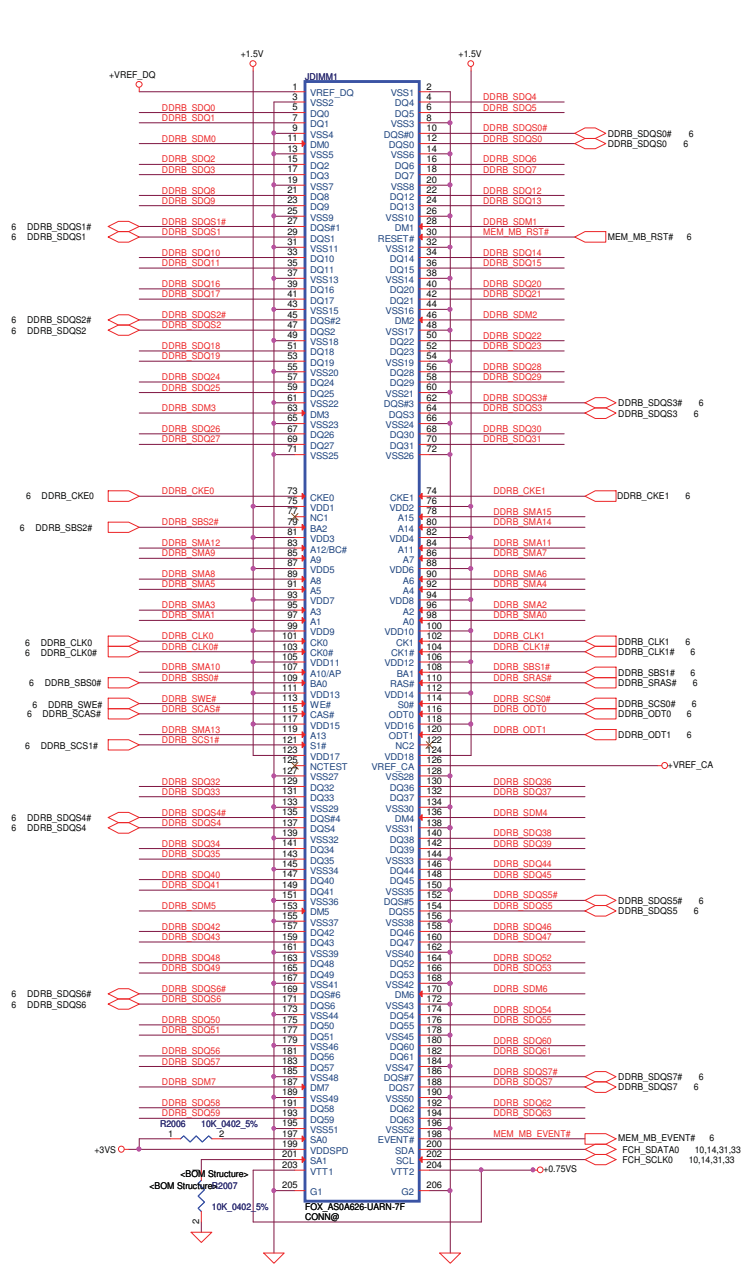
<http://hobi-elektronika.net>

Security Classification	Compal Secret Data		Title	Doc Number	Rev
Issued Date	2011/04/18	Deciphered Date			
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.					
Date:	Monday, January 16, 2012	Sheet	10	of	50

Compal Electronics, Inc.

DDRIT1 SO-DIMM 1

1A-8121P

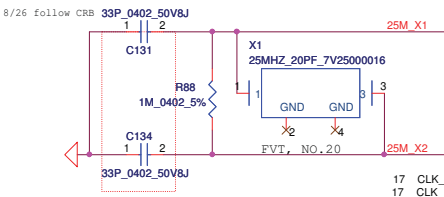
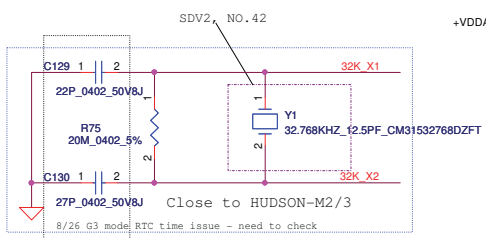
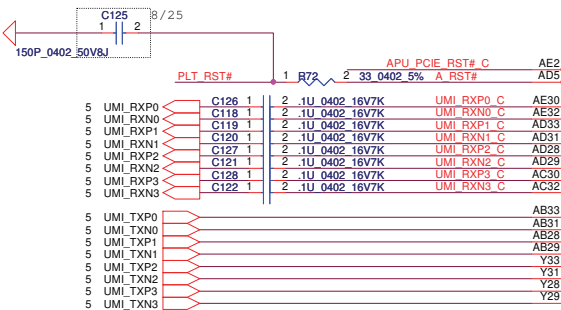


Reverse H: 9.2mm

<http://hobi-elektronika.net>

Security Classification	Compal Secret Data		Title	Compal Electronics, Inc.	
Issued Date	2011/04/18	Deciphered Date		2015/07/08	DDRIT1 SO-DIMM 2
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.					
Size	Document Number	Date		Monday, January 16, 2012	Sheet 11 of 50
C	IA-8121P				Rev 0.4

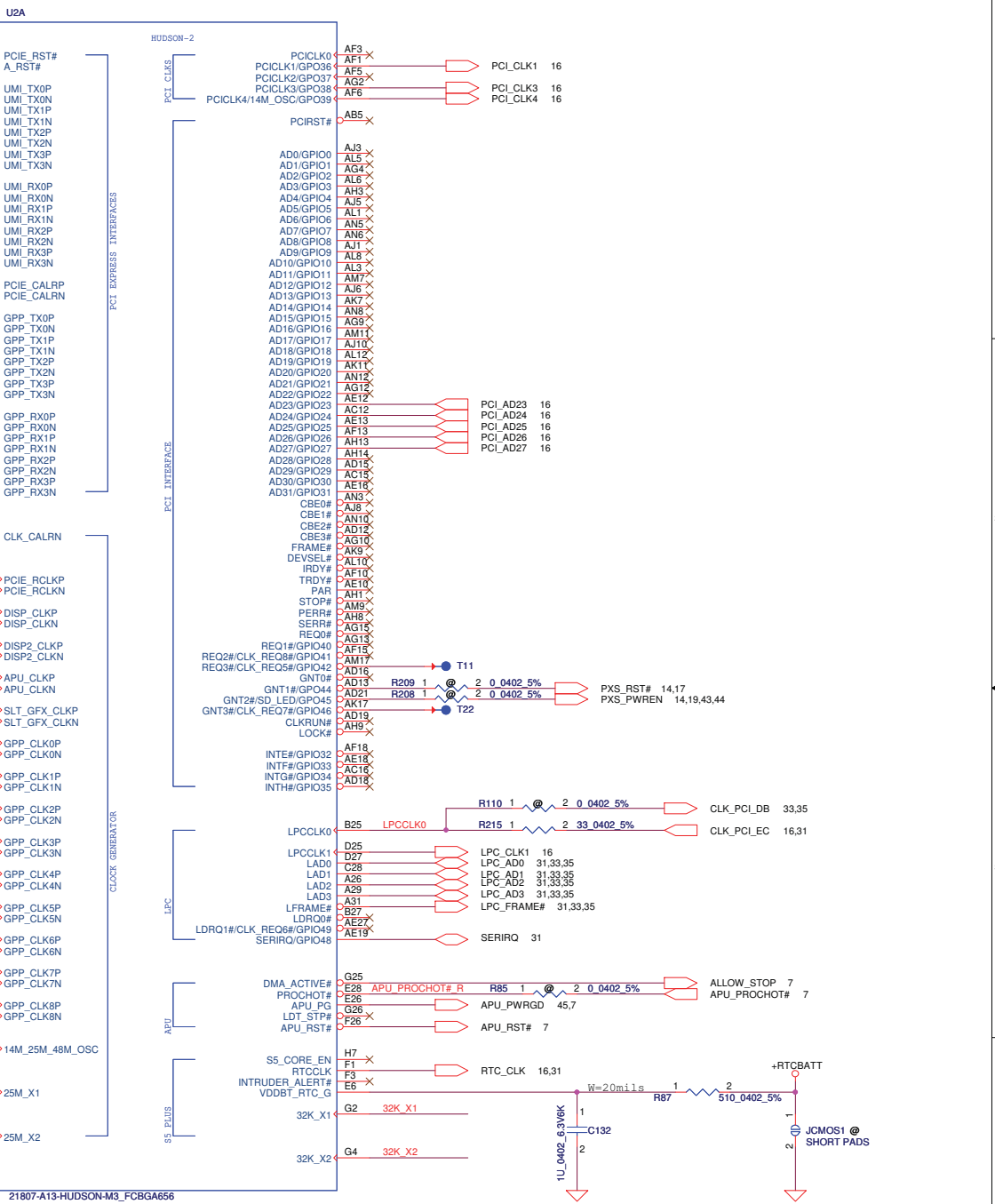
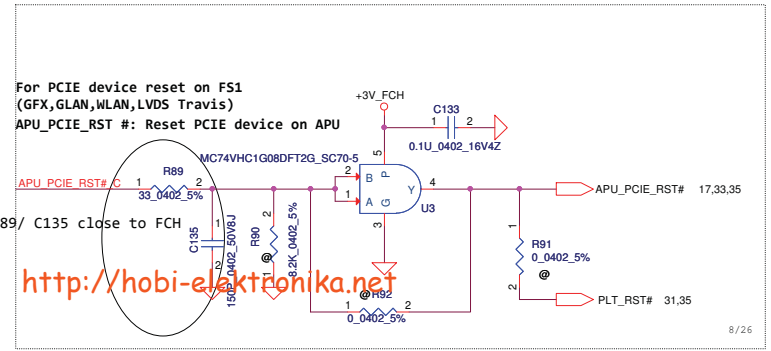
R90/ C146 close to FCH



WLAN

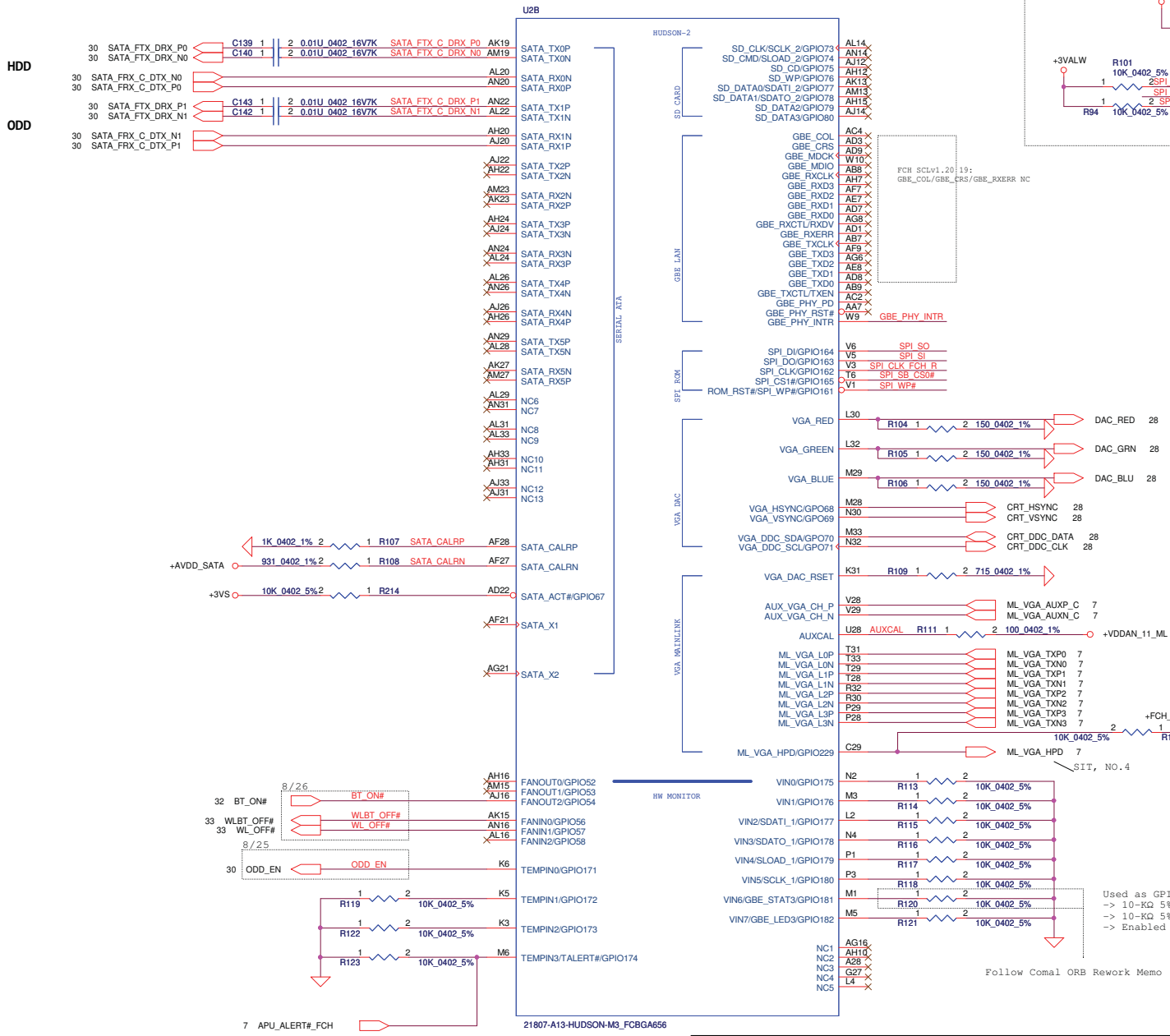
LAN

Card Reader

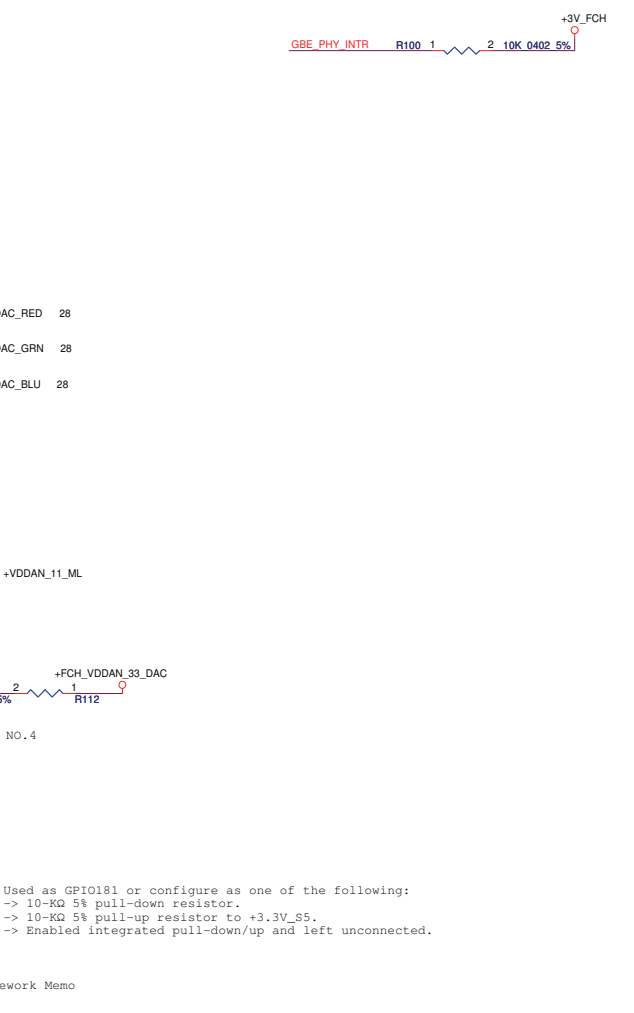
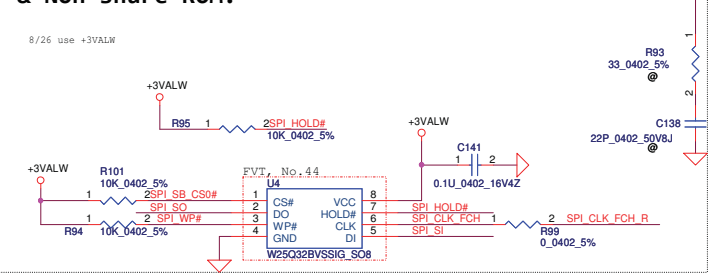


Security Classification	Compal Secret Data		2015/07/08		Title	
Issued Date	2011/04/18	Deciphered Date			FCH PCIE/CLK/PCI/LPC/RTC	
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.				Size	Document Number	Rev
				Custom	LA-8121P	0.4
				Date:	Monday, January 16, 2012	Sheet 12 of 50

<http://hobi-elektronika.net>



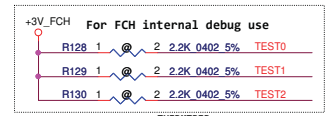
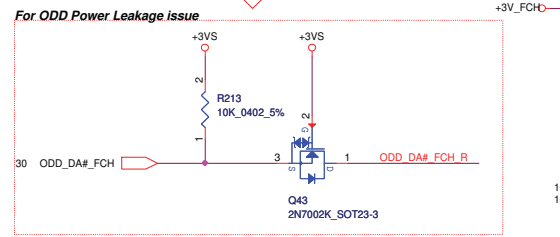
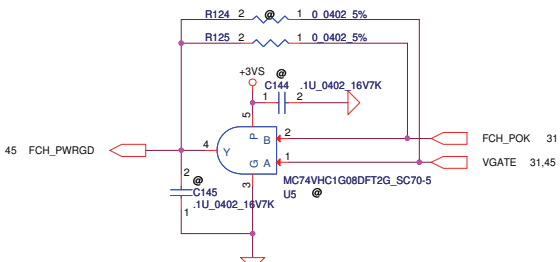
4MB SPI ROM & Non-share ROM.



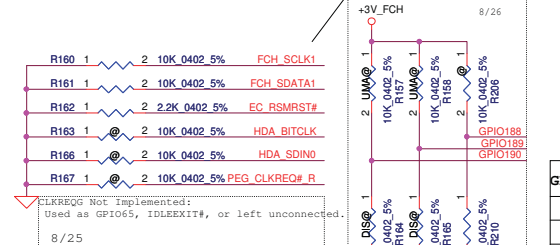
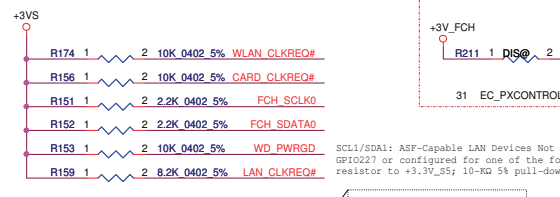
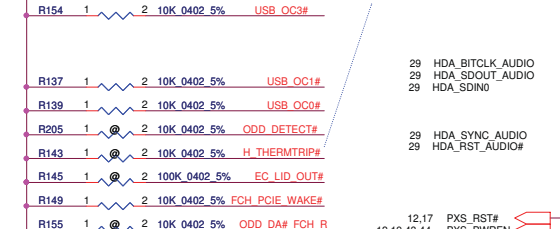
Used as GPIO181 or configure as one of the following:
 -> 10-KΩ 5% pull-down resistor.
 -> 10-KΩ 5% pull-up resistor to +3.3V_S5.
 -> Enabled integrated pull-down/up and left unconnected.

Follow Comal ORB Rework Memo

Security Classification		Compal Secret Data		Title	
Issued Date	2011/04/18	Deciphered Date	2015/07/08	FCH SATA/SPI/VGA/HWM/SD	
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.					
Size	Document Number	Date		Sheet	Rev
Custom	LA-8121P	Monday, January 16, 2012		13	0.4



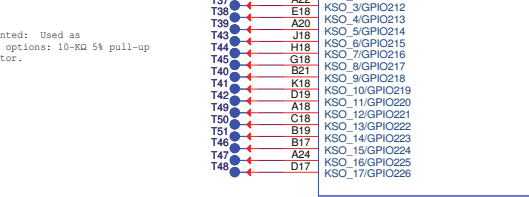
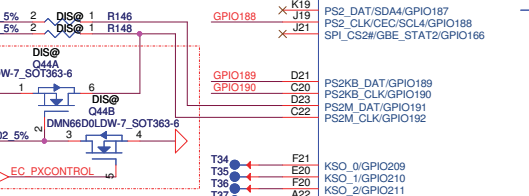
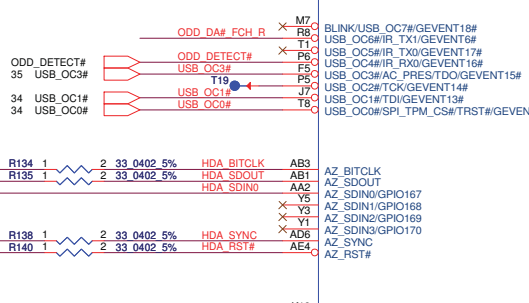
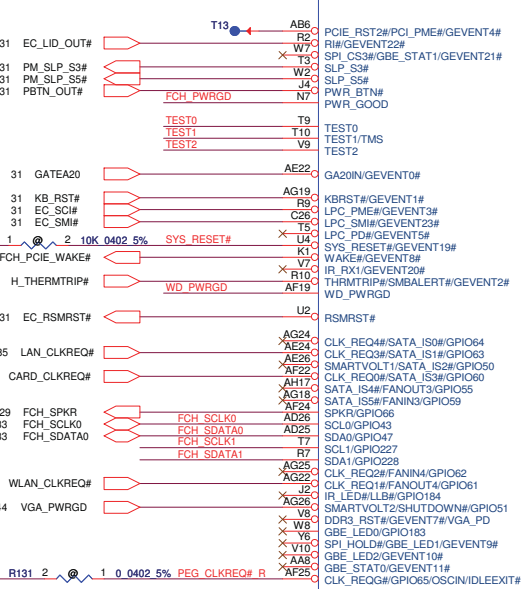
For FCH internal debug use
 8/16 AMD confirmed: The FCH already has internal PU resistor and don't need external PU resistor.
 Note: need BIOS check: Ensure FCH internal pull-up resistor to +3.3V 55 is disabled to prevent leakage when APU is powered down.



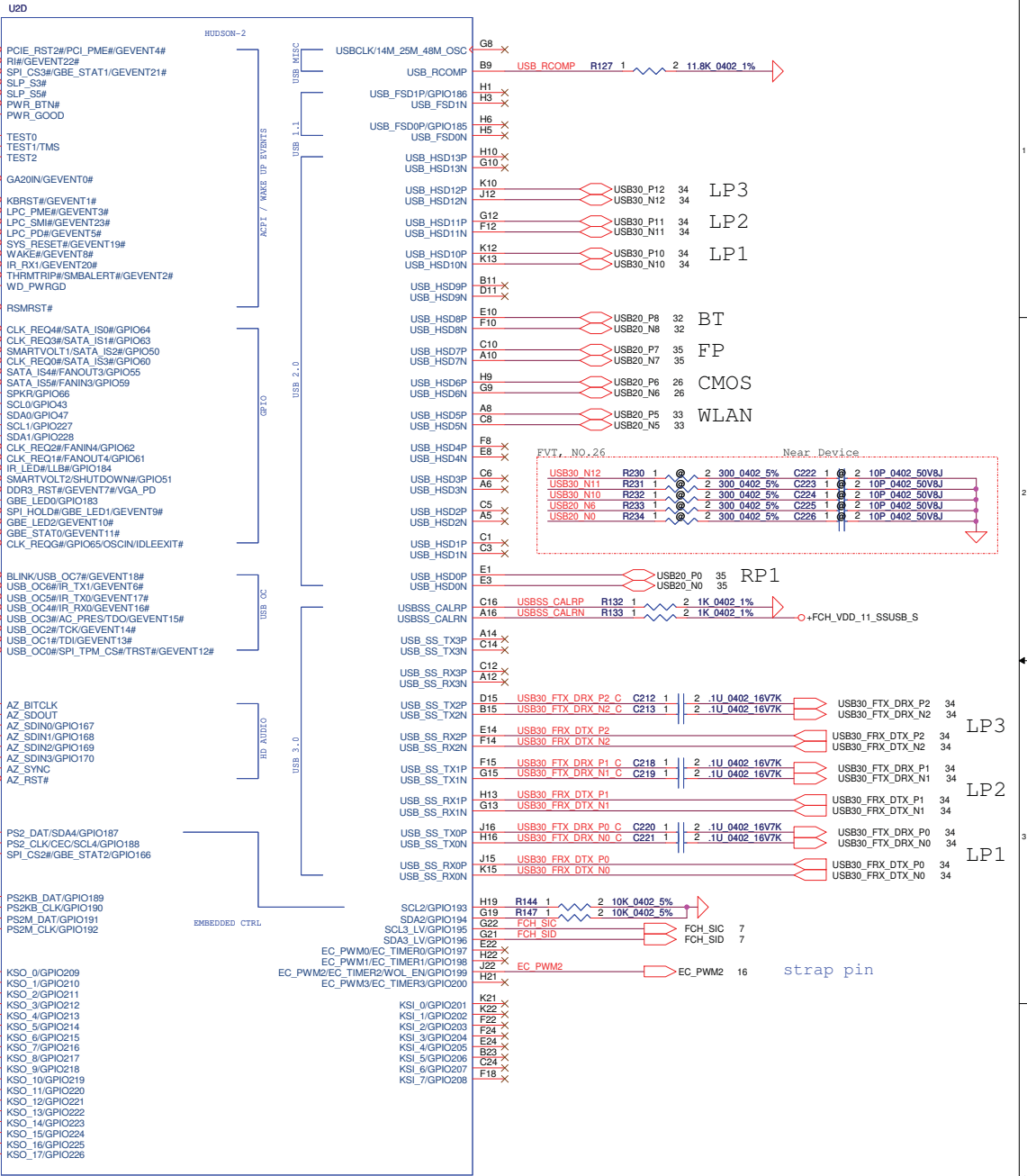
CLKREQ# Not Implemented:
 Used as GPIO65, IDLEEXIT#, or left unconnected.
 8/25

<http://hobi-elektronika.net>

PCIE_RST2 : Reset PCIE device on Hudson2/3

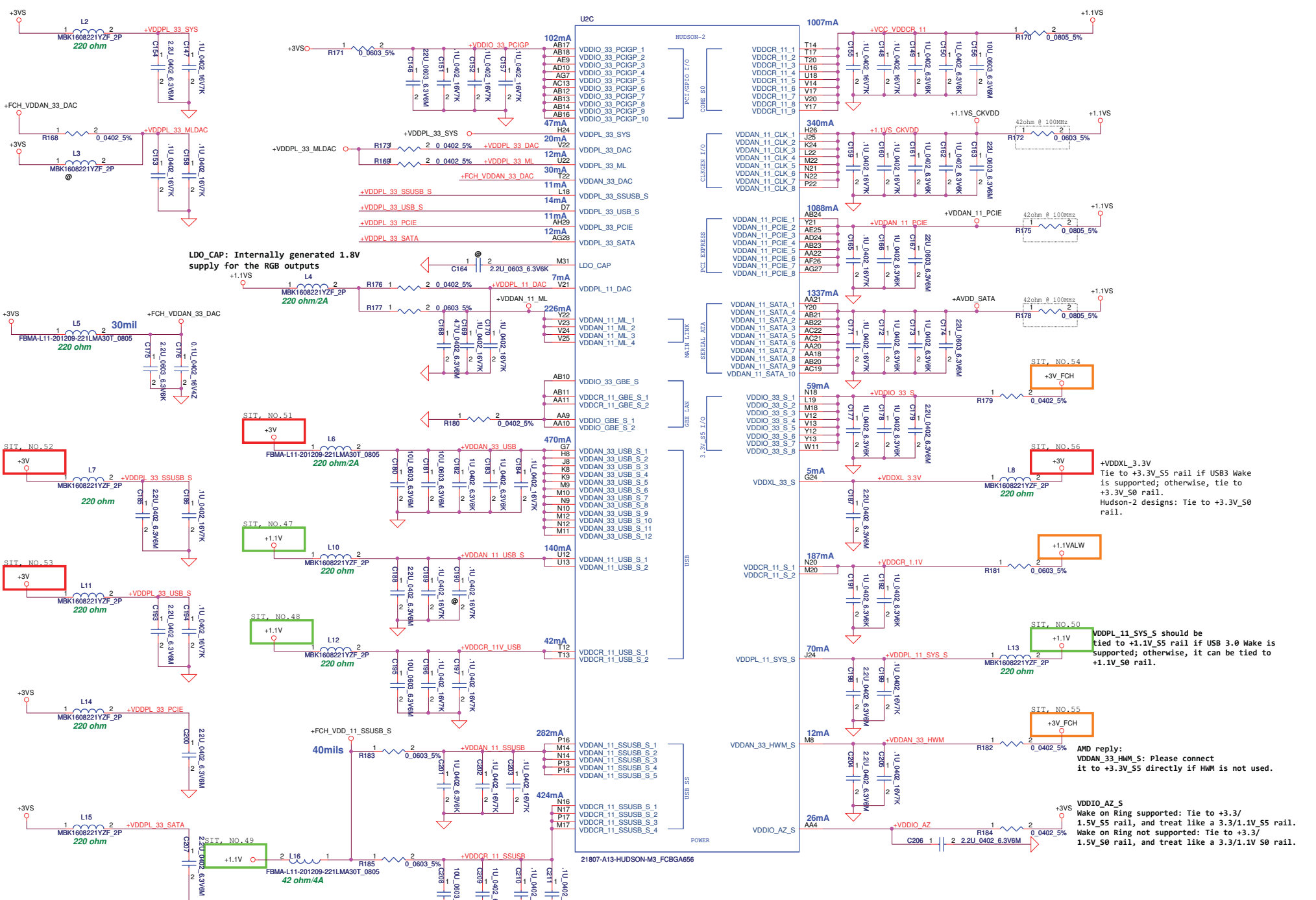


GPIO188	GPIO189	GPIO190	Function
0	0	0	PX
0	0	1	Reserved
0	1	0	DISCRET
0	1	1	UMA



21807-A13-HUDSON-M3_FCBGA655

Security Classification		Compal Secret Data		Title	
Issued Date	2011/04/18	Deciphered Date	2015/07/08	FCH SATA/SPI/VGA/HWM/SD	
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.				<p align="center">Compal Electronics, Inc.</p> <p align="center">LA-8121P</p>	
Size	Document Number	Rev	14 of 50		
Custom	LA-8121P	0.4	Monday, January 16, 2012		



LDO_CAP: Internally generated 1.8V supply for the RGB outputs

SIT, NO. 54

SIT, NO. 56

SIT, NO. 50

SIT, NO. 55

SIT, NO. 49

AMD reply: VDDAN_33_HWM_S: Please connect it to +3.3V_S5 directly if HWM is not used.

VDDIO_AZ_S Wake on Ring supported: Tie to +3.3V_S5 rail, and treat like a 3.3/1.1V_S5 rail. Wake on Ring not supported: Tie to +3.3V_S5 rail, and treat like a 3.3/1.1V_S0 rail.

<http://hobi-elektronika.net>

Security Classification		Compal Secret Data		Title	
Issued Date	2011/04/18	Deciphered Date	2015/07/08	FCH PWR	
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.					
Size	Document Number	Rev		0.4	
Custom	LA-8121P	Monday, January 16, 2012		Sheet 15 of 50	

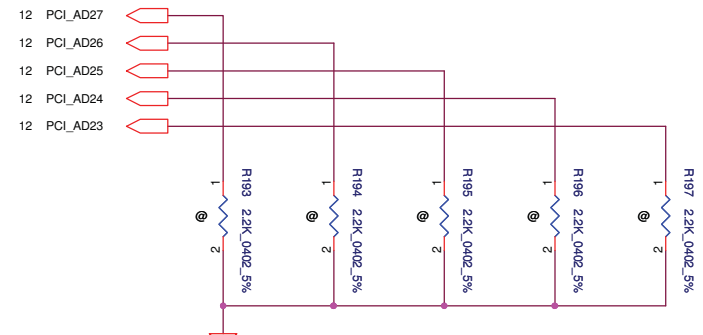
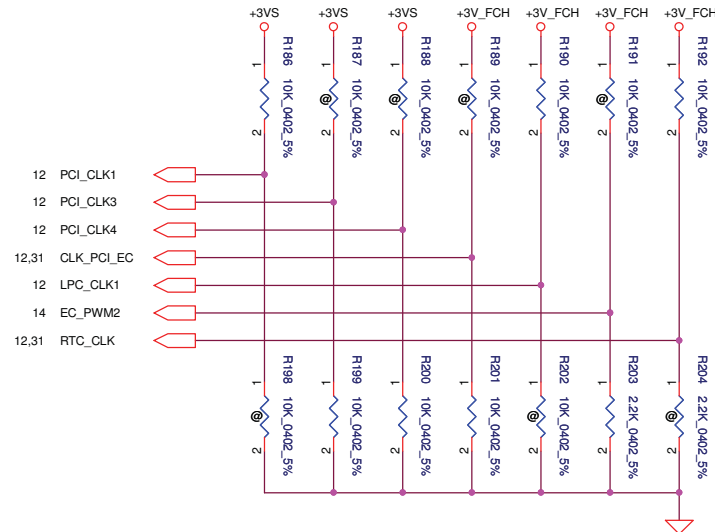
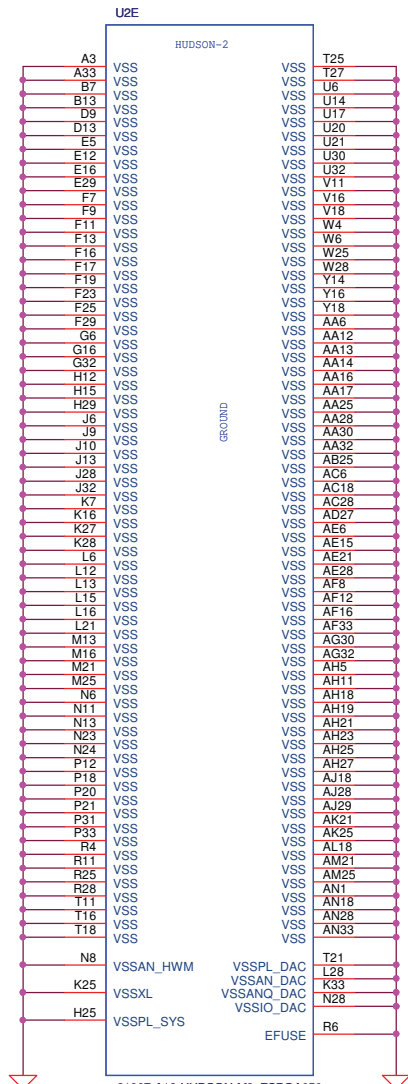
STRAP PINS

	PCI_CLK1	PCI_CLK3	PCI_CLK4	CLK_PCI_EC	LPC_CLK1	EC_PWM2	RTC_CLK
PULL HIGH	ALLOW PCIE GEN2 DEFAULT	USE DEBUG STRAPS	NON_FUSION CLOCK MODE	EC ENABLED	CLKGEN ENABLED	LPC ROM	S5 PLUS MODE DISABLED DEFAULT
PULL LOW	FORCE PCIE GEN1	IGNORE DEBUG STRAP DEFAULT	FUSION CLOCK MODE DEFAULT	EC DISABLED	CLKGEN DISABLE	SPI ROM DEFAULT	S5 PLUS MODE ENABLED

DEBUG STRAPS

FCH HAS 15K INTERNAL PU FOR PCI_AD[27:23]

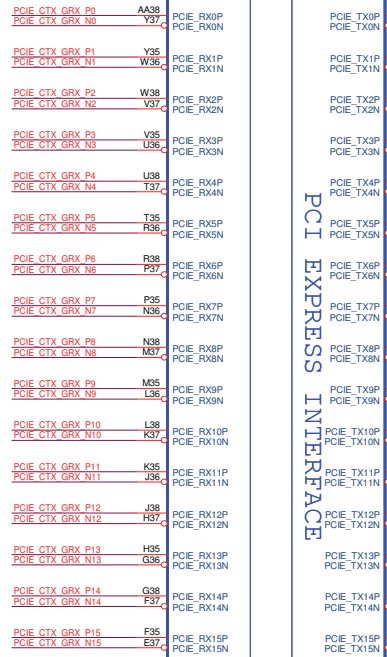
	PCI_AD27	PCI_AD26	PCI_AD25	PCI_AD24	PCI_AD23
PULL HIGH	USE PCI PLL DEFAULT	DISABLE ILA AUTORUN DEFAULT	USE FC PLL DEFAULT	USE DEFAULT PCIE STRAPS DEFAULT	DISABLE PCI MEM BOOT DEFAULT
PULL LOW	BYPASS PCI PLL	ENABLE ILA AUTORUN	BYPASS FC PLL	USE EEPROM PCIE STRAPS	ENABLE PCI MEM BOOT



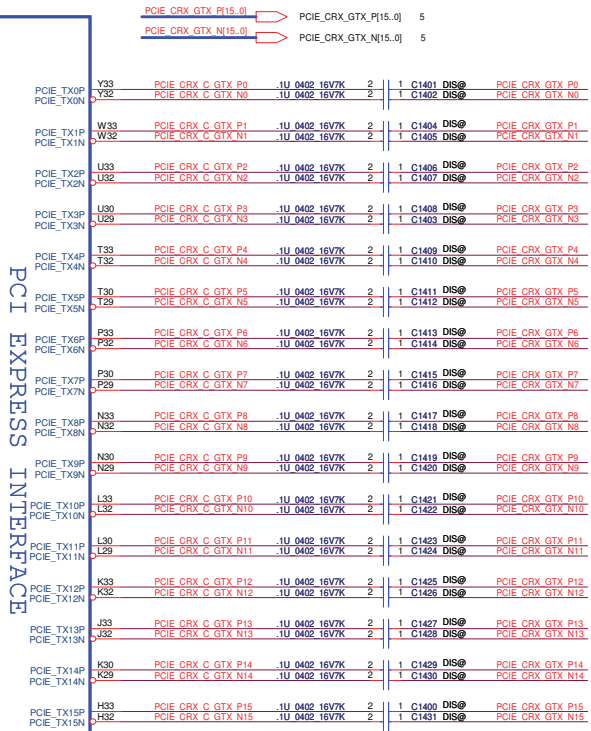
Security Classification	Compal Secret Data			Compal Electronics, Inc.	
Issued Date	2011/04/18	Deciphered Date	2015/07/08	Title	FCH-VSS/Strap
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.				Document Number	LA-8121P
				Date:	Monday, January 16, 2012
				Sheet	16 of 50

5 PCIE_CTX_GRX_P15_0] PCIE_CTX_GRX_P15_0] U1401A
 5 PCIE_CTX_GRX_N15_0] PCIE_CTX_GRX_N15_0] U1401A

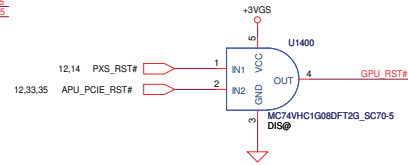
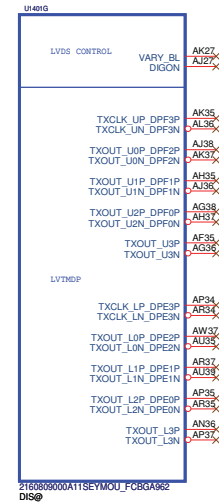
PCIE_CRX_GTX_P15_0] PCIE_CRX_GTX_P15_0] 5
 PCIE_CRX_GTX_N15_0] PCIE_CRX_GTX_N15_0] 5



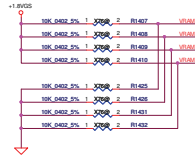
PCI EXPRESS INTERFACE



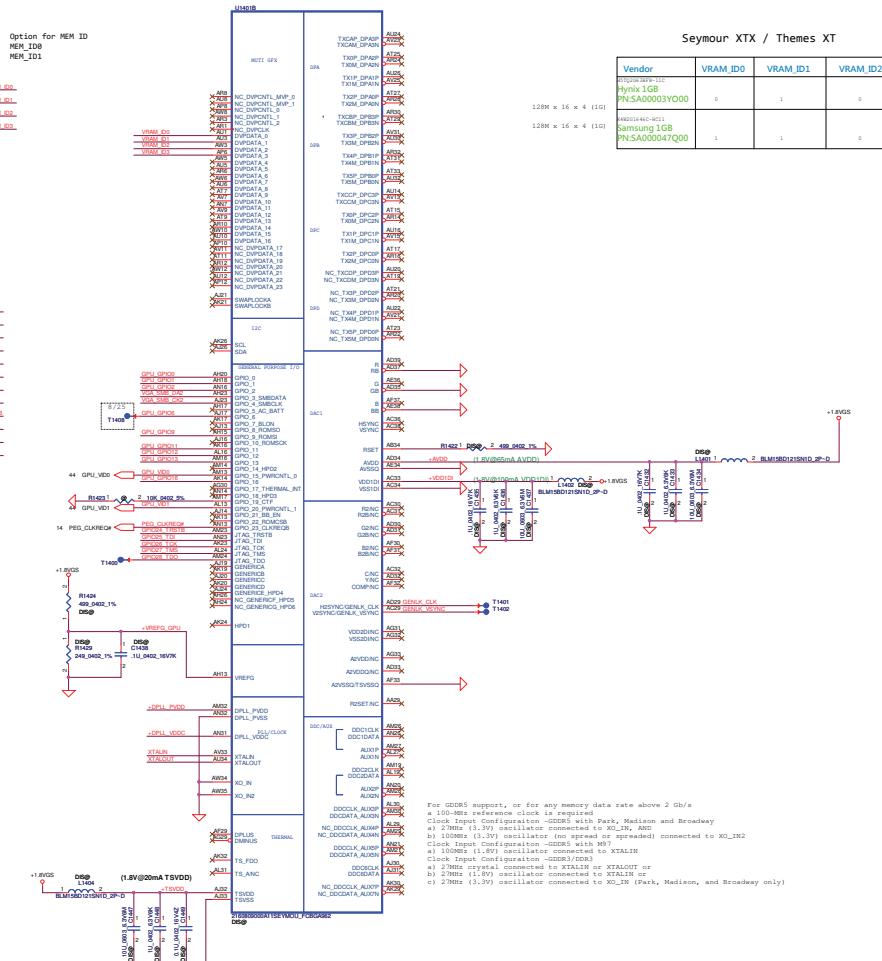
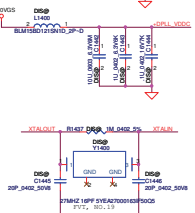
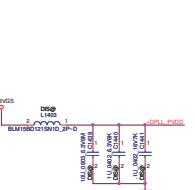
LVDS Interface



Option for MEM ID
MEM_ID0
MEM_ID1



STRAPS

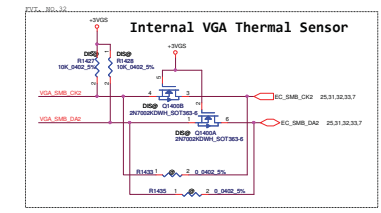


Seymour XT / Themes XT

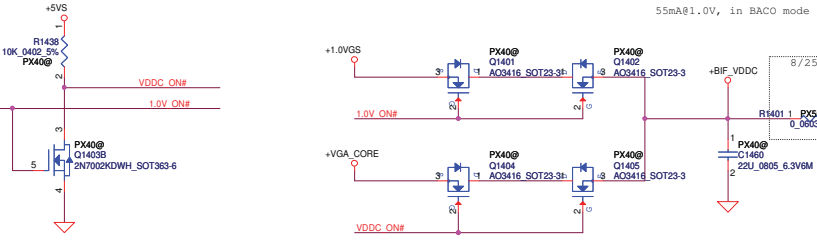
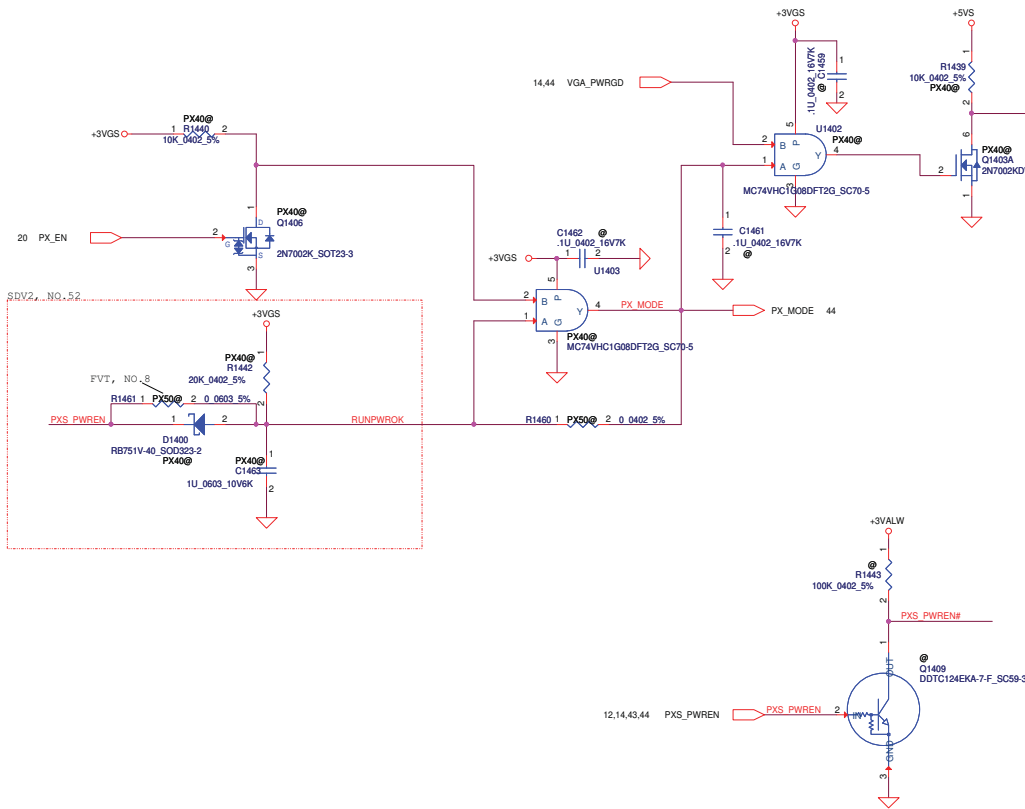
Vendor	VRAM_ID0	VRAM_ID1	VRAM_ID2
MT6370C02P010			
Hynix 1GB PNSA0003Y000	0	1	0
128M x 16 x 4 (1G)			
128M x 16 x 4 (1G)			
RAMSUNG 1GB PNSA00007A7000	1	1	0

For DDR3 support, or for any memory data rate above 2 Gb/s a 100-MHz reference clock is required.
Clock Input Configuration -DDR3 with Park, Madison and Broadway
a) 27MHz (1.8V) oscillator connected to RD_15V_A00
b) 100MHz (1.8V) oscillator (not spread or spreaded) connected to XTALIN
Clock Input Configuration -DDR3 with HPS
a) 100MHz (1.8V) oscillator connected to XTALIN
Clock Input Configuration -DDR3/DDR3L
a) 27MHz crystal connected to XTALIN or XTALOUT or
b) 27MHz (1.8V) oscillator connected to XTALIN or
c) 27MHz (1.8V) oscillator connected to RD_15V (Park, Madison, and Broadway only)

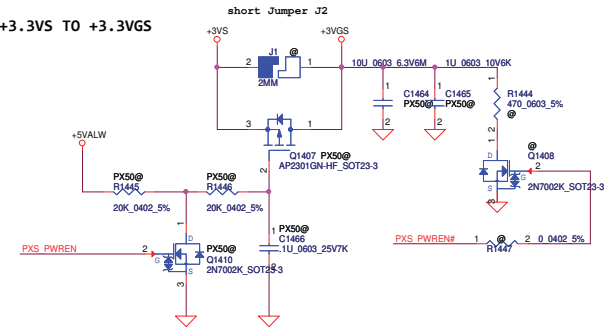
CONFIGURATION STRAPS -- SEE EACH DATABASE FOR STRAP DETAILS				
ALLOW FOR PULLUP PADS FOR THESE STRAPS AND IF THESE GPIOs ARE USED				
THEY MUST NOT CONFLICT DURING RESET				
STRAPS	MIPS	PN	DESCRIPTION OF DEFAULT SETTINGS	Default SETTINGS
MIPS_DISABLE	NA	GPIO_28_P00	1: Enable MIPS, NA for Themes/Chameleon/Seymour 0: Enable MIPS, enable GPIO Pinstrap 2: Enable MIPS, enable GPIO Pinstrap	X
TX_PWRM_ENB	PS_106	GPIO0	1: Enable Power Settings Enable 0: Fail to output swing	X
TX_DMAMP_EN	PS_105	GPIO1	1: TX de-emphasis disabled 0: TX de-emphasis enabled	X
BP_GEN2_EN_A	PS_170	GPIO2	1: BP GEN2 enabled at power-on 0: BP GEN2 disabled at power-on NOTE: Reserved for Themes/Chameleon/Seymour	1
BP_VGA_DS	PS_126	GPIO3	1: VGA controller capacity enabled 0: VGA controller capacity disabled (for multi-GPU)	0
ROMCFG000	PS_ID_11	GPIO13(11)	Serial ROM type or memory aperture size select 0: GDDR3 = 0, perform memory aperture size 1: GDDR3 = 1, perform ROM type 2: ROM = 02048 MEGABITS (CST) 3: ROM = 0M01 MEGABITS (CST) 4: ROM = 0M01 MEGABITS (CST) 5: ROM = 0M01 MEGABITS (CST) 6: ROM = 0M01 MEGABITS (CST) 7: ROM = 0M01 MEGABITS (CST) 8: ROM = 0M01 MEGABITS (CST) 9: ROM = 0M01 MEGABITS (CST) 10: ROM = 0M01 MEGABITS (CST) 11: ROM = 0M01 MEGABITS (CST) 12: ROM = 0M01 MEGABITS (CST) 13: ROM = 0M01 MEGABITS (CST) 14: ROM = 0M01 MEGABITS (CST) 15: ROM = 0M01 MEGABITS (CST) 16: ROM = 0M01 MEGABITS (CST) 17: ROM = 0M01 MEGABITS (CST) 18: ROM = 0M01 MEGABITS (CST) 19: ROM = 0M01 MEGABITS (CST) 20: ROM = 0M01 MEGABITS (CST) 21: ROM = 0M01 MEGABITS (CST) 22: ROM = 0M01 MEGABITS (CST) 23: ROM = 0M01 MEGABITS (CST) 24: ROM = 0M01 MEGABITS (CST) 25: ROM = 0M01 MEGABITS (CST) 26: ROM = 0M01 MEGABITS (CST) 27: ROM = 0M01 MEGABITS (CST) 28: ROM = 0M01 MEGABITS (CST) 29: ROM = 0M01 MEGABITS (CST) 30: ROM = 0M01 MEGABITS (CST) 31: ROM = 0M01 MEGABITS (CST) 32: ROM = 0M01 MEGABITS (CST) 33: ROM = 0M01 MEGABITS (CST) 34: ROM = 0M01 MEGABITS (CST) 35: ROM = 0M01 MEGABITS (CST) 36: ROM = 0M01 MEGABITS (CST) 37: ROM = 0M01 MEGABITS (CST) 38: ROM = 0M01 MEGABITS (CST) 39: ROM = 0M01 MEGABITS (CST) 40: ROM = 0M01 MEGABITS (CST) 41: ROM = 0M01 MEGABITS (CST) 42: ROM = 0M01 MEGABITS (CST) 43: ROM = 0M01 MEGABITS (CST) 44: ROM = 0M01 MEGABITS (CST) 45: ROM = 0M01 MEGABITS (CST) 46: ROM = 0M01 MEGABITS (CST) 47: ROM = 0M01 MEGABITS (CST) 48: ROM = 0M01 MEGABITS (CST) 49: ROM = 0M01 MEGABITS (CST) 50: ROM = 0M01 MEGABITS (CST) 51: ROM = 0M01 MEGABITS (CST) 52: ROM = 0M01 MEGABITS (CST) 53: ROM = 0M01 MEGABITS (CST) 54: ROM = 0M01 MEGABITS (CST) 55: ROM = 0M01 MEGABITS (CST) 56: ROM = 0M01 MEGABITS (CST) 57: ROM = 0M01 MEGABITS (CST) 58: ROM = 0M01 MEGABITS (CST) 59: ROM = 0M01 MEGABITS (CST) 60: ROM = 0M01 MEGABITS (CST) 61: ROM = 0M01 MEGABITS (CST) 62: ROM = 0M01 MEGABITS (CST) 63: ROM = 0M01 MEGABITS (CST) 64: ROM = 0M01 MEGABITS (CST) 65: ROM = 0M01 MEGABITS (CST) 66: ROM = 0M01 MEGABITS (CST) 67: ROM = 0M01 MEGABITS (CST) 68: ROM = 0M01 MEGABITS (CST) 69: ROM = 0M01 MEGABITS (CST) 70: ROM = 0M01 MEGABITS (CST) 71: ROM = 0M01 MEGABITS (CST) 72: ROM = 0M01 MEGABITS (CST) 73: ROM = 0M01 MEGABITS (CST) 74: ROM = 0M01 MEGABITS (CST) 75: ROM = 0M01 MEGABITS (CST) 76: ROM = 0M01 MEGABITS (CST) 77: ROM = 0M01 MEGABITS (CST) 78: ROM = 0M01 MEGABITS (CST) 79: ROM = 0M01 MEGABITS (CST) 80: ROM = 0M01 MEGABITS (CST) 81: ROM = 0M01 MEGABITS (CST) 82: ROM = 0M01 MEGABITS (CST) 83: ROM = 0M01 MEGABITS (CST) 84: ROM = 0M01 MEGABITS (CST) 85: ROM = 0M01 MEGABITS (CST) 86: ROM = 0M01 MEGABITS (CST) 87: ROM = 0M01 MEGABITS (CST) 88: ROM = 0M01 MEGABITS (CST) 89: ROM = 0M01 MEGABITS (CST) 90: ROM = 0M01 MEGABITS (CST) 91: ROM = 0M01 MEGABITS (CST) 92: ROM = 0M01 MEGABITS (CST) 93: ROM = 0M01 MEGABITS (CST) 94: ROM = 0M01 MEGABITS (CST) 95: ROM = 0M01 MEGABITS (CST) 96: ROM = 0M01 MEGABITS (CST) 97: ROM = 0M01 MEGABITS (CST) 98: ROM = 0M01 MEGABITS (CST) 99: ROM = 0M01 MEGABITS (CST) 100: ROM = 0M01 MEGABITS (CST)	XXX
SDS_ROM_EN	PS_108	GPIO3	1: Enable external BIOS ROM device 0: Disable	X
AE01	NA	GPIO	1: Enable audio function 0: Disable audio for DP only 1: Enable audio for both DP and HPS	XX
AE01	NA	GPIO	1: Enable audio function 0: Disable audio for DP only 1: Enable audio for both DP and HPS	XX
EEC_STS	PS_104		Reserved for future EEC	0
RESERVED	PS_112	GPIO_114	Reserved	
RESERVED	PS_112	GPIO_115	Reserved	
RESERVED	PS_112	GPIO_116	Reserved	
RESERVED	PS_112	GPIO_117	Reserved	
RESERVED	PS_112	GPIO_118	Reserved	
RESERVED	PS_112	GPIO_119	Reserved	
RESERVED	PS_112	GPIO_120	Reserved	
RESERVED	PS_112	GPIO_121	Reserved	
RESERVED	PS_112	GPIO_122	Reserved	
RESERVED	PS_112	GPIO_123	Reserved	
RESERVED	PS_112	GPIO_124	Reserved	
RESERVED	PS_112	GPIO_125	Reserved	
RESERVED	PS_112	GPIO_126	Reserved	
RESERVED	PS_112	GPIO_127	Reserved	
RESERVED	PS_112	GPIO_128	Reserved	
RESERVED	PS_112	GPIO_129	Reserved	
RESERVED	PS_112	GPIO_130	Reserved	
RESERVED	PS_112	GPIO_131	Reserved	
RESERVED	PS_112	GPIO_132	Reserved	
RESERVED	PS_112	GPIO_133	Reserved	
RESERVED	PS_112	GPIO_134	Reserved	
RESERVED	PS_112	GPIO_135	Reserved	
RESERVED	PS_112	GPIO_136	Reserved	
RESERVED	PS_112	GPIO_137	Reserved	
RESERVED	PS_112	GPIO_138	Reserved	
RESERVED	PS_112	GPIO_139	Reserved	
RESERVED	PS_112	GPIO_140	Reserved	
RESERVED	PS_112	GPIO_141	Reserved	
RESERVED	PS_112	GPIO_142	Reserved	
RESERVED	PS_112	GPIO_143	Reserved	
RESERVED	PS_112	GPIO_144	Reserved	
RESERVED	PS_112	GPIO_145	Reserved	
RESERVED	PS_112	GPIO_146	Reserved	
RESERVED	PS_112	GPIO_147	Reserved	
RESERVED	PS_112	GPIO_148	Reserved	
RESERVED	PS_112	GPIO_149	Reserved	
RESERVED	PS_112	GPIO_150	Reserved	
RESERVED	PS_112	GPIO_151	Reserved	
RESERVED	PS_112	GPIO_152	Reserved	
RESERVED	PS_112	GPIO_153	Reserved	
RESERVED	PS_112	GPIO_154	Reserved	
RESERVED	PS_112	GPIO_155	Reserved	
RESERVED	PS_112	GPIO_156	Reserved	
RESERVED	PS_112	GPIO_157	Reserved	
RESERVED	PS_112	GPIO_158	Reserved	
RESERVED	PS_112	GPIO_159	Reserved	
RESERVED	PS_112	GPIO_160	Reserved	
RESERVED	PS_112	GPIO_161	Reserved	
RESERVED	PS_112	GPIO_162	Reserved	
RESERVED	PS_112	GPIO_163	Reserved	
RESERVED	PS_112	GPIO_164	Reserved	
RESERVED	PS_112	GPIO_165	Reserved	
RESERVED	PS_112	GPIO_166	Reserved	
RESERVED	PS_112	GPIO_167	Reserved	
RESERVED	PS_112	GPIO_168	Reserved	
RESERVED	PS_112	GPIO_169	Reserved	
RESERVED	PS_112	GPIO_170	Reserved	
RESERVED	PS_112	GPIO_171	Reserved	
RESERVED	PS_112	GPIO_172	Reserved	
RESERVED	PS_112	GPIO_173	Reserved	
RESERVED	PS_112	GPIO_174	Reserved	
RESERVED	PS_112	GPIO_175	Reserved	
RESERVED	PS_112	GPIO_176	Reserved	
RESERVED	PS_112	GPIO_177	Reserved	
RESERVED	PS_112	GPIO_178	Reserved	
RESERVED	PS_112	GPIO_179	Reserved	
RESERVED	PS_112	GPIO_180	Reserved	
RESERVED	PS_112	GPIO_181	Reserved	
RESERVED	PS_112	GPIO_182	Reserved	
RESERVED	PS_112	GPIO_183	Reserved	
RESERVED	PS_112	GPIO_184	Reserved	
RESERVED	PS_112	GPIO_185	Reserved	
RESERVED	PS_112	GPIO_186	Reserved	
RESERVED	PS_112	GPIO_187	Reserved	
RESERVED	PS_112	GPIO_188	Reserved	
RESERVED	PS_112	GPIO_189	Reserved	
RESERVED	PS_112	GPIO_190	Reserved	
RESERVED	PS_112	GPIO_191	Reserved	
RESERVED	PS_112	GPIO_192	Reserved	
RESERVED	PS_112	GPIO_193	Reserved	
RESERVED	PS_112	GPIO_194	Reserved	
RESERVED	PS_112	GPIO_195	Reserved	
RESERVED	PS_112	GPIO_196	Reserved	
RESERVED	PS_112	GPIO_197	Reserved	
RESERVED	PS_112	GPIO_198	Reserved	
RESERVED	PS_112	GPIO_199	Reserved	
RESERVED	PS_112	GPIO_200	Reserved	



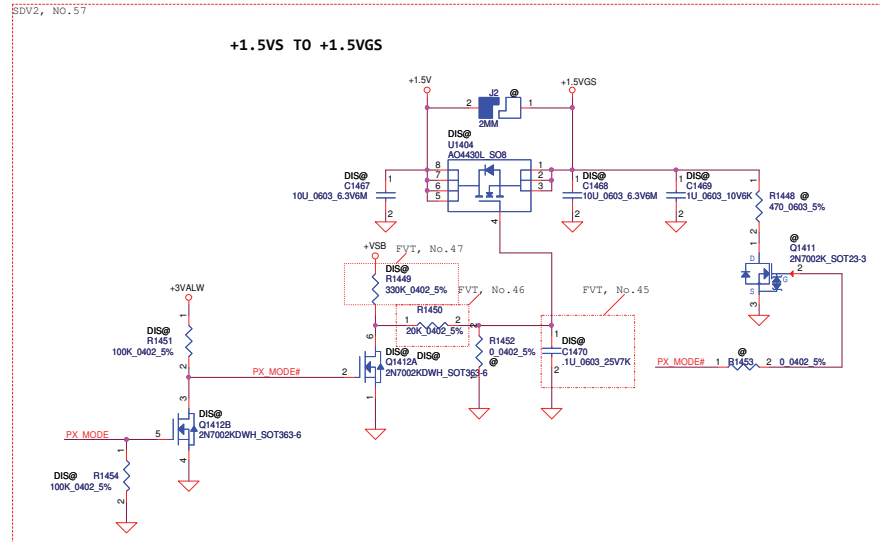
Security Classification	Compul Secret Data	Issued Date	2016/07/08	Disphered Date	2016/07/08	Rev	1	Compul Electronics, Inc.
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPUL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSMITTED FROM THE CUSTODY OF THE COOPERATION DIVISION OF THE COMPUL ELECTRONICS CORPORATION WITHOUT THE WRITTEN CONSENT OF COMPUL ELECTRONICS, INC. THIS SHEET IS THE PROPERTY OF COMPUL ELECTRONICS, INC. AND IS NOT TO BE REPRODUCED OR DISCLOSED TO ANY THIRD PARTY WITHOUT THE WRITTEN CONSENT OF COMPUL ELECTRONICS, INC.								
All Themes XT M2 Main MSIC								
LA-8121P								



+3.3VS TO +3.3VGS

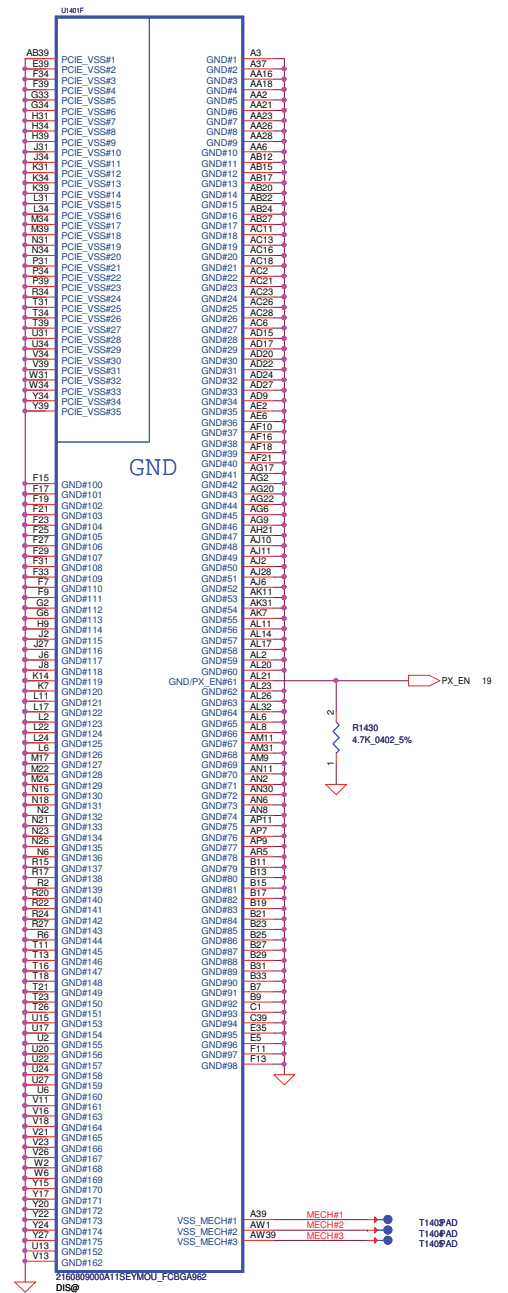
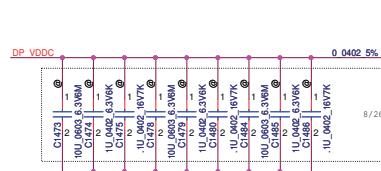
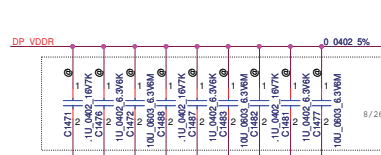
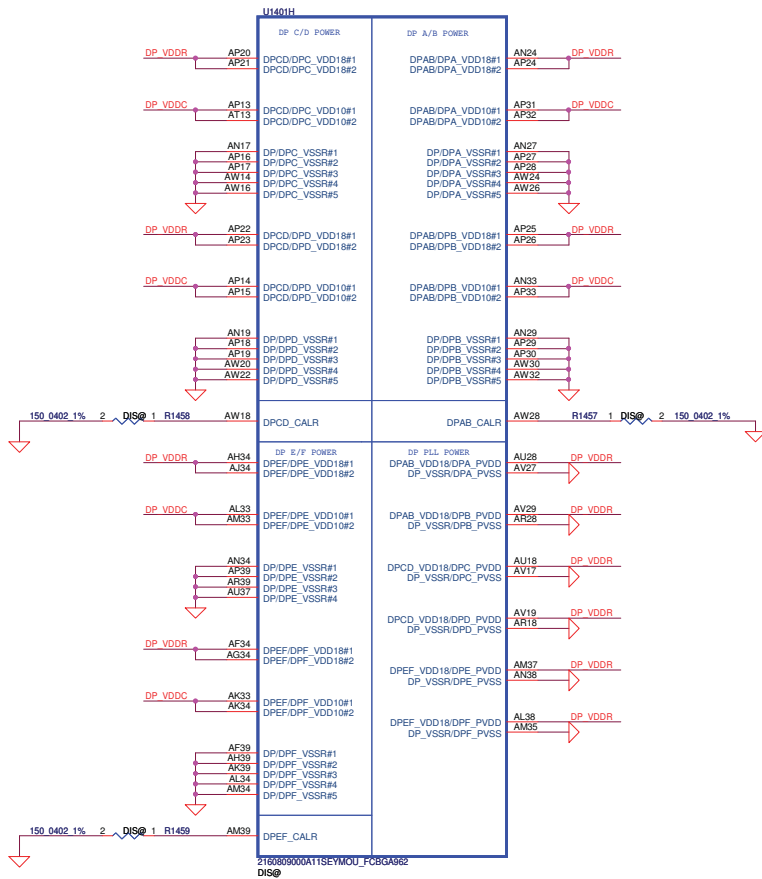


+1.5VS TO +1.5VGS

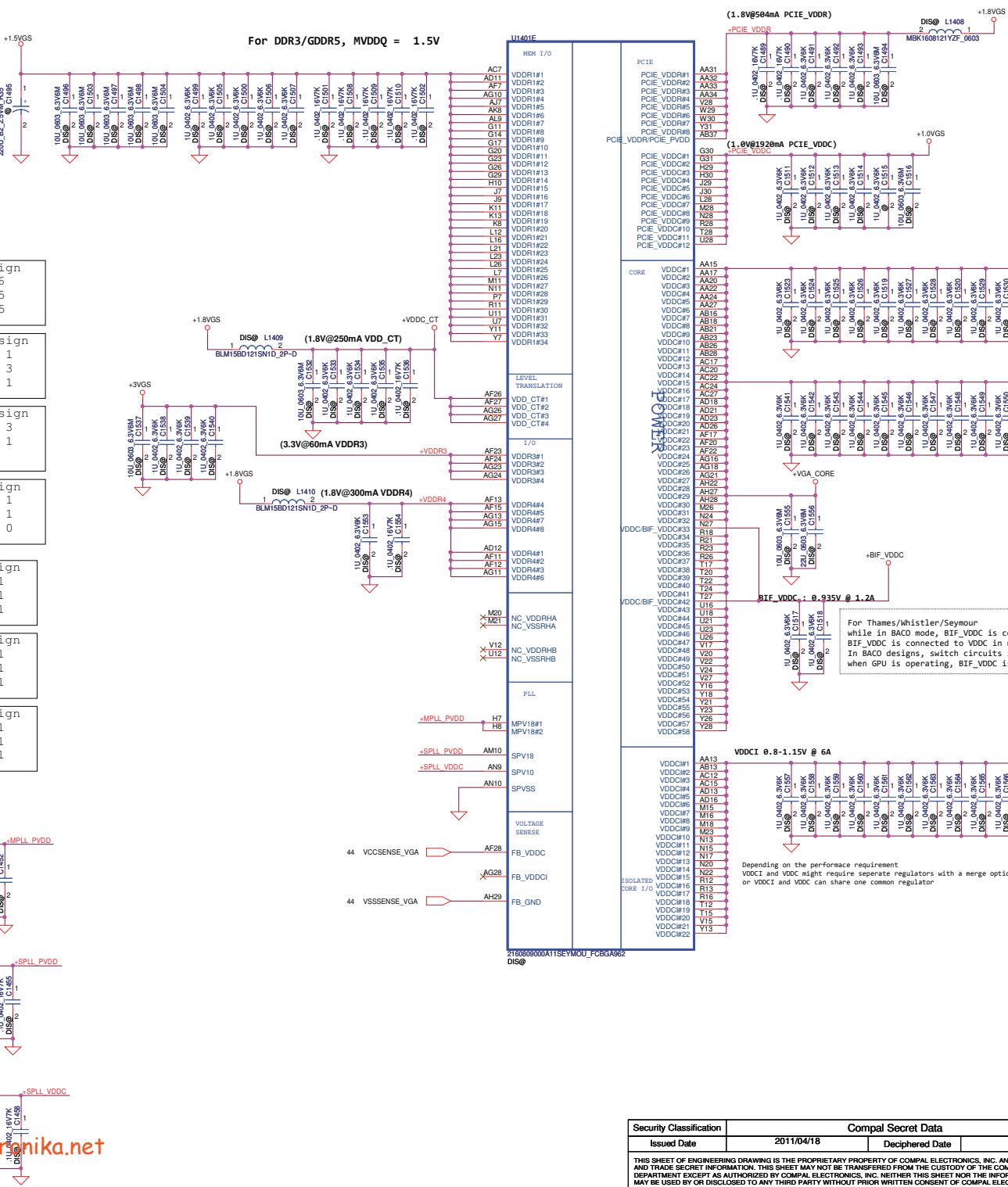


<http://hobi-elektronika.net>

Security Classification	Compal Secret Data			Title	
Issued Date	2011/04/18	Deciphered Date	2015/07/08	Compal Electronics, Inc.	
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.					
Size	Document Number			Rev	
C	IA-8121P			0.4	
Date: Monday, January 16, 2012 Sheet 19 of 50					



For DDR3/GDDR5, MVDDQ = 1.5V



VDDR1	CRB	Design
0.1u	11	6
1u	10	5
10u	6	5

VDD_CT	CRB	Design
0.1u	1	1
1u	3	3
10u	1	1

VDDR3	CRB	Design
1u	3	3
10u	1	1

VDDR4	CRB	Design
0.1u	2	1
1u	2	1
10u	2	0

MPV18	CRB	Design
0.1u	2	1
1u	2	1
10u	1	1

SPV18	CRB	Design
0.1u	1	1
1u	1	1
10u	1	1

SPV10	CRB	Design
0.1u	1	1
1u	1	1
10u	1	1

PCIE_VDDR	CRB	Design
0.01u	1	0
0.1u	1	2
1u	3 (2@)	3
10u	1	1

PCIE_VDDC	CRB	Design
0.1u	3	0
1u	10	5 (1@)
10u	2	1

+BIF_VDDC	CRB	Design
1u	2	2
10u	1	0

VDDC	CRB	Design
1u	30	25
10u	9	1
22u	0	1

VDDCI	CRB	Design
1u	10	9
10u	3	2
22u	0	1

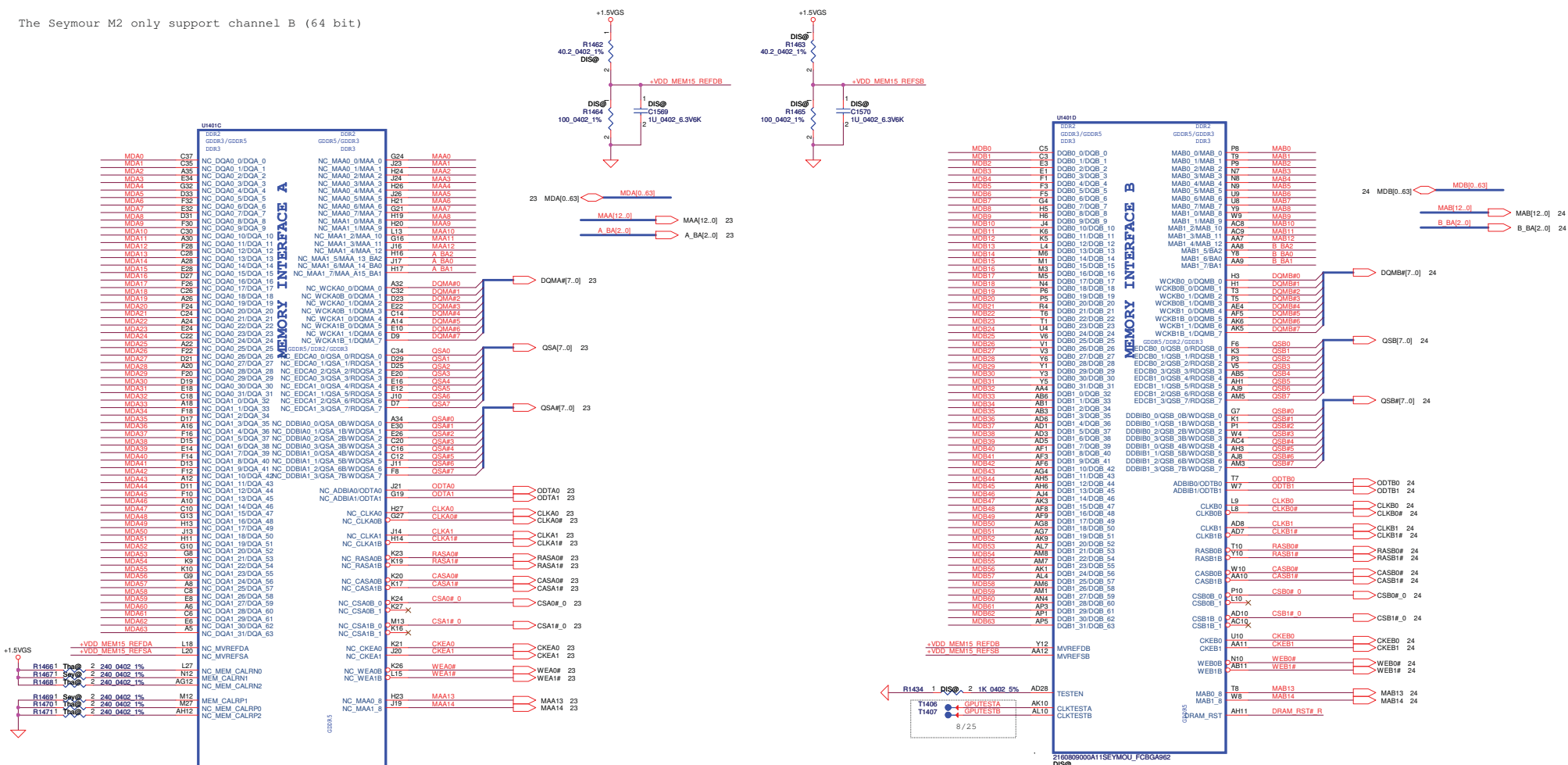
For Thames/Whistler/Seymour while in BACO mode, BIF_VDDC is connected to +1.8V BIF_VDDC is connected to VDDC in non BACO designs. In BACO designs, switch circuits is required so that when GPU is operating, BIF_VDDC is connected to VDDC

VDDCI 0.8-1.15V @ 6A

Depending on the performance requirement VDDCI and VDDC might require separate regulators with a merge option on PCB or VDDCI and VDDC can share one common regulator

<http://hobi-electronika.net>

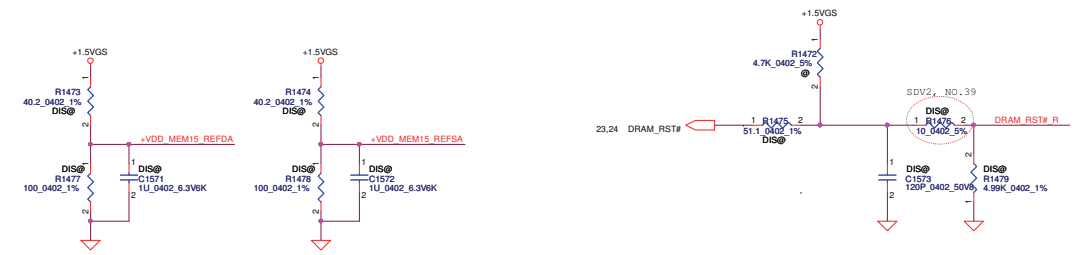
Security Classification	Compal Secret Data		Title
Issued Date	2011/04/18	Deciphered Date	
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.			ATI Themes XT_M2_Power Document Number IA-8121P
Date	Monday, January 16, 2012	Sheet	21 of 50



Themes XT	Seymour XT
R1466	POP @
R1467	@ POP
R1468	POP @
R1469	@ POP
R1470	POP @
R1471	POP @

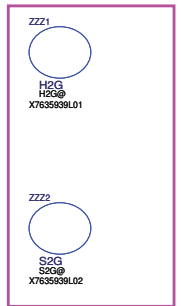
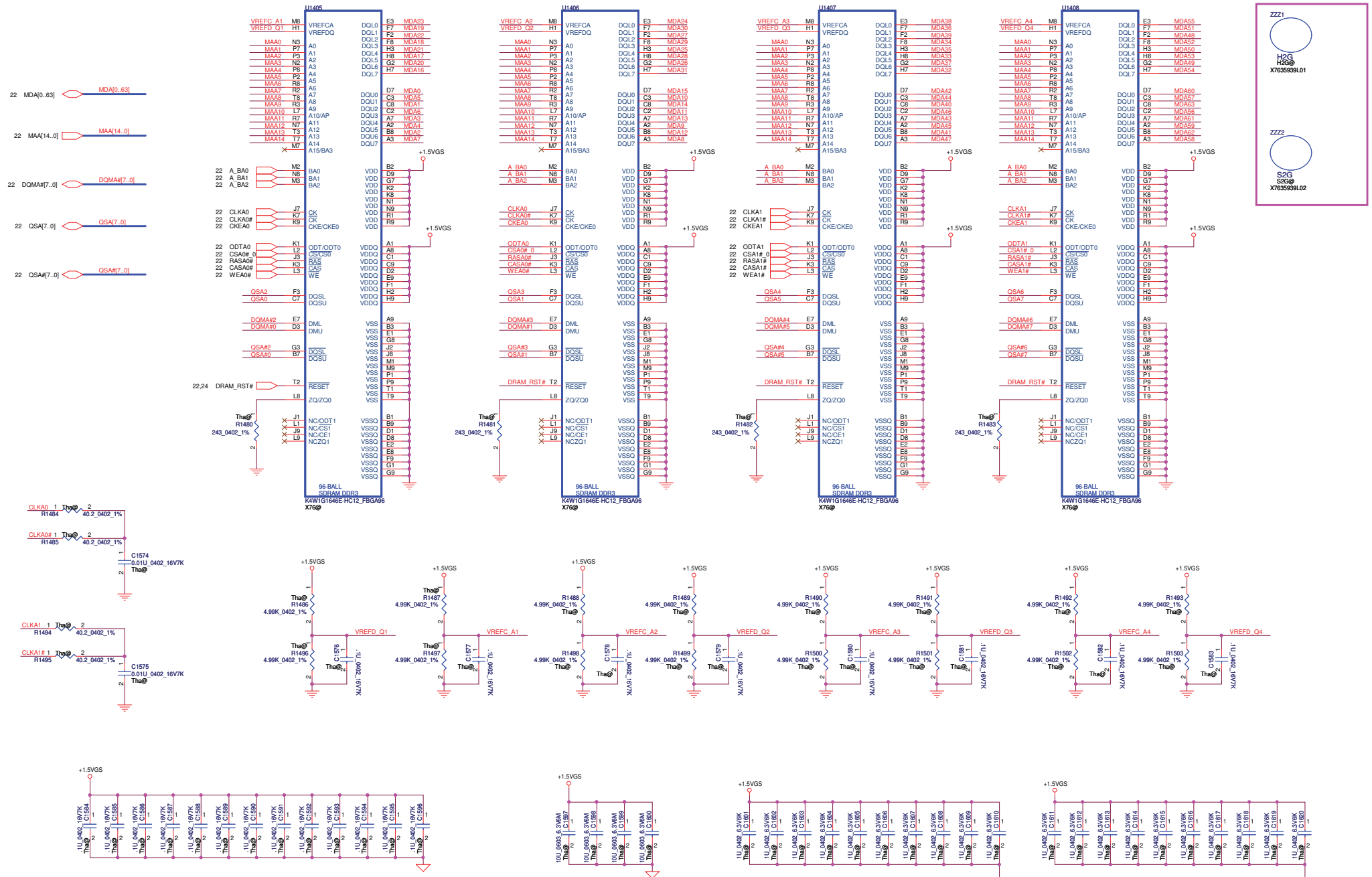
Place all these components very close to GPU (within 25mm) and keep all components close to each other
 ** This basic topology should be used for DRAM_RST for DDR3/GDR5

These Capacitors and Resistor values are an example only
 The series R and || cap values will depend on the DRAM loads and will have to be calculated for different Memory, DRAM loads and board to pass Reset Signal Spec



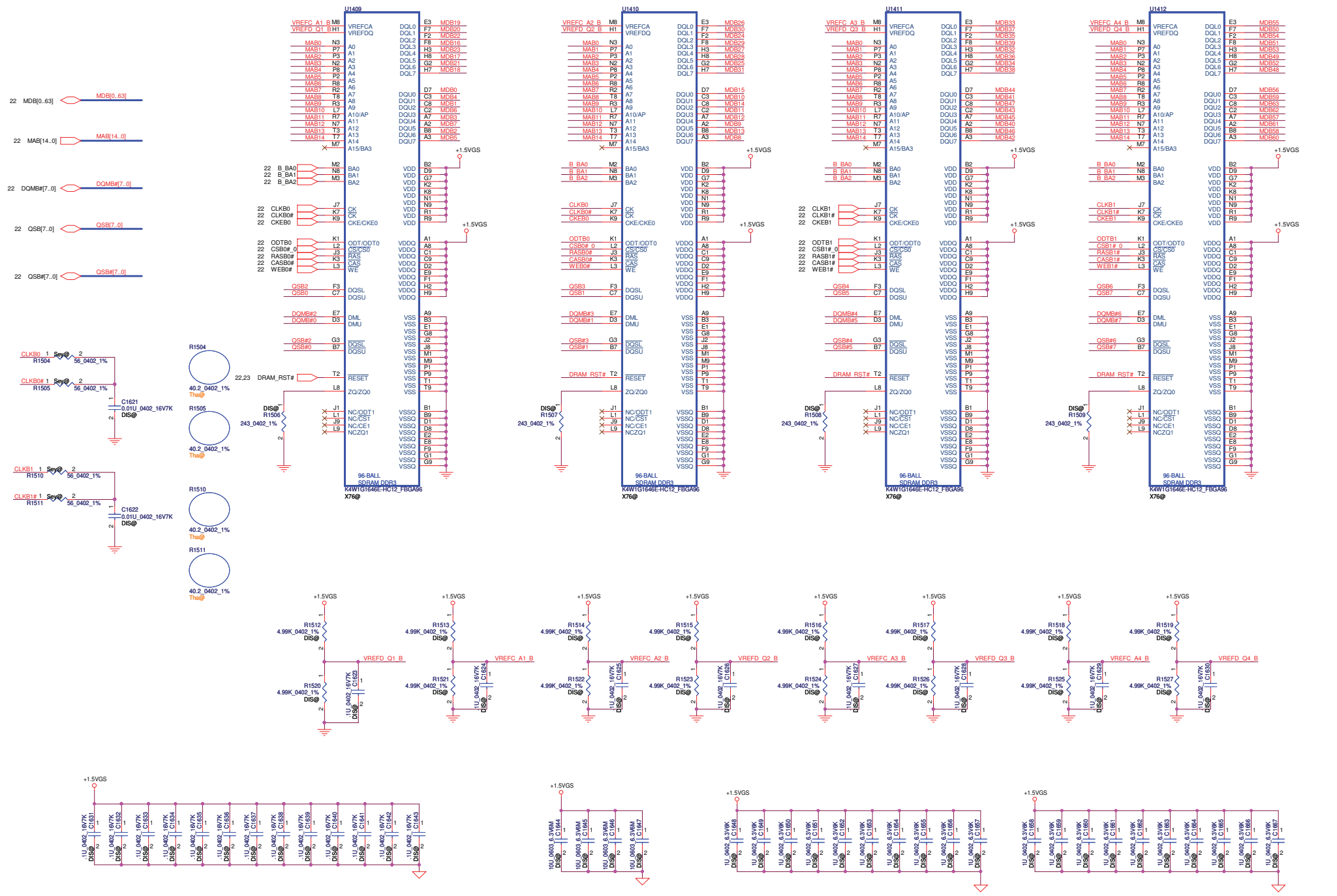
Security Classification	Compal Secret Data			Title
Issued Date	2011/04/16	Deciphered Date	2015/07/08	
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF COMPAL ELECTRONICS, INC. WITHOUT THE WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.				ATT Themes XT_M2_MEM IF LA-8121P
Date:	Monday, January 16, 2012	Sheet:	22	of 50

The Seymour M2 only support channel B (64 bit),
this page unmount all parts



<http://hobi-elektronika.net>

Security Classification	Compal Secret Data		Title	Compal Electronics, Inc.
Issued Date	2011/04/18	Deciphered Date	2015/07/08	ATI Themes XT_M2_VRAM_A
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.				
Size	Document Number	Date		Rev
	IA-8121P	Monday, January 16, 2012		04
			Sheet	23 of 50

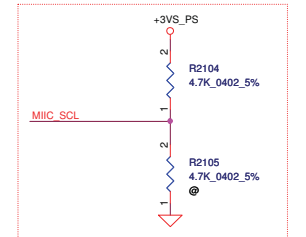
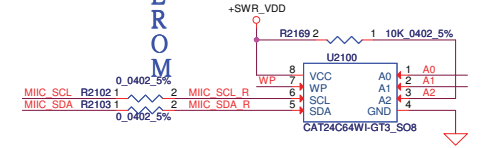
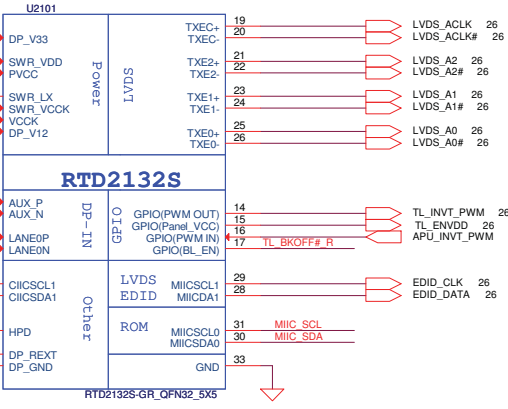
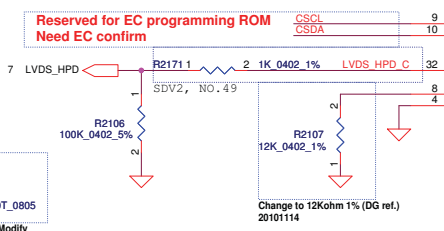
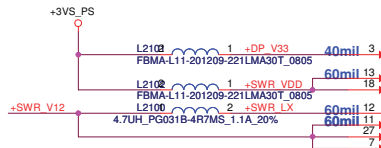
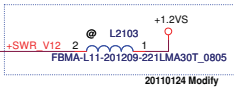
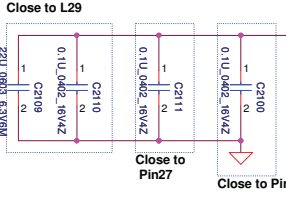
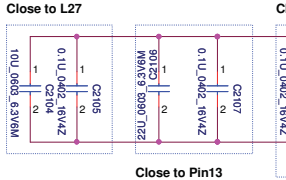
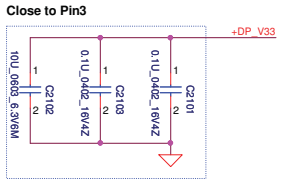
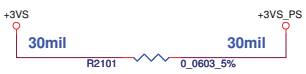


<http://hobi-elektronika.net>

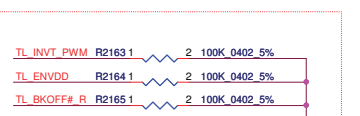
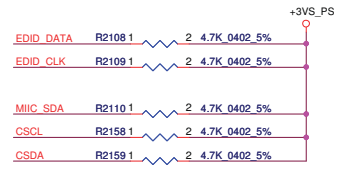
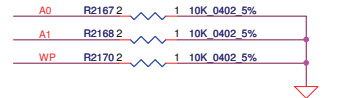
Security Classification		Compal Secret Data		Title	
Issued Date	2011/04/18	Deciphered Date	2015/07/08	ATI Themes XT_M2_VRAM_B	
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.					
Size	C	Document Number	IA-8121P	Rev	04
Date	Monday, January 16, 2012	Sheet	24	of 50	

Part number: SA00004EU10

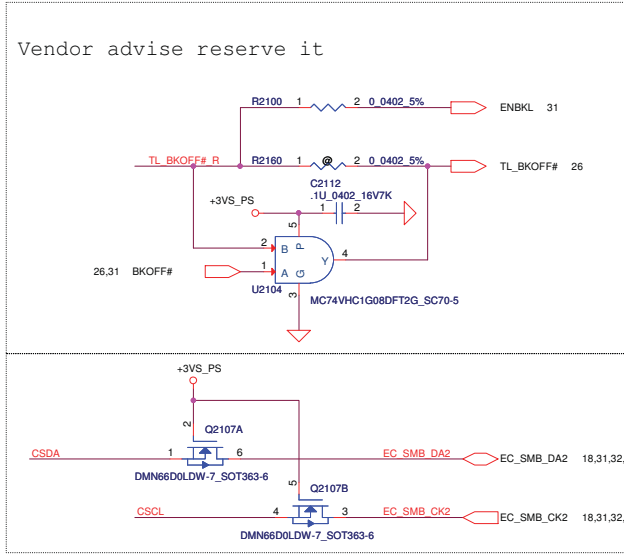
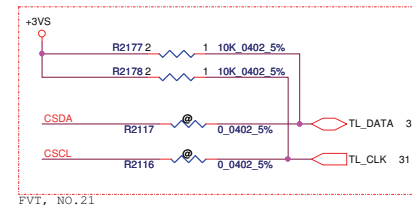
EEROM



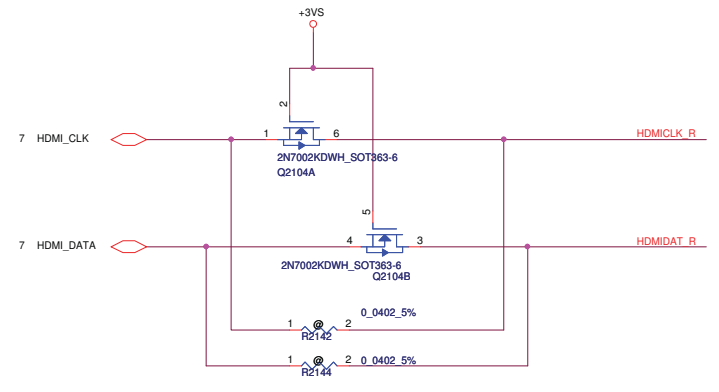
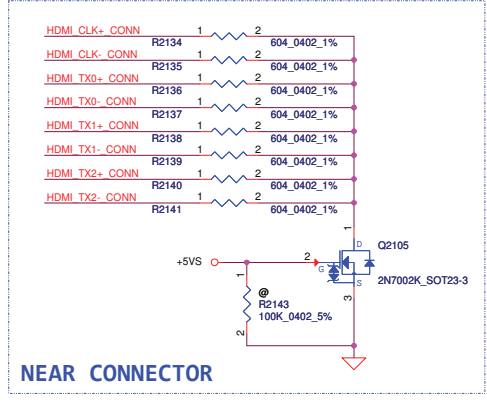
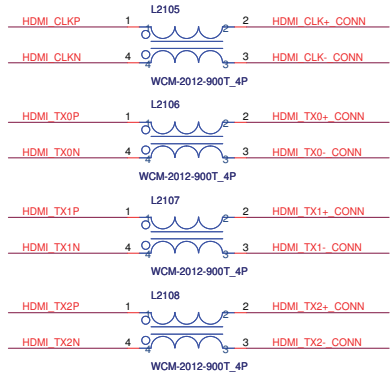
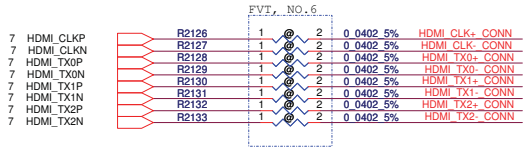
2132S-Ver E: External ROM, pin31 PU +3VS
Internal RAM support, pin31 PD to GND
EEROM EEROM EEROM EEROM



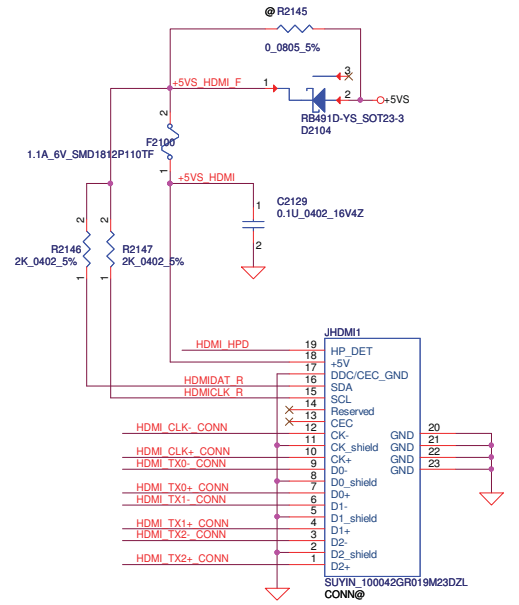
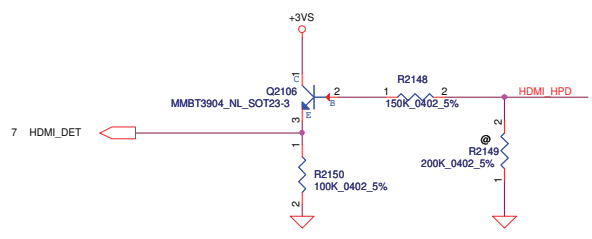
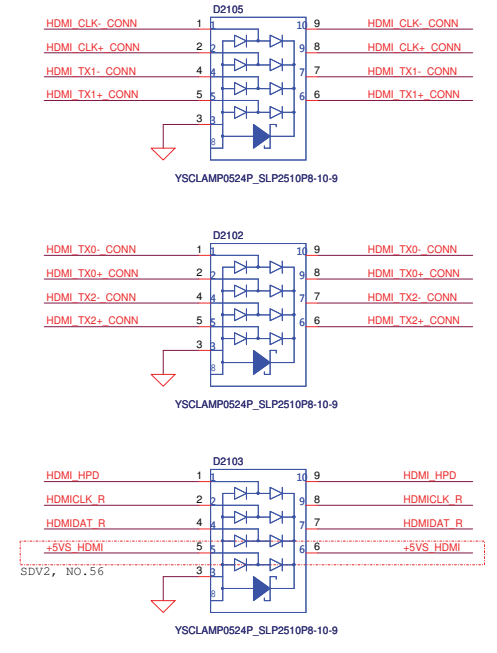
Vendor Suggest 2011.08.15



Security Classification	Compal Secret Data		Title	
Issued Date	2011/04/18	Deciphered Date	2015/07/08	LVDS Translator - RTD2132S
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.				Rev 0.4
Date: Monday, January 16, 2012				Sheet 25 of 50

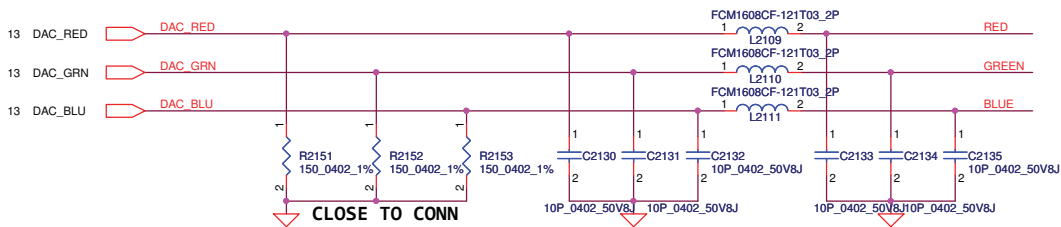


ESD Request 2011.08.13

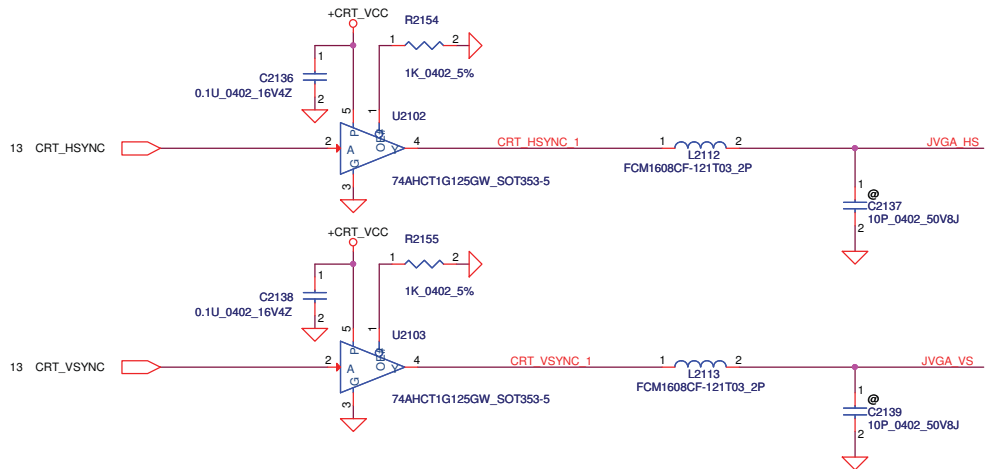
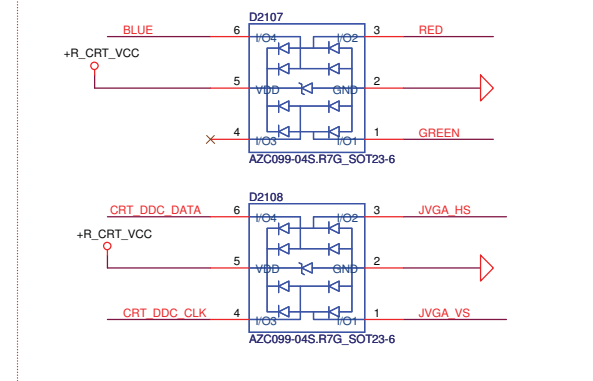


<http://hobi-elektronika.net>

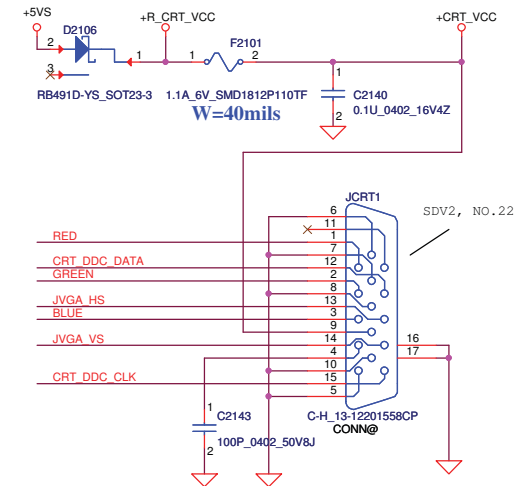
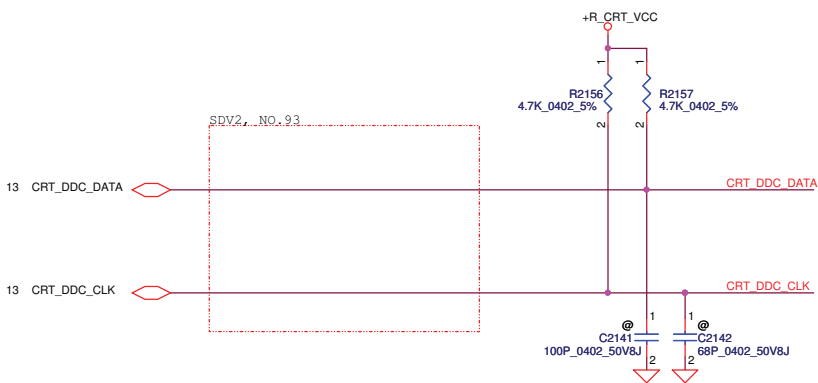
Security Classification	Compal Secret Data		Title	Compal Electronics, Inc.	
Issued Date	2011/04/18	Deciphered Date	2015/07/08	HDMI Connector	
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.					
Size	Document Number	Rev	LA-8121P		
Custom		0.4	Date:	Monday, January 16, 2012	Sheet 27 of 50



ESD Request 2011.08.13



CRT Connector

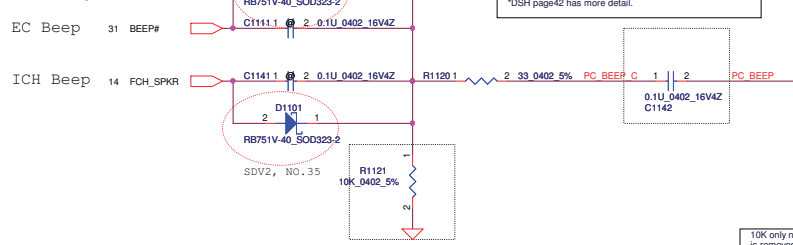


AMD check list update
20101110

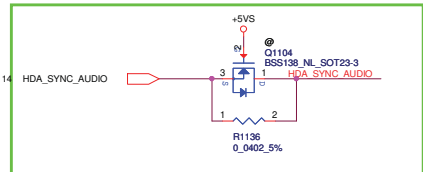
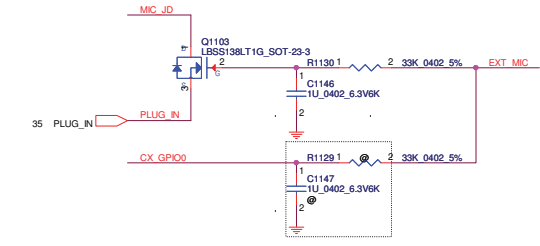
Security Classification	Compal Secret Data		Title	
Issued Date	2011/04/18	Deciphered Date	2015/07/08	CRT Connector
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.				Rev 0.4
Date: Monday, January 16, 2012		Sheet 28 of 50		LA-8121P

CX20671
 High Definition Audio Codec SoC
 With Integrated Class-D Stereo
 Amplifier.
 An integrated 5 V to 3.3 V Low-dropout
 voltage regulator (LDO).
 An integrated 3.3 V to 1.8V Low-dropout
 voltage regulator (LDO).

PC BEEP

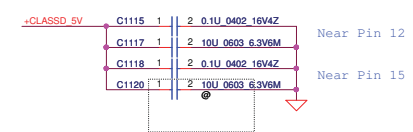


Combo Jack detect (normal close)

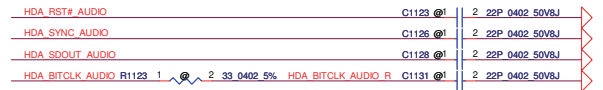


potential leakage concern

Decoupling CAP



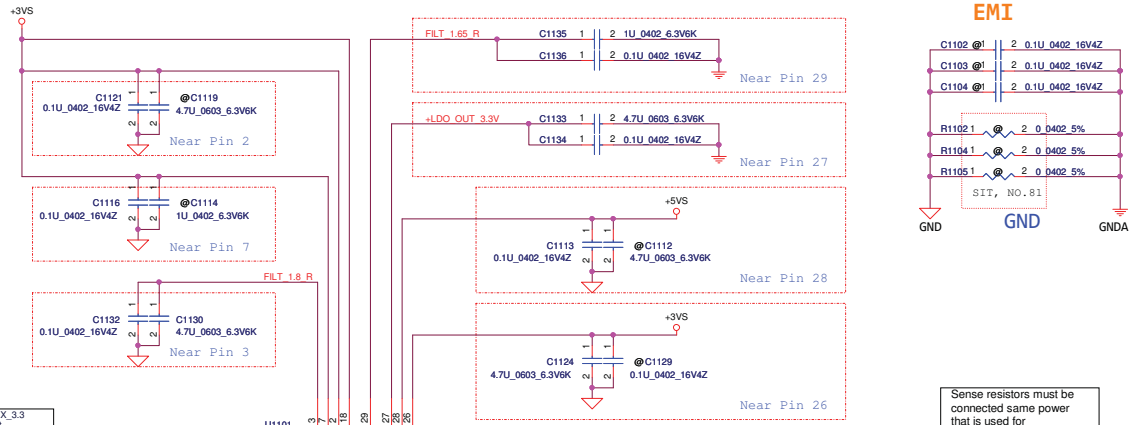
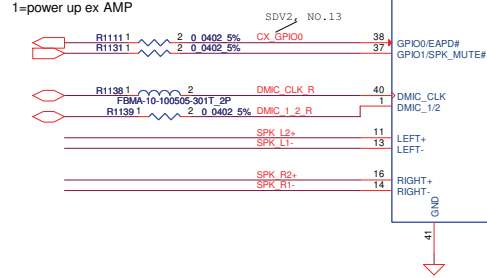
EMI



Layout Note: Path from +5VS to Pin12, Pin15 must be very low resistance (<0.01 ohms).
 To support Wake-on-Jack or Wake-on-Ring, the CODEC VAUX_3.3 & VDD_IO pins must be powered by a rail that is not removed unless AC power is removed.
 *DSH page42 has more detail.

10K only needed if supply to VAUX_3.3 is removed during system re-start.

EAPD active low
 0=power down ex AMP
 1=power up ex AMP



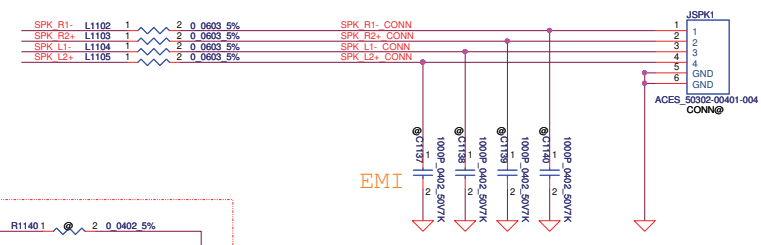
Sense resistors must be connected same power that is used for VAUX_3.3

Changed from 5.1ohm to 15ohm for "z1" noise.

Rdc < 0.05 ohms
 Rated Current > 2A

Width 20 mil

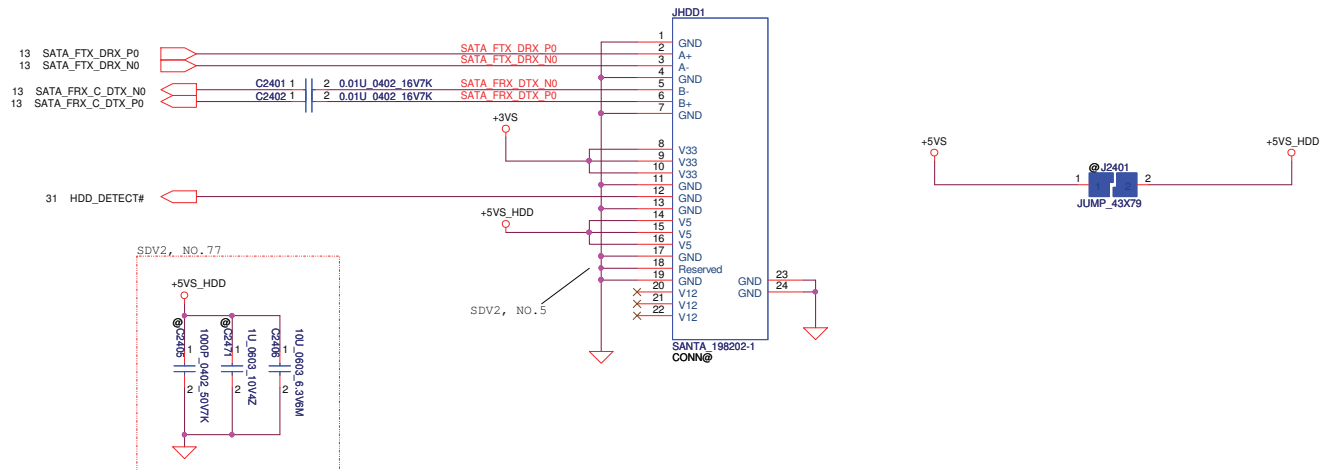
Internal Speaker



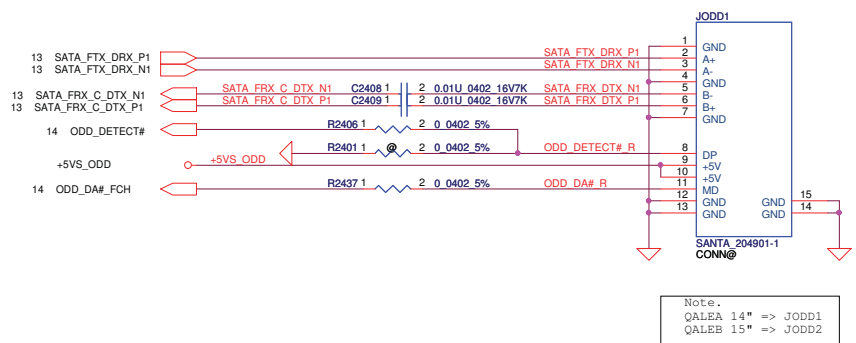
Note:
 CALEX 14" -> JSPK1 -> 4Pin
 CALEX 15" -> JSPK1 -> 6Pin

Security Classification	Compal Secret Data		Title	
Issued Date	2011/04/18	Deciphered Date	2015/07/08	Compal Electronics, Inc.
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF COMPAL ELECTRONICS, INC. DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.				HD Audio Codec CX20671 Document Number LA-8121P Date: Monday, January 16, 2012 Sheet 29 of 50

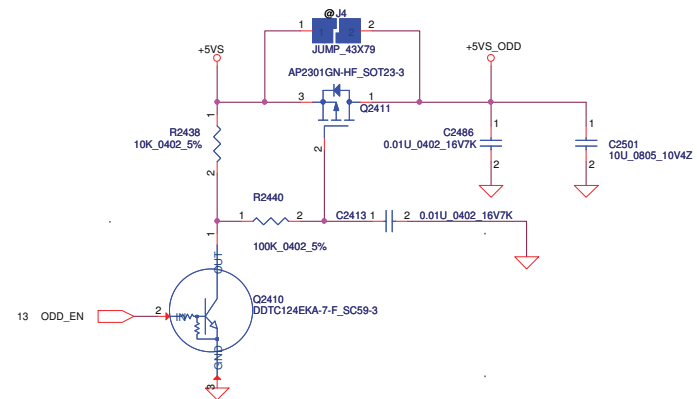
SATA HDD Conn.



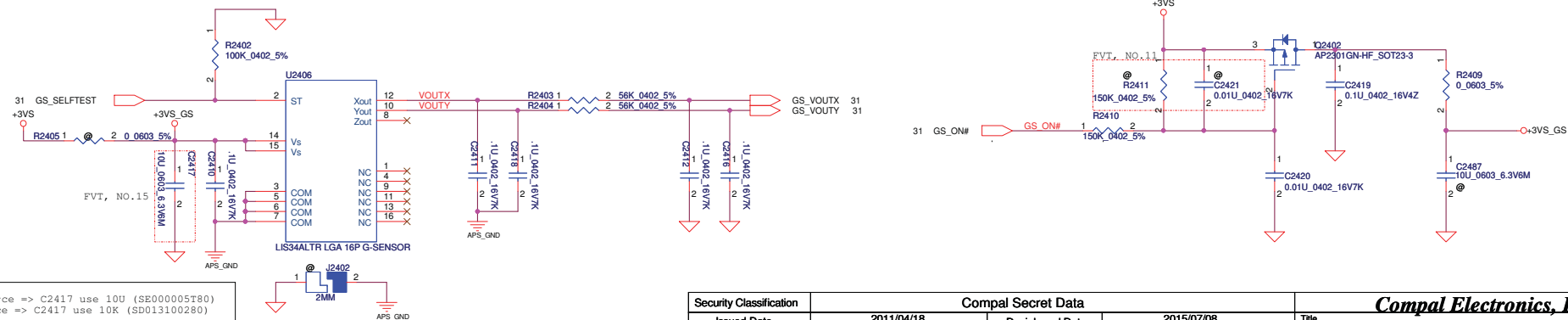
SATA ODD Conn.



ODD Power Control



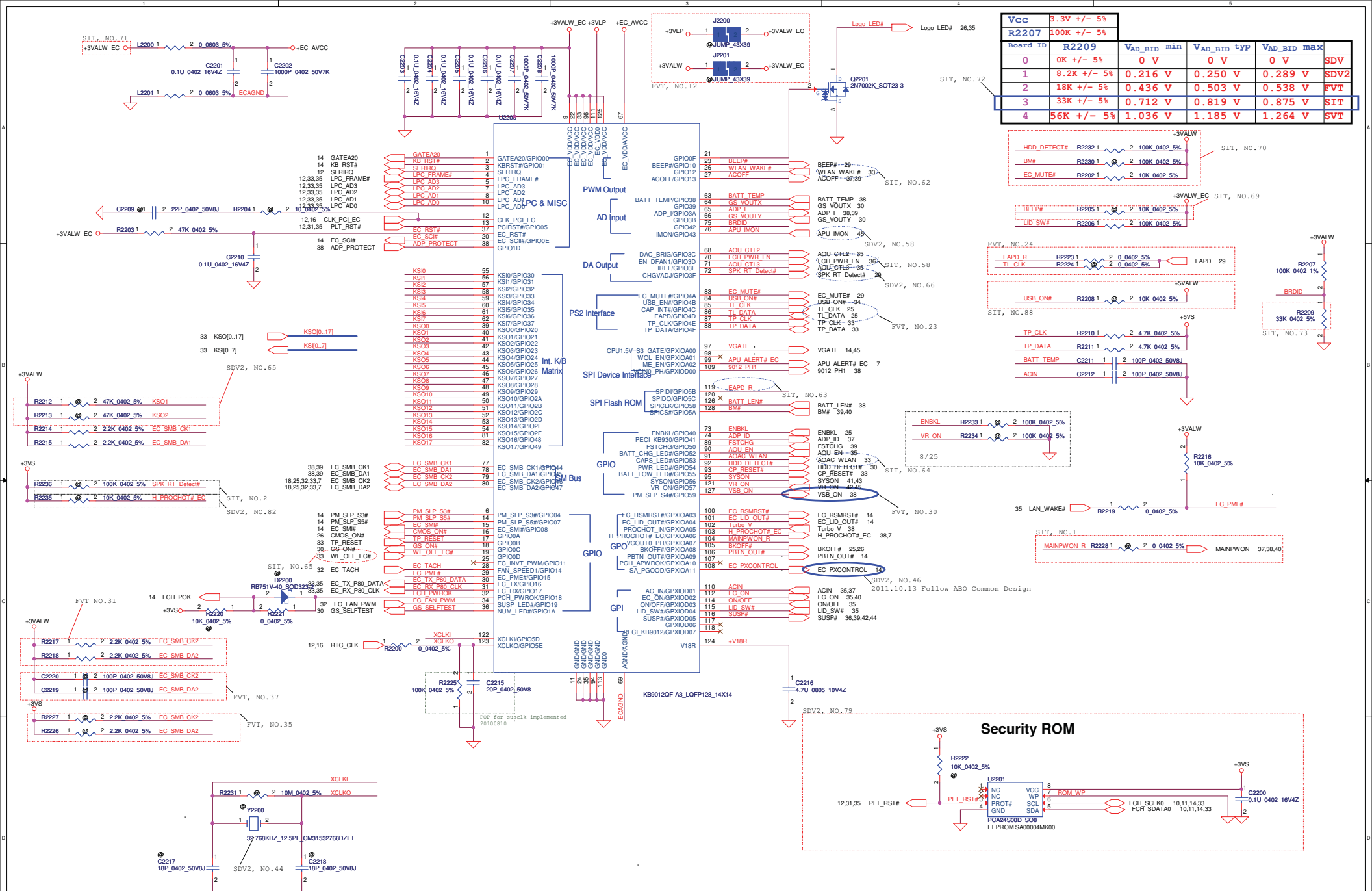
APS G-Sensor



Note.
Main Source => C2417 use 10U (SE000005T80)
2nd Source => C2417 use 10K (SD013100280)

<http://hobi-elektronika.net>

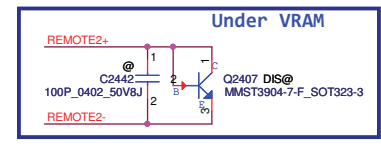
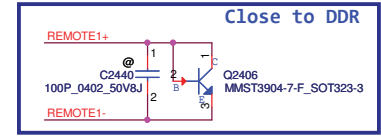
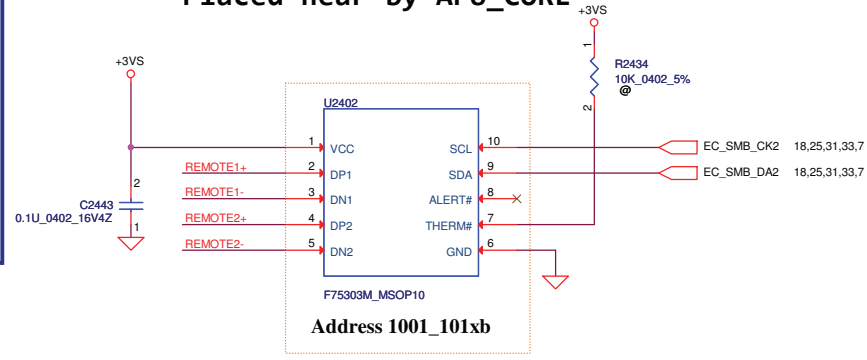
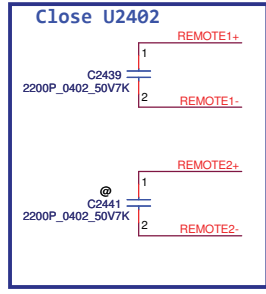
Security Classification		Compal Secret Data		Title	
Issued Date	2011/04/18	Deciphered Date	2015/07/08	HDD/ODD/G-Sensor	
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.					
Size B	Document Number	Date		Sheet	Rev
	LA-8121P	Monday, January 16, 2012		30	0.4



Vcc	3.3V +/- 5%				
R2207	100K +/- 5%				
Board ID	R2209	VAD_BID min	VAD_BID typ	VAD_BID max	SDV
0	0K +/- 5%	0 V	0 V	0 V	
1	8.2K +/- 5%	0.216 V	0.250 V	0.289 V	SDV2
2	18K +/- 5%	0.436 V	0.503 V	0.538 V	FVT
3	33K +/- 5%	0.712 V	0.819 V	0.875 V	SIT
4	56K +/- 5%	1.036 V	1.185 V	1.264 V	SVT

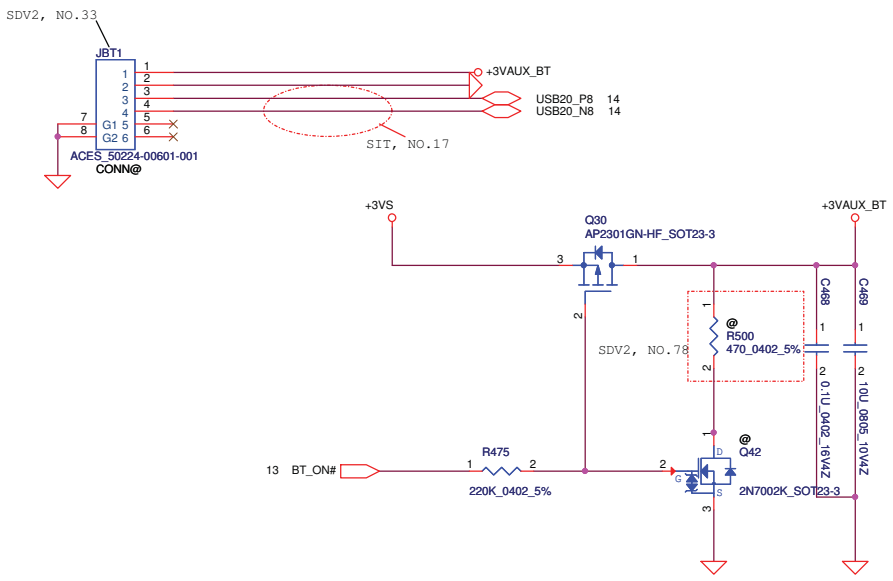
Security Classification	Compal Secret Data		Title
Issued Date	2011/04/18	Deciphered Date	2015/07/08
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF COMPAL ELECTRONICS, INC. DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.			EC ENE-KB9012 Document Number LA-8121P Date: Monday, January 16, 2012 Sheet 31 of 50

Fintek Thermal sensor Placed near by APU_CORE

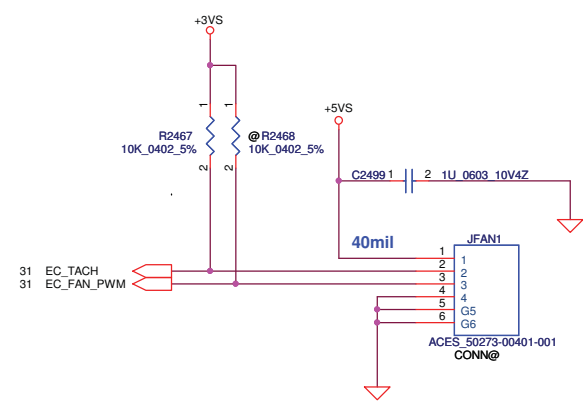


REMOTE1,2+/-:
Trace width/space:10/10 mil
Trace length:<8"

BT Connector

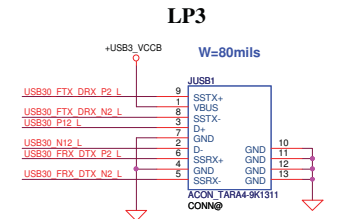
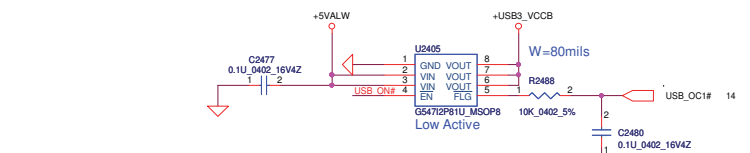
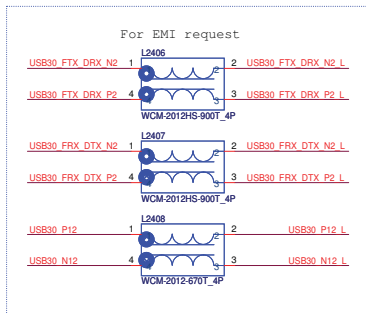
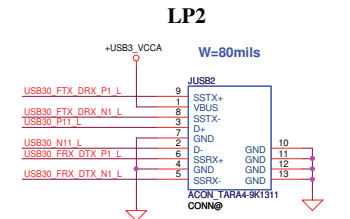
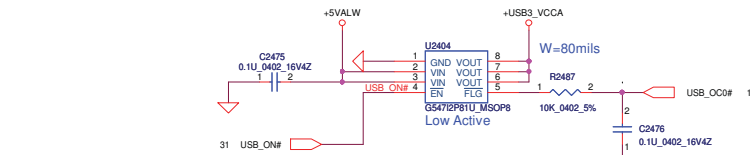
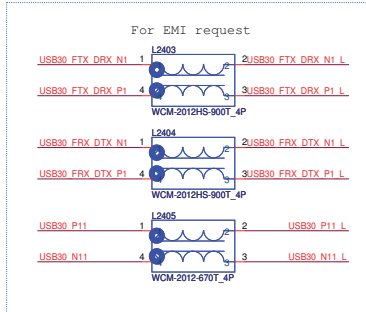
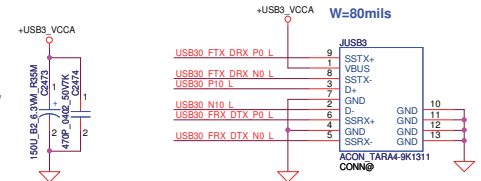
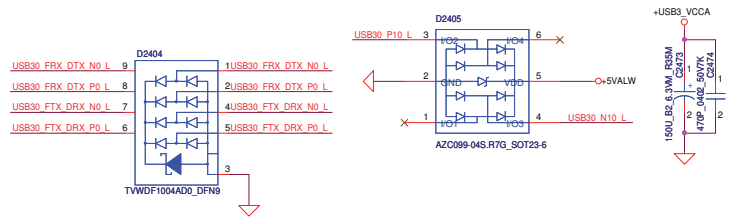
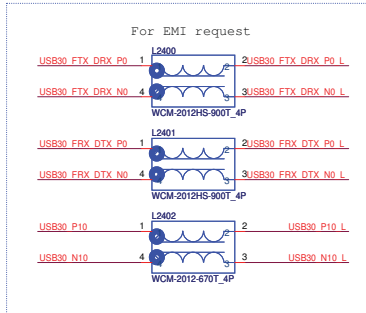
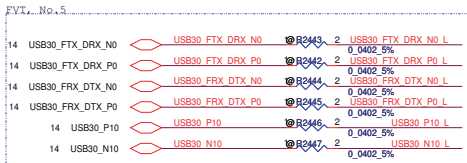


FAN1 Conn



Security Classification	Compal Secret Data		Title	
Issued Date	2011/04/18	Deciphered Date	2015/07/08	Compal Electronics, Inc.
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.				Rev 0.4
Document Number			LA-8121P	
Date:	Monday, January 16, 2012	Sheet	32	of 50

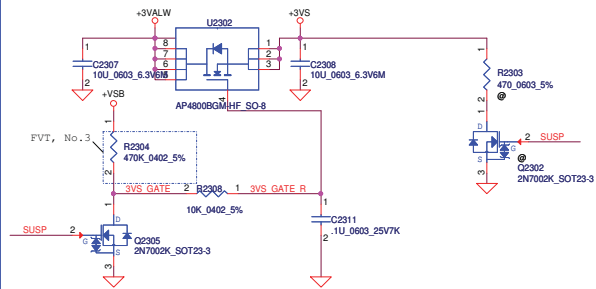
USB3.0 Conn *3



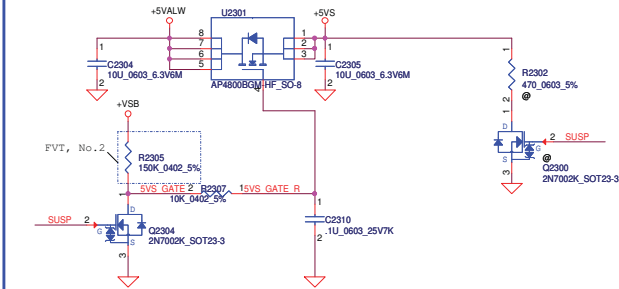
<http://hobi-elektronika.net>

Security Classification	Compal Secret Data		2015/07/08		Title		Compal Electronics, Inc.	
Issued Date	2011/04/18		Deciphered Date		2015/07/08		USB 3.0 Conn	
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.								
Size	Document Number		Date		Monday, January 16, 2012		Rev 0.4	
C	IA-8121P		Sheet		34		of 50	

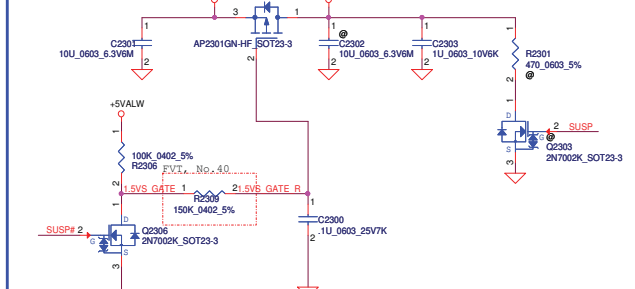
+3VALW TO +3VS



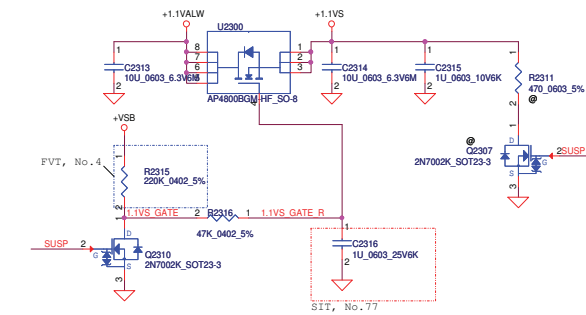
+5VALW TO +5VS



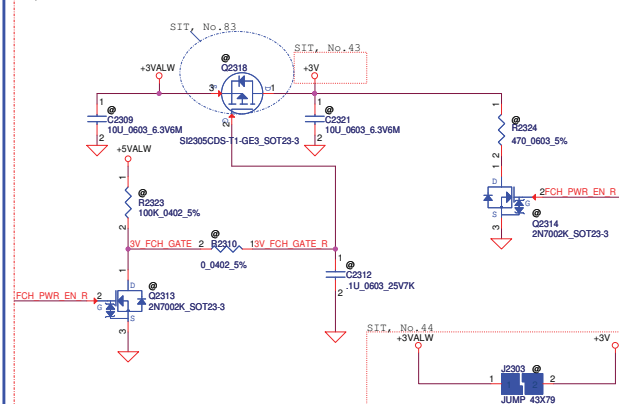
+1.5V to +1.5VS



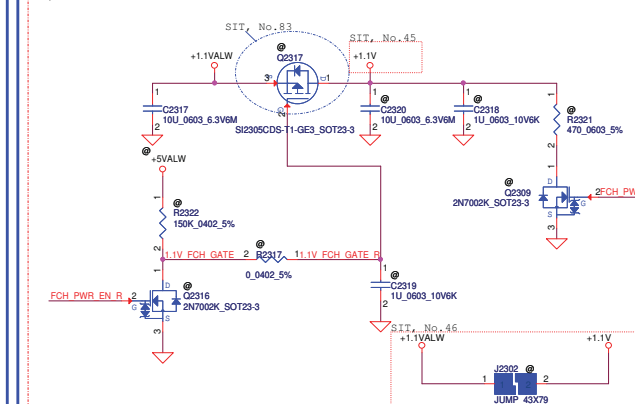
+1.1VALW to +1.1VS



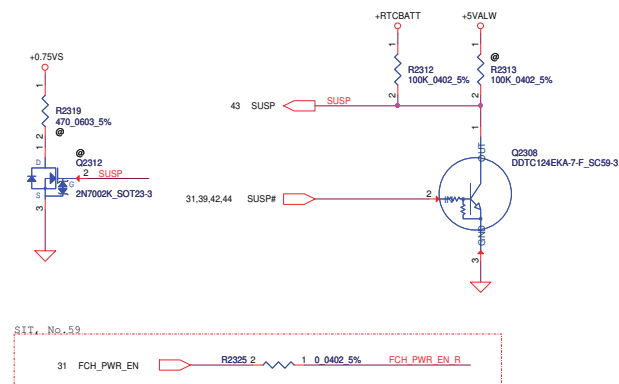
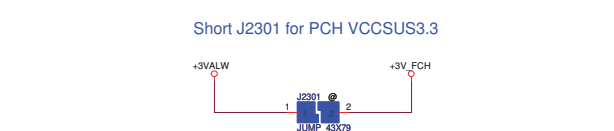
+3VALW TO +3V

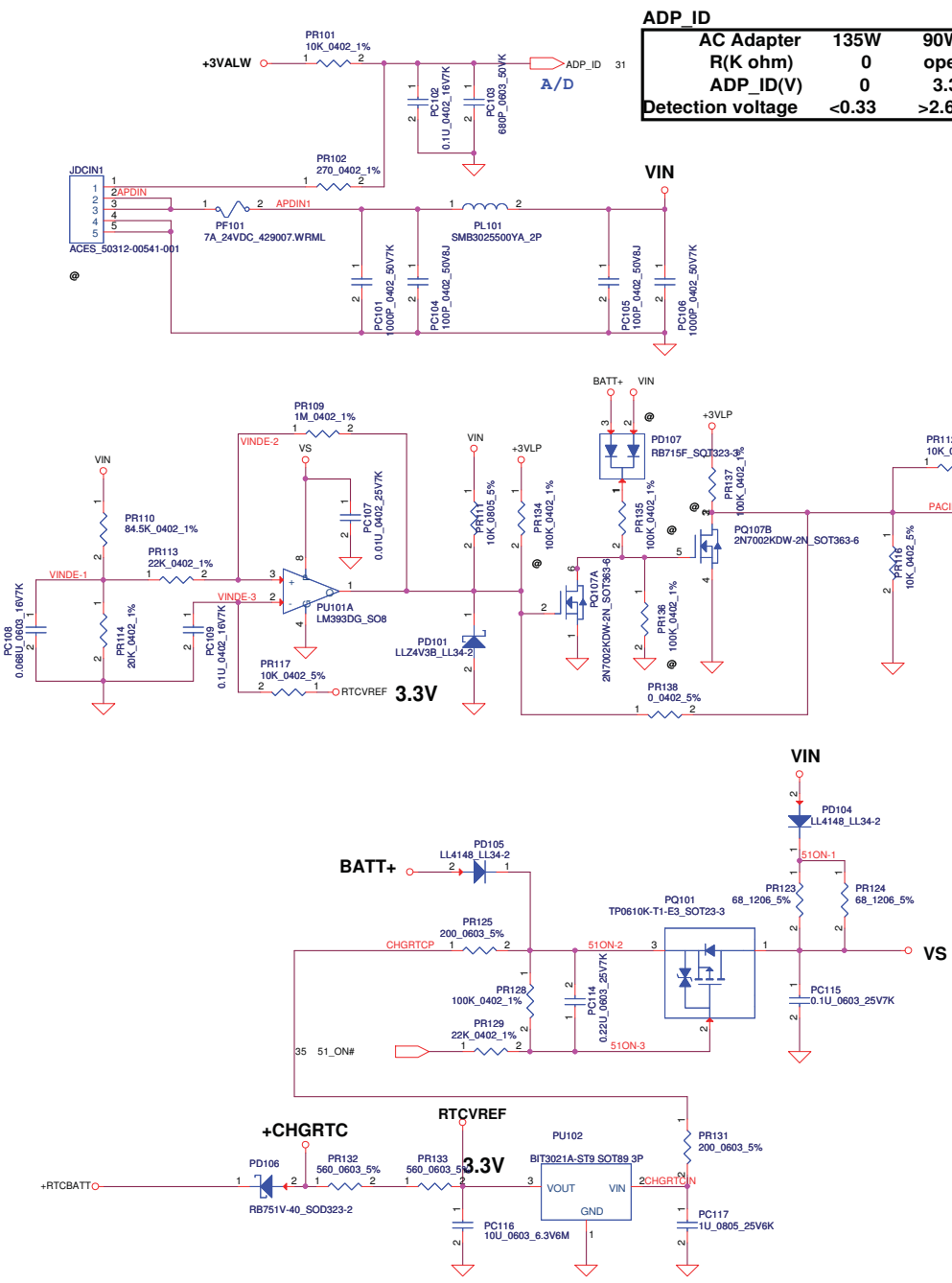


+1.1VALW to +1.1V



+3VALW TO +3V_FCH





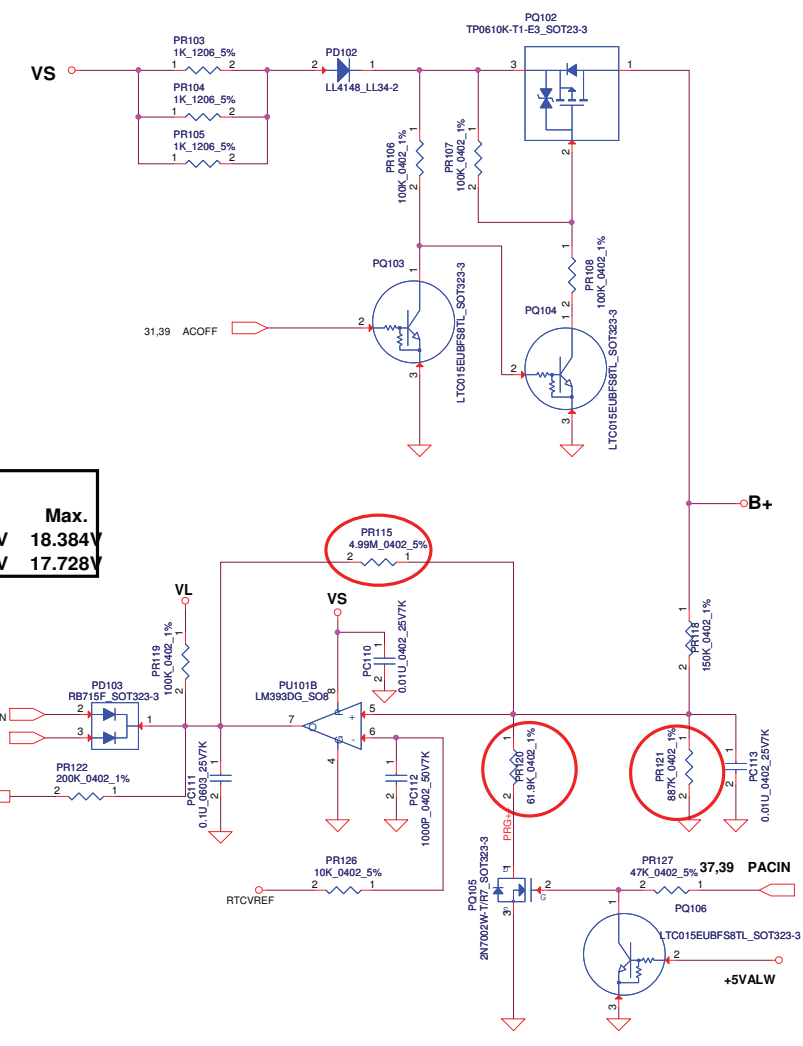
ADP_ID

AC Adapter	135W	90W	65W
R(K ohm)	0	open	10
ADP_ID(V)	0	3.3	1.65
Detection voltage	<0.33	>2.64	1.32~1.98

Vin Detector

	Min.	typ.	Max.
L->H	17.430V	17.901V	18.384V
H->L	16.976V	17.262V	17.728V

**Precharge detector
15.97V/14.84V FOR
ADAPTOR**

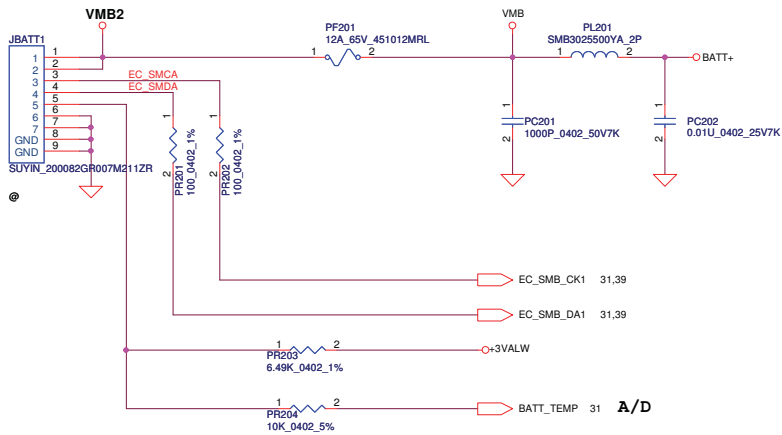


ACIN

Precharge detector			
Min.	typ.	Max	
L->H	14.991V	15.381V	15.782V
H->L	13.860V	14.247V	14.621V

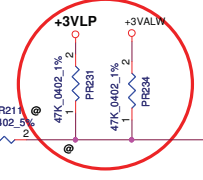
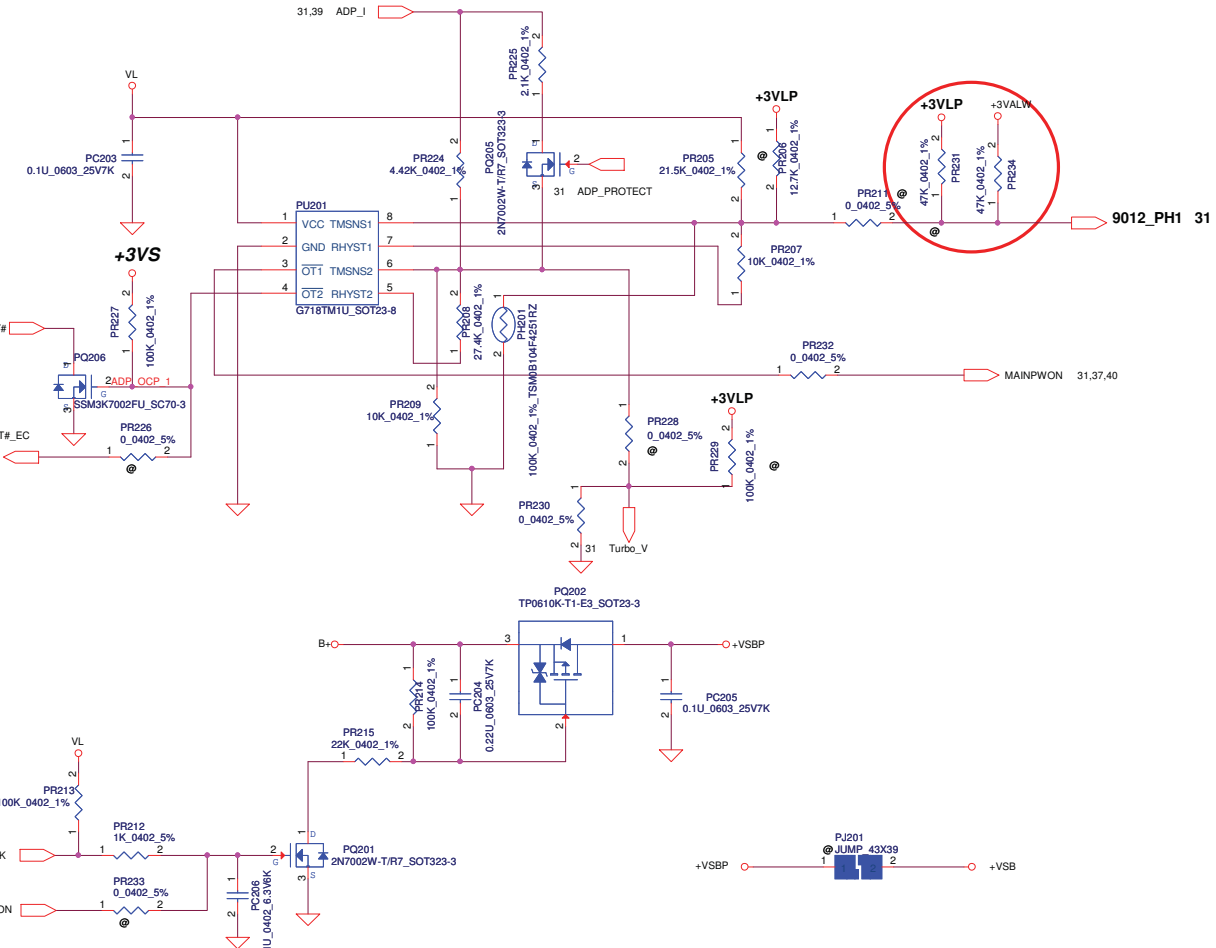
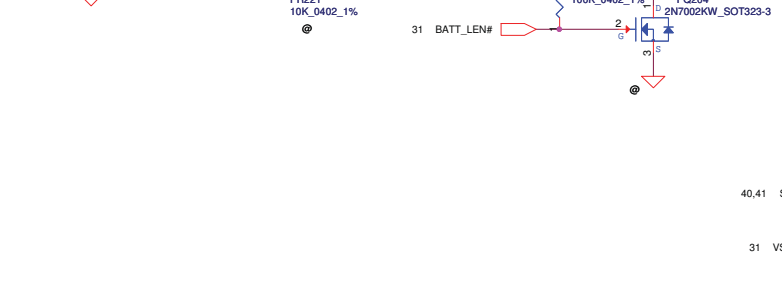
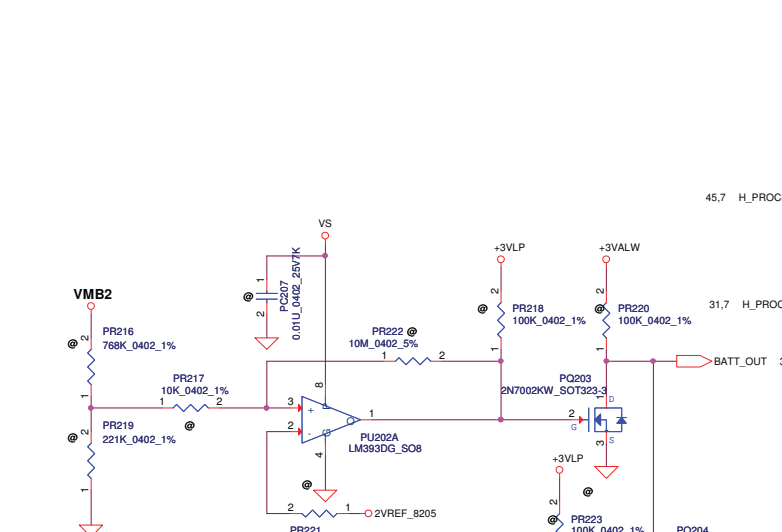
BATT ONLY

Precharge detector			
Min.	typ.	Max	
L->H	7.196V	7.349V	7.505V
H->L	6.138V	6.214V	6.056V



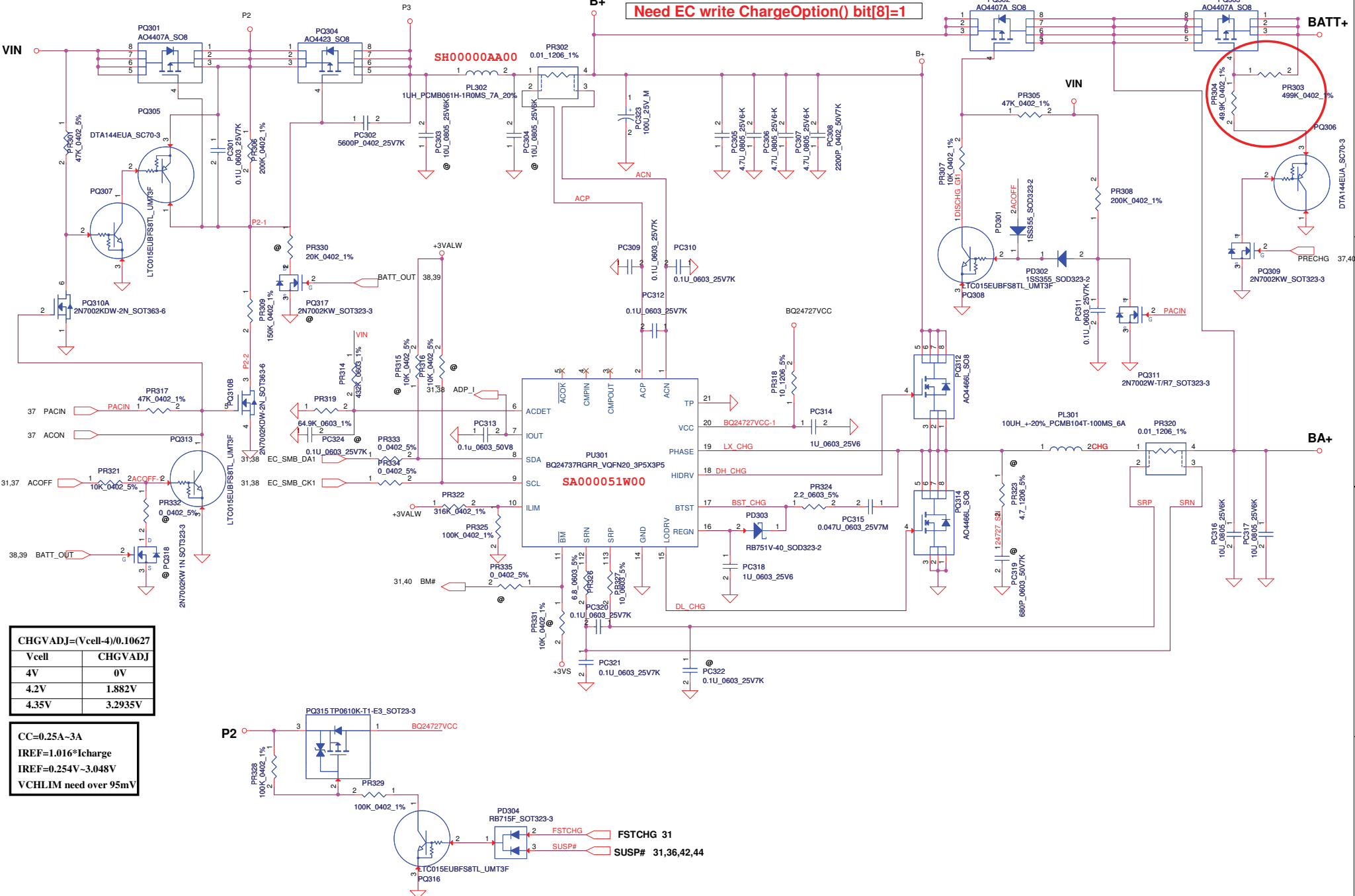
PH1 under CPU bottom side :
 CPU thermal protection at 93 +/-3 degree C
 Recovery at 56 +/-3 degree C

For KB930 --> Keep PU201 circuit
 (Vth = 1.25V)
 For KB9012 (Red square) --> Remove PU201 circuit, but keep PR206
 PH201



Security Classification	Compal Secret Data		Title Compal Electronics, Inc. PWR-BATTERY CONN/OTP
Issued Date	2011/04/18	Deciphered Date	
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.			
Size	Document Number	Rev	Date: Monday, January 16, 2012 Sheet 38 of 48
Custom	C38-G series Chief River Schematic	0.1	

Need EC write ChargeOption() bit[8]=1



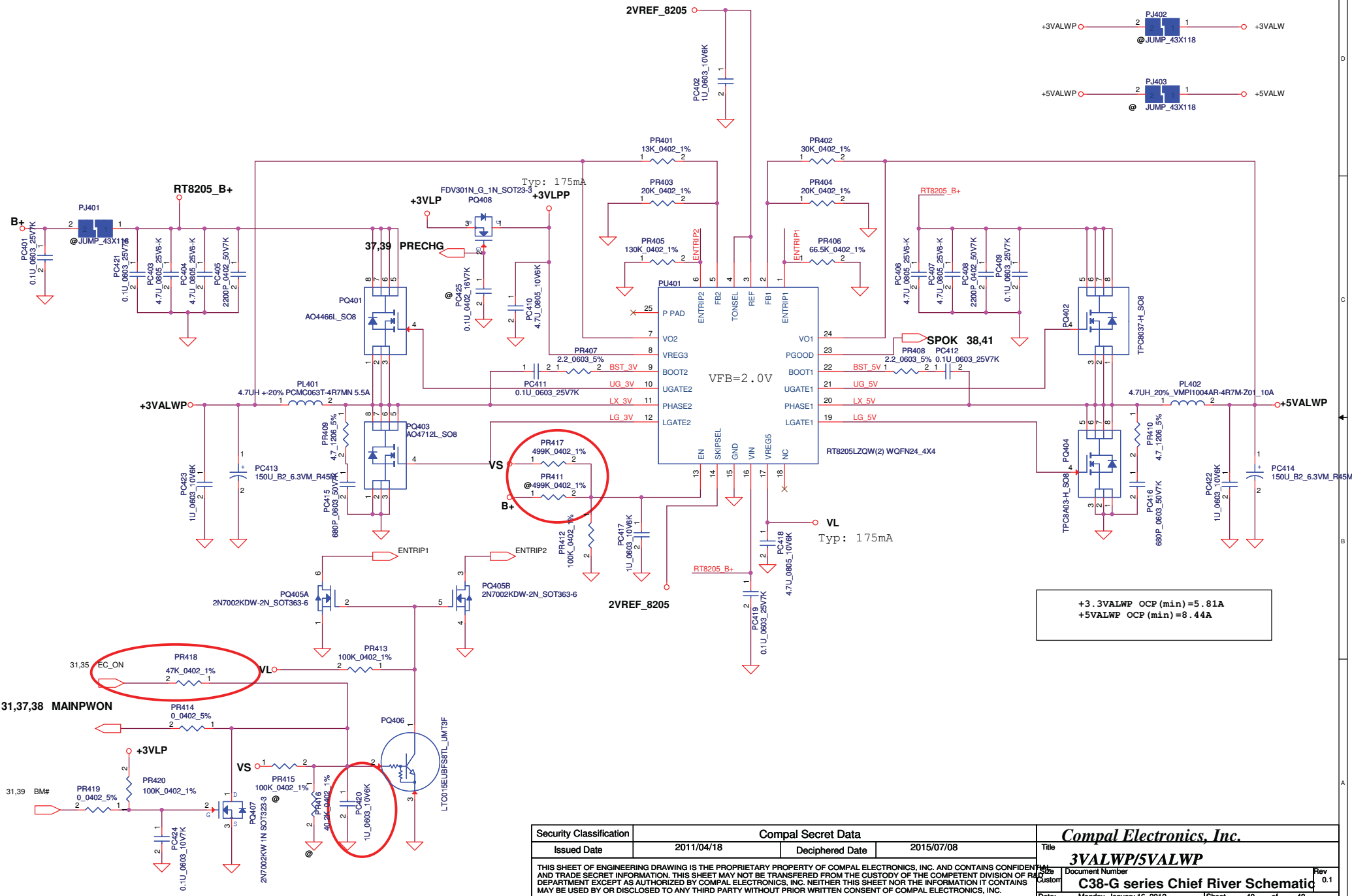
CHGVADJ=(Vcell-4)/0.10627	
Vcell	CHGVADJ
4V	0V
4.2V	1.882V
4.35V	3.2935V

CC=0.25A-3A
 IREF=1.016*Icharge
 IREF=0.254V~3.048V
 VCHLIM need over 95mV

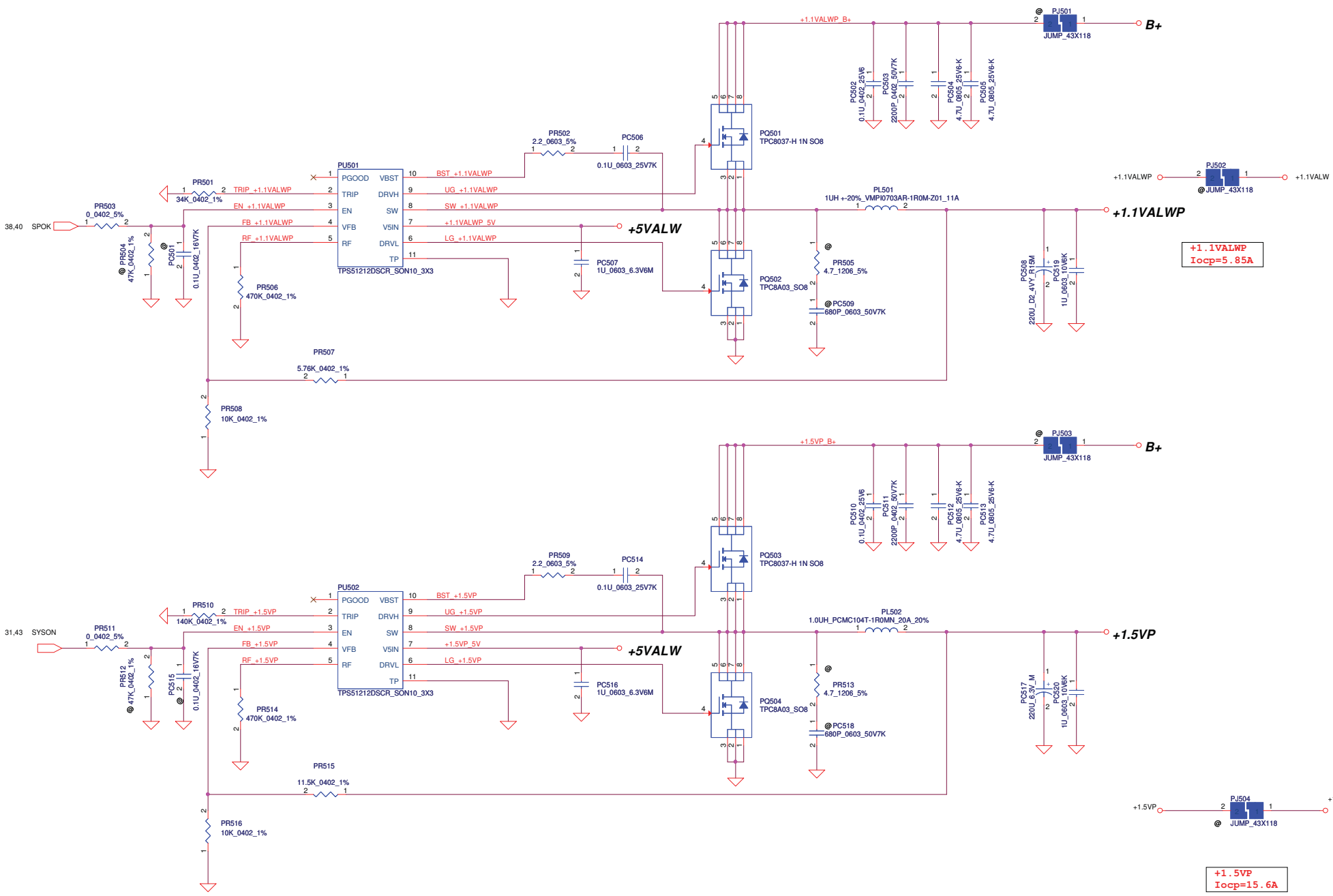
<http://hobi-elektronika.net>

Security Classification	Compal Secret Data		Compal Electronics, Inc.	
Issued Date	2011/04/18	Deciphered Date	2015/07/08	Title
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.				Document Number
				C38-G series Chief River Schematic
				Rev 0.1
				Date: Monday, January 16, 2012 Sheet 39 of 48

Note:
 Use TPS51125 IC can remove RTC refernece LDO
 Use TPS51427 IC must keep RTC refernece LDO



Security Classification	Compal Secret Data		Title 3VALWP/5VALWP
Issued Date	2011/04/18	Deciphered Date	
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.			File Number C38-G series Chief River Schematic Rev 0.1
Date:	Monday, January 16, 2012	Sheet	40 of 48



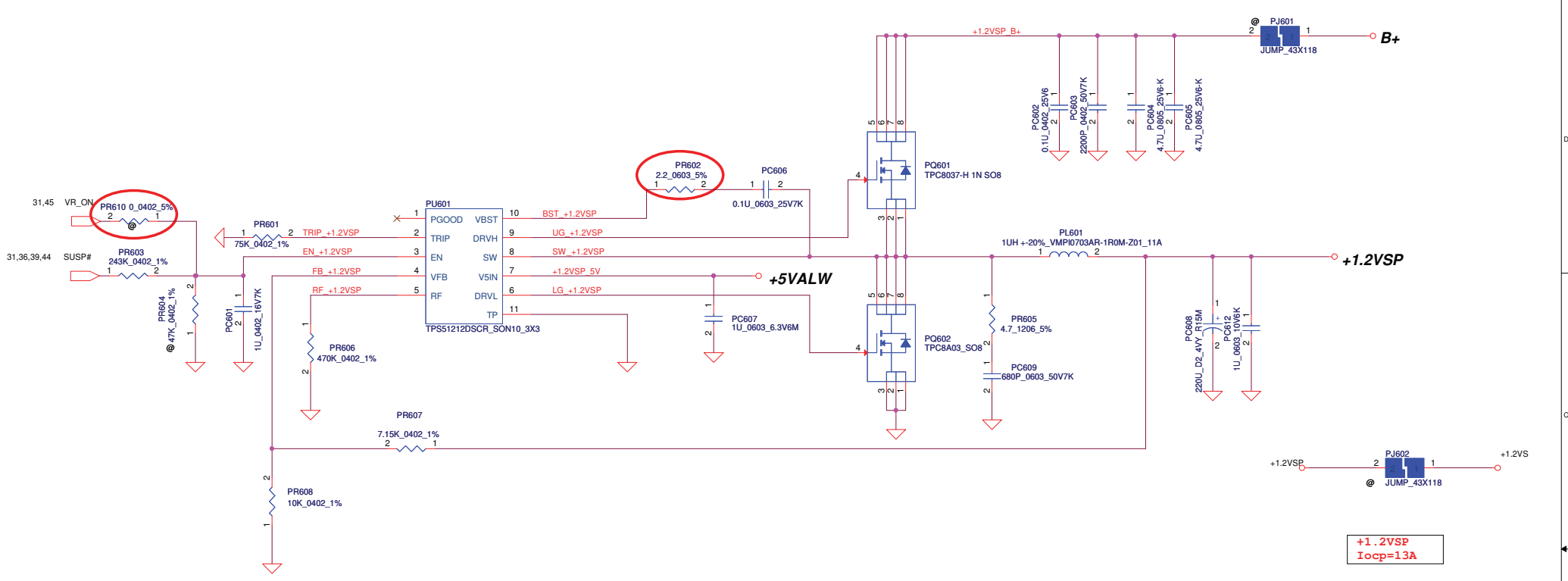
+1.1VALWP
I_{oCP}=5.85A

+1.5VP
I_{oCP}=15.6A

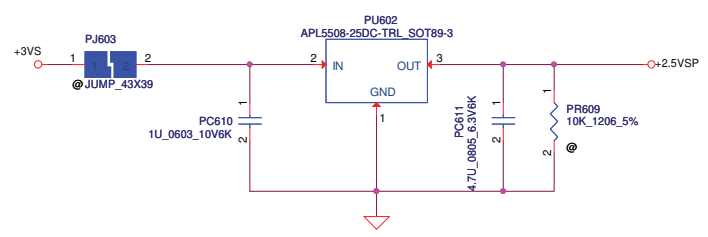
<http://hobi-elektronika.net>

Security Classification	Compal Secret Data			Title	
Issued Date	2011/04/18	Deciphered Date		+1.1VALWP/+1.5VP	
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.					
Size	Document Number	Rev	0.1		
Date:	Monday, January 16, 2012	Sheet	41	of 48	

Compal Electronics, Inc.

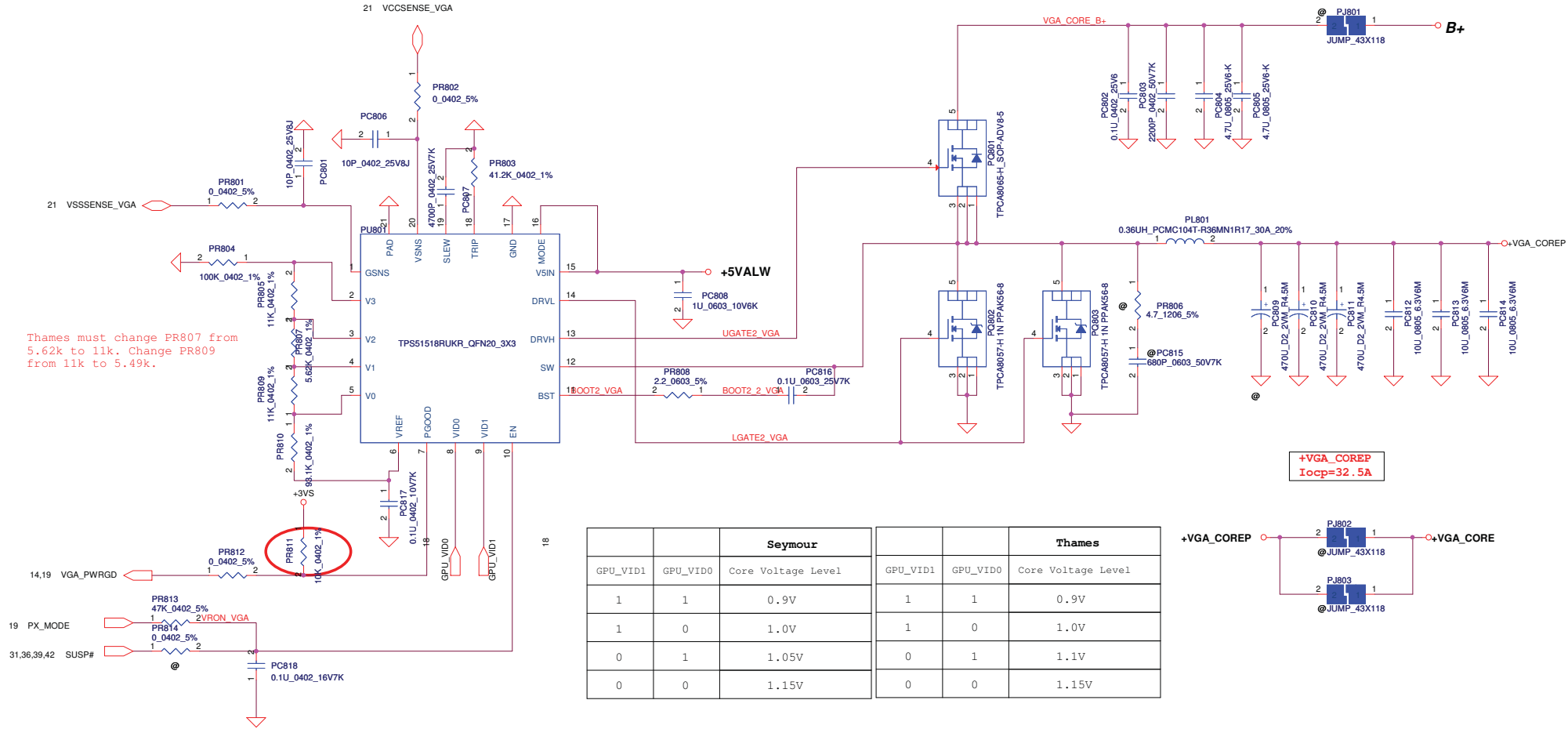


+1.2VSP
I_{oCP}=13A

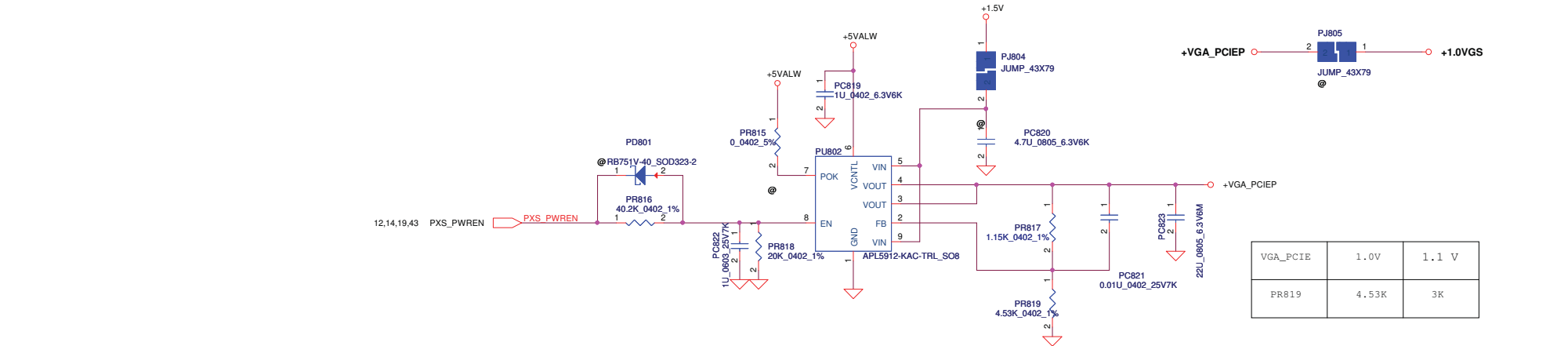


+2.5VSP
@ JUMP_43X39
(0.38A, 20mils, Via NO.=1)

Security Classification	Compal Secret Data		Compal Electronics, Inc.	
Issued Date	2011/04/18	Deciphered Date	Title	
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.			+1.2VSP/+2.5VSP	
Size	Document Number		Rev	0.1
Date:	Monday, January 16, 2012	Sheet	42	of 48

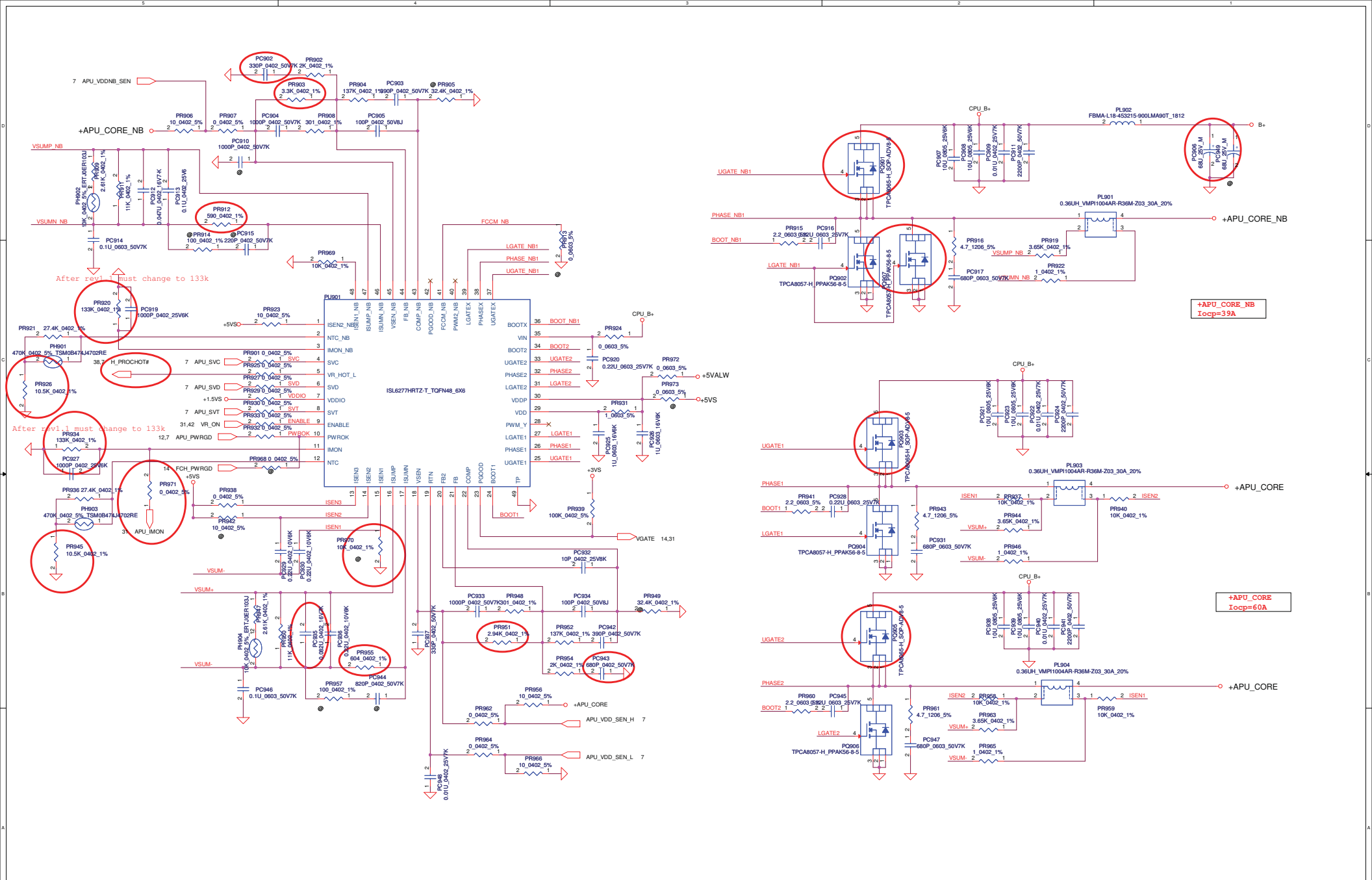


Seymour			Thames		
GPU_VID1	GPU_VID0	Core Voltage Level	GPU_VID1	GPU_VID0	Core Voltage Level
1	1	0.9V	1	1	0.9V
1	0	1.0V	1	0	1.0V
0	1	1.05V	0	1	1.1V
0	0	1.15V	0	0	1.15V

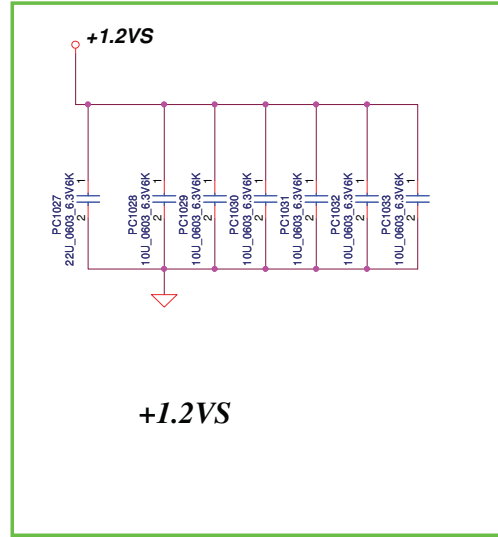
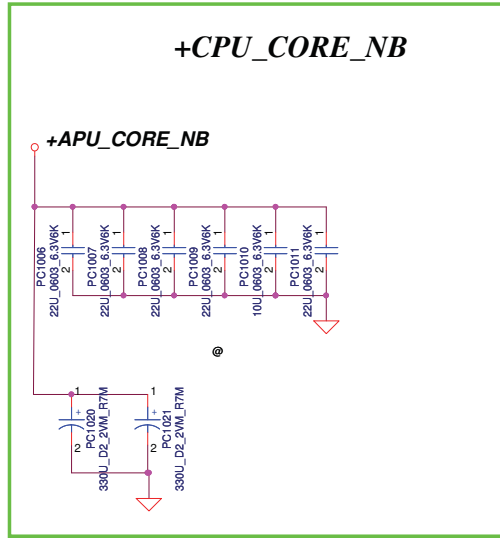
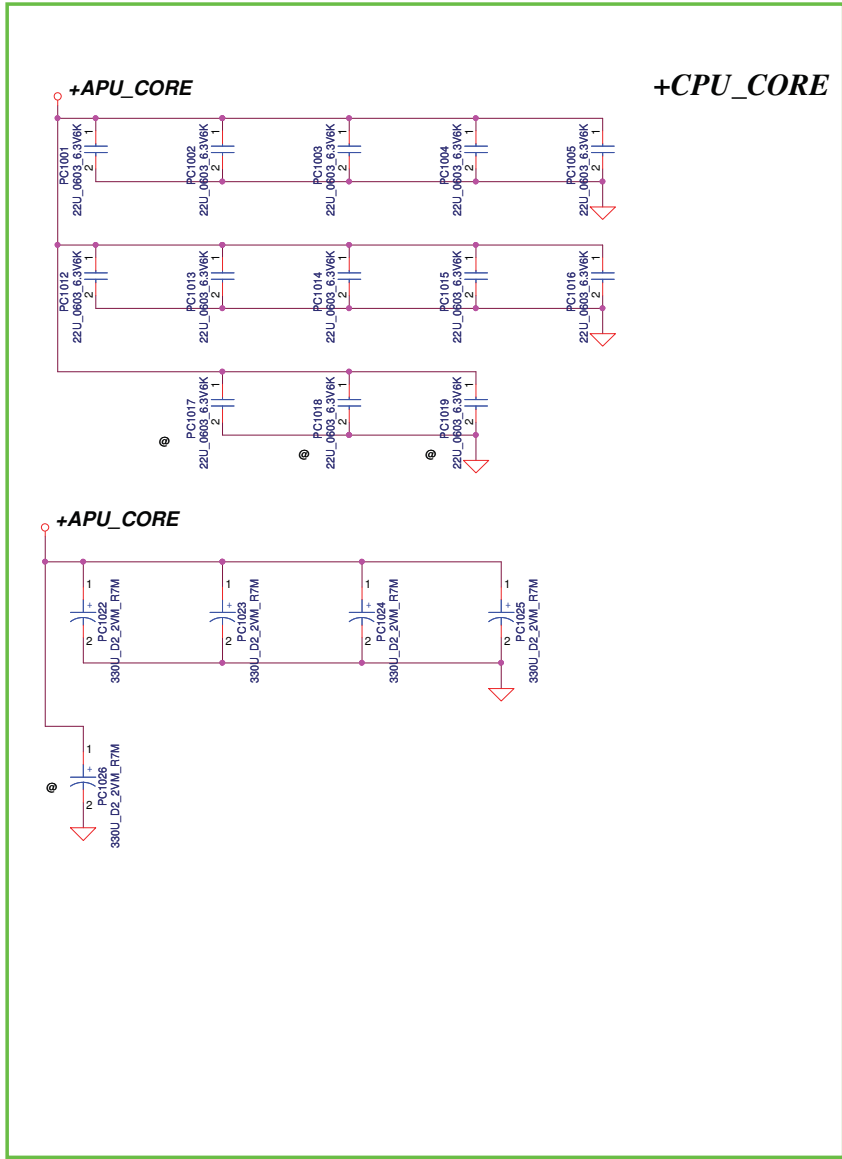


VGA_PCIE	1.0V	1.1 V
PR819	4.53K	3K

Security Classification	Compal Secret Data		Compal Electronics, Inc.	
Issued Date	2011/04/18	Deciphered Date	Title VGA_COREP	
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.			Document Number	Rev 0.1
Date:	Monday, January 16, 2012	Sheet	44	of 48



Security Classification	Compal Secret Data		Title	Compal Electronics, Inc.
Issued Date	2011/04/18	Deciphered Date	2015/07/08	CPU COREP
<small>THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.</small>				<small>Document Number</small> <small>Rev</small> 0.1
			Date: Monday, January 16, 2012	Sheet 45 of 48



Security Classification	Compal Secret Data			Compal Electronics, Inc. PROCESSOR DECOUPLING	
Issued Date	2011/04/18	Deciphered Date			
<small>THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.</small>					
Size	AS	Document Number		Rev	0.1
Date:	Monday, January 16, 2012	Sheet	46	of	48

Item	Reason for change	PG#	Modify List	Date	Phase
1					
2					
3					
4					
5					
6					
7					
8					
9					
10					
11					
12					
13					
14					
15					
16					
17					
18					
19					
20					

<http://hobi-elektronika.net>

Security Classification		Compal Secret Data		Compal Electronics, Inc.	
Issued Date	2011/04/18	Deciphered Date	2015/07/08	Title	PIR (PWR)
<small>THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF RESEARCH AND DEVELOPMENT DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.</small>				Document Number C38-G series Chief River Schematic	Rev 0.1
Date: Monday, January 16, 2012				Sheet	47 of 48

Phase	Date	No.	BOM	Sch	Layout	Description
SDV2	2011/09/13	No.1	V			Page29, install R1102, R1104, R1105 for audio noise prevention
	2011/09/14	No.2	V			page12~16, change FCH P/N from SA0000431C0 to SA0000431G0
	2011/09/16	No.3	V	V		Page35, Swap JCARD1 Pin3,4 to Pin9,10 PCIE TX & RX for CardReader no function issue
	2011/09/16	No.4	V	V		Page33, Modify JTF1 Pin1 to TP_DATA2, JTF1 Pin6 to TP_CLK2 for Click Pad no function issue
	2011/09/17	No.5	V	V		Page30, Modify JHDD1 Pin12 connect to GND for SATA Gen2
	2011/09/17	No.6	V			Page5~9, Modify U1 to JCPU1
	2011/09/17	No.7	V			Page10~11, SWAP JDIMM1 & JDIMM2
	2011/09/17	No.8	V			Page33, Modify JTF1 to JFP1,Modify JWLAM1 to JMINI1,Modify JLAN1 to JRJ45
	2011/09/17	No.9	V			Page31, Modify CLRPI to JCMOS1
	2011/09/26	No.10	V			Page31, POP U2201,C2200,R2229 for Security ROM Function not work issue
	2011/09/26	No.11	V			Page14, Modify D1103,D1104 to DIS8 for DIS only
	2011/09/28	No.12	V	V		Page34, Reserve R249, R2490 with CRX_C_TX_N1,PCIE_CRX_C_TX_P1 for PCIE WLAN RX AC Decoupling
	2011/09/28	No.13	V	V		Page29, R1111.2 Connect to U1101 Pin38 add net name CX_GPIO0 for vendor request
	2011/09/28	No.14	V	V		Page35, Add D2416 to replace D2414 for ESD request
	2011/09/28	No.15	V	V		Page5~9, Modify JCPU1 Footprint to LOTES_ACA_ZIF-109_722P-A39 for A39 DFX Rule
	2011/09/28	No.16	V	V		Page12~16, Modify U2 JUDSON PCBGA 656P-A39 for A39 DFX Rule
	2011/09/28	No.17	V	V		Page17~22, Modify U1401 Footprint to 2160809000A11SEY_FCBGA_962P-A39 for A39 DFX Rule
	2011/09/28	No.18	V	V		Page23~24, Modify U1405~U1412 Footprint to K4W1G1646E-HC12_FBGA_96P-A39 for A39 DFX Rule
	2011/09/28	No.19	V	V		Page31, Modify Board ID Table for AMD Build Plan Change
	2011/09/28	No.20	V	V		Page31, Modify R2209 for QALEA FVT Build Board IC Mapping
	2011/09/28	No.21	V	V		Page29, Add Signal Ring for USB30 [P..N][10..12]_C , D1104.1 for PX control enable delay
	2011/09/30	No.22	V			Page28, update JCRT1 Footprint from SUVIN_070546PR015S2002R_15P to C-H_13-12201558CP_15P-T for ME Conn modify
	2011/10/03	No.23	V			Page14, Add R2222~R2229 for USB30 [P..N][10..12]_C [P..N][10..12]_C for USB30 [P..N][10..12]_C
	2011/10/04	No.24	V	V		Page14, Add C222~C237 connect to all USB30 port near connector for AMD request that about USB Signal Driving
	2011/10/05	No.25	V	V		Page35, Add JDB3 Conn for SW Debug request
	2011/10/05	No.26	V	V		Page12, Add TP52~T58 on U2 GPIO input pin for debug
	2011/10/05	No.27	V	V		Page13, Add TP59~T61, TP67~T74 on U2 GPIO input pin for debug
	2011/10/05	No.28	V	V		Page14, Add TP52~T58 on U2 GPIO input pin for debug
	2011/10/06	No.29	V	V		Page26, Q2101 P/N change to SB00007H10 for Component common
	2011/10/06	No.30	V	V		Page35, JFPB1 update P/N to SP010002300 for Conn List update
	2011/10/06	No.31	V	V		Page35, JFPW1 update P/N to SP010002300 for Conn List update
	2011/10/06	No.32	V	V		Page35, JRJ45 update Footprint to ACES_50516-01841-P01_18P-T for Conn List update
	2011/10/06	No.33	V	V		Page32, JBT1 update P/N to SP02000TF00 for Conn List update
	2011/10/06	No.34	V	V		Page35, JCARD1 update Footprint to ACES_50224-0140N-001_14P-T for Conn List update
	2011/10/07	No.35	V	V		Page29, reserve D1101 for Audio Noise issue
	2011/10/11	No.36	V	V		Del TP52~T58 on U2 GPIO input pin for debug
	2011/10/11	No.37	V	V		Page13, Del TP59~T61, TP67~T74 on U2 GPIO input pin for debug
	2011/10/11	No.38	V	V		Page14, Add TP62~T93 on U2 GPIO input pin for debug
	2011/10/12	No.39	V			Page22, Replace R1476 P/N From D028100A00 to SD028100A80 for HF Part modify
	2011/10/12	No.40	V			Page19, 30, 36, Replace Q1409, Q2309, Q2410 P/N From SB0000124010 to SB000007000 for HF Part modify
	2011/10/13	No.41	V			Page12, Replace X1 P/N From SJ100003300 to SJ10000EL00 for Sourcer request (No Footprint, Use SJ10000DJ00)
	2011/10/13	No.42	V			Page12, Replace Y1 P/N From SJ132P7KW10 to SJ10000BM00 for Sourcer request
	2011/10/13	No.43	V			Page18, Replace V1400 P/N From SJ100006800 to SJ10000D000 for Sourcer request (No Footprint, Use SJ10000DJ00)
	2011/10/13	No.44	V			Page31, Replace U2200 P/N From SJ132P7KW10 to SJ10000BM00 for Sourcer request
	2011/10/13	No.45	V	V		Page31, Modify U2200 Pin107 EC_PXCNTROL to U2200 Pin108 for ABO Common Design
	2011/10/14	No.46	V	V		Page31, Add R2235 pull up to +3V3 for EPROCHOT#_EC
	2011/10/14	No.47	V	V		Page19, Replace Q1401,Q1402,Q1405 P/N from SB00000FG00 to SB00000FG10 for Sourcer request
	2011/10/17	No.48	V	V		Page26, Add C2144,C2145 1000P Caps connect to DMIC_CLK & DMIC_L2 for EMI Request(Noise issue)
	2011/10/17	No.49	V	V		Page25, Add R2171 connect to LVDS_HPD_R for Vendor Request (Noise Filtering)
	2011/10/17	No.50	V	V		Page7,9,27 Replace Q2,Q3,Q8,Q2106 P/N From SB000006A00 to SB000006A10 for HF Part modify
	2011/10/17	No.51	V	V		Page14, Del D1103,D1104 with CRT_DDC_DATA & CRT_DDC_CLK use EC Control for VGA Sequence tuning
	2011/10/17	No.52	V	V		Page19, Modify C1463,D1400,R1442 BOM Structure from DIS8 to FX400 & D1400 use u_0603_58 for FX50
	2011/10/17	No.53	V			Page7, Modify R65,R69 BOM Structure to @ for Power Leakage issue
	2011/10/17	No.54	V			Page12, Modify R80,R82 value from 0 ohm to 33 ohm for EMI Noise Issue
	2011/10/18	No.55	V	V		Page7, 31, Modify Input/output direction: H_PROCHOT#, Turbo_V
	2011/10/18	No.56	V	V		Page27, Add Net +5V5_HDMI on D2103 Pin5 & Pin6 for ESD Request
	2011/10/18	No.57	V			Page19, Modify R1454,Q1412,R1450,R1451,R1449,C1470,U1404,C1467,C1468,C1469,C1470 BOM Structure from PX40 to DIS8 for FX50 Function workable
	2011/10/19	No.58	V	V		Page31, Add Net APU_LMON on U2200 Pin76 for Power Team Request
	2011/10/19	No.59	V	V		Page35, Add intersheet of PLT_RST# on debug card
	2011/10/19	No.60	V	V		Page25, modify net name: LVDS_HPD_R to LVDS_HPD_C
	2011/10/20	No.61	V	V		Page33, Del A0AC circuit for Customer request
	2011/10/20	No.62	V	V		Page31, Del A0AC Powe Control Pin WLAN_POWER# for Customer request
	2011/10/20	No.63	V	V		Page14, Modify USB Signal net name from USB20_[P..N][10..12]_C to USB30_[P..N][10..12]_C for USB30 net name error
	2011/10/21	No.64	V	V		Page12, Modify R83,R84 value from 0 ohm to 33 ohm for EMI Noise Issue
	2011/10/21	No.65	V	V		Page31, Modify R2212,R2213 BOM Structure to @ for ENE Suggestion
	2011/10/21	No.66	V	V		Page31, Modify U2200 Pin 72 Net Name From AOU_LILIM to SPK_RT_Detect# for Speaker main stream & retail
	2011/10/21	No.67	V	V		Page31, Add R2236 pull up to +3V3 for SPK_RT_Detect#
	2011/10/21	No.68	V	V		Page35, Modify JAUD1 Pin20 Net Name From AOU_LILIM to GND , Pin17 From AOU_CTL1 to GND ,Pin4 From NC to AGNDFor USB Charger Function
	2011/10/21	No.69	V	V		Page29, Modify JSPEK1 P/N From DC030008W00 to SP02000N000 & Add JSPEK1 Pin5 connect to SPK_RT_Detect#,JSPEK1 Pin6 connect to GND for Speaker main stream & retail
	2011/10/21	No.70	V	V		Page31, Modify U2200 Pin120 Net Name From AOU_CTL1 to NC for USB Charger Function
	2011/10/24	No.71	V	V		Page29, reserve D1102 for Audio Noise issue
	2011/10/24	No.72	V			Page35, Modify D2415 BOM Structure to POP for ESD Request
	2011/10/24	No.73	V			Page33, Modify D2402,D2403 BOM Structure to POP for ESD Request
	2011/10/24	No.74	V			Page34, Modify D2402,D2403 BOM Structure to POP for ESD Request
	2011/10/24	No.75	V	V		Page26, Del R2116,R2117, Add R2172~R2176 & Reverse D2110 for PWM Power Leakage issue
	2011/10/24	No.76	V	V		Page30, Del C2404,Reserve C2471,C2405 for Intel Circuit Common
	2011/10/24	No.78	V	V		Page32, Modify R500 BOM Structure to @ for BOM Error
	2011/10/24	No.79	V	V		Page31, Del R2223~R2229, Q2200 to update Security ROM Circuit for Intel Circuit Common
	2011/10/24	No.80	V	V		Page35, Swap JRJ45 PCIE_CRX_DTX_P0 to PCIE_CRX_DTX_N0, PCIE_CTX_DRX_P0 to PCIE_CTX_DRX_N0 For LAN Board Common
	2011/10/24	No.81	V	V		Page35, Del R2462 to update Power OK circuit for Intel Circuit Common
	2011/10/24	No.82	V	V		Page36, Del R2300, R2310, C2312, R2317 update Power OK circuit for Intel Circuit Common
	2011/10/24	No.83	V			Page31, Modify R2235 BOM Structure to @ for H_PROCHOT#_EC
	2011/10/24	No.84	V			Page34, Modify D2404,D2406,D2408 P/N from SC300001D00 to SC300002800 for ESD Request
	2011/10/24	No.85	V			Page34, Modify D2404~D2409,L2400~L2408 BOM Structure from @ to POP for EMC Request
	2011/10/24	No.86	V			Page27, Modify L2105~L2108 BOM Structure from @ to POP for EMI Request
	2011/10/24	No.87	V			Page34, Modify L2402,L2405,L2408 P/N from SC300000I00 to SM070000000 for ESD Request (Footprint SM0700000I00)
	2011/10/24	No.88	V			Page34, Modify L2403, L2404, L2400, L2401, L2406, L2407 P/N from SC300000I00 to SM0700001500 for ESD Request
	2011/10/24	No.89	V			Page27, Modify D2102,D2103,D2105 P/N from SC300001Y00 to SC300002C00 for ESD Request
	2011/10/24	No.90	V			Page35, Modify D2413 P/N from SC300001600 to SC300001200 for EMI Request
	2011/10/25	No.91	V	V		Page29, Modify JSPEK1 P/N From SP02000N000 to SP030008W00 for LD Requirement
	2011/10/25	No.92	V	V		Page29, Add R1140 connect to SPK_RT_Detect# to GND for Speaker Verify
	2011/10/25	No.93	V	V		Page28, Del Q2412 with CRT_DDC_DATA & CRT_DDC_CLK for AMD Design Guide Require
	2011/10/26	No.94	V	V		Page26, Del R2122,R2123,R2124 with EDID_DATA & EDID_CLK pull up for Duplicate Pull up error
	2011/10/26	No.95	V	V		Page26, Modify R2174 BOM Structure to @ for BOM Error
	2011/10/26	No.96	V	V		Page25, Reserve R2116, R2117 to Connect from CSCL & CSCA to EC_SMB_DA2 & EC_SMB_CB2 for Power Leakage issue
	2011/10/26	No.97	V	V		Page29, Modify D1101, D1102 BOM Structure From @ to POP for Audio Noise issue
	2011/10/27	No.98	V	V		Page24, Modify U2416 P/N from SC300001000 to SC300001000 for ESD Request
	2011/10/27	No.99	V	V		Page29, Modify C1111 ,C1141 BOM Structure From POP to @ for Audio Noise issue

<http://hobi-elektronika.net>

Security Classification		Compal Secret Data		Compal Electronics, Inc.		
Issued Date	2008/08/10	Deciphered Date	2011/03/04	Title	EE modify list	
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.						
Size	Document Number			Rev		
Customer	LA-7121P			0.4		
Date:	Monday, January 16, 2012	Sheet	48	of	50	

Phase	Date	No.	BOM	Sch	Layout	Description
FVT	2011/11/14	No.1	V			Page17-24, Modify U1401 P/N From SA000047H00 to SA000047H50 for GPU Version update
	2011/11/14	No.2	V			Page36, Modify R2305 P/N From SD028200280 (20K_0402_5%) to SD028150380 (150K_0402_5%) for Power Consumption & Power Sequence tuning
	2011/11/14	No.3	V			Page36, Modify R2304 P/N From SD028470280 (47K_0402_5%) to SD028470380 (470K_0402_5%) for Power Consumption & Power Sequence tuning
	2011/11/14	No.4	V			Page36, Modify R2315 P/N From SD028750280 (75K_0402_5%) to SD028220380 (220K_0402_5%) for Power Consumption & Power Sequence tuning
	2011/11/14	No.5	V			Page34, Modify R2442-R2459 BOM Structure From POP to @ for EMI Request
	2011/11/14	No.6	V			Page27, Modify R2126-R2133 BOM Structure From POP to @ for EMI Request
	2011/11/14	No.7	V	V	V	Page14, Replace C222-C237 to R216-R231 on all usb port signal for AMD Design checklist update (USB no function issue)
	2011/11/14	No.8	V	V	V	Page19, Add R1461 to connect PKS_FWR_EN# for RUNFWOK for PX50 Power Enable
	2011/11/14	No.9	V	V	V	Page14, Remove R230-R231 on all usb port signal for AMD Design checklist update (USB no function issue)
	2011/11/15	No.10	V	V	V	Page35, Remove D2415 for ESD Request
	2011/11/21	No.11	V	V	V	Page30, Reserve R2411,C2421 for G Sensor Vendor Suggestion
	2011/11/21	No.12	V	V	V	Page31, Add J2200,J2201 to improve EC Power Source +3VLP or +3VALW to +3VALW_EC Power Source Option and modify +3VALW Net Name to +3VALW_EC for Lenovo S4 Lid Function
	2011/11/21	No.13	V	V	V	Page31, Update Borad ID table for FVT Phase
	2011/11/21	No.14	V	V	V	Page31, Modify R2209 From 8.2K to 18K for FVT BRDID update
	2011/11/21	No.15	V	V	V	Page30, C2417 BOM Change from 10U (SE000005T80) to 10K (SD013100280) for G Sensor Vendor Suggestion
	2011/11/21	No.16	V	V	V	Page36, Add R2321,R2322,C2317,C2318,C2319,Q2313,Q2314 for +3V_FCH Power Control
	2011/11/21	No.17	V	V	V	Page31, U2200 Pin70 Add_FCH_FWR_EN# for +3V_FCH Power Control
	2011/11/22	No.18	V	V	V	Page35, Add R2481 Pull up to +3VLP & Reserve R2482 Pull up to +3VALW for Lenovo S4 LID Function
	2011/11/22	No.19	V			Page18, Y1400 P/N From SJ10000Y000 to SJ10000CV00 for BOM Change
	2011/11/22	No.20	V			Page12, X1 P/N From SJ10000E000 to SJ10000CX00 for BOM Change
	2011/11/22	No.21	V	V	V	Page25, Modify R2117 connect to TL_DATA & R2116 connect to TL_CLK, Two signals connect to R2177,R2178 pull up to +3VS for LVDS Translator EEPROM Reserve
	2011/11/22	No.22	V	V	V	Page31, Modify U2200 Pin86 EAPD to TL_DATA & Add U2200 Pin85 TL_CLK Two signals connect to R2177,R2178 pull up to +3VS for LVDS Translator EEPROM Reserve Function
	2011/11/22	No.23	V	V	V	Page31, Add U2200 Pin26 EAPD_R for LVDS Translator EEPROM Reserve Function
	2011/11/22	No.24	V	V	V	Page31, Add R2223 & R2224 to option EAPD GPIO Output signal from Pin26 (EAPD_R) or Pin86 (TL_DATA) for LVDS Translator EEPROM Reserve Function
	2011/11/23	No.25	V	V	V	Page14, Del R216-R229 for USB2.0 Signals tuning circuit remove
	2011/11/23	No.26	V	V	V	Page14, Reserve R230-R234 & C222-C226 with USB2.0 N signals port 0,6,10,11,12 for AMD Suggestion
	2011/11/24	No.27	V	V	V	Page36, Del R2321,R2322,C2317,C2318,C2319,Q2313,Q2314 for +3V_FCH Power Control
	2011/11/24	No.28	V	V	V	Page31, U2200 Pin70 Del_FCH_FWR_EN# for +3V_FCH Power Control
	2011/11/24	No.29	V	V	V	Page29, Modify J5PK1 P/N from DC030008W00 to DC030009100 for ME Connector List update
	2011/11/24	No.30	V	V	V	Page31, U2200 Pin127 Add_VSB_ON & Reserve R2226 for +VSB Power Control
	2011/11/25	No.31	V	V	V	Page31, Modify R2217, R2218 Power Source from +3VS to +3VALW for +3VGS Power Leakage issue
	2011/11/25	No.32	V	V	V	Page18, Install Q1400, R1427, R1428 & Remove R1433, R1435 for +3VGS Power Leakage issue
	2011/11/25	No.33	V	V	V	Page33, Modify H10 & H22 From NPTH to PTH For ME Drawing Lose
	2011/11/25	No.34	V	V	V	Page31, Del R2226 for VSB_ON resistor double reserve
	2011/11/26	No.35	V	V	V	Page31, Add R2226,R2227 Pull up to +3VS & Reserve R2217,R2218 pull up to +3VALW for SMBUS Leakage issue
	2011/11/28	No.36	V	V	V	Page7, Del R65,R69 & Reserve R45 & R45 with APU_SID & APU_SIC By Pass APU_SID_R & APU_SIC_R for SMBUS Power Leakage Issue
	2011/11/28	No.37	V	V	V	Page31, Reserve C2219,C2210 to +3VALW For SMBUS2 AC Decoupling
	2011/11/28	No.38	V	V	V	Page31, Del C2213,C2214 & Modify R2226,R2227 BOM Structure to @ & R2217,R2218 to POP For SMBUS Power Leakage Issue
	2011/11/29	No.39	V			Page7, Modify R45,R48 BOM Structure to POP & Q9 to @ For SMBUS Power Leakage issue
	2011/11/29	No.40	V			Page36, Modify R2309 P/N from SD028750180 (7.5K) to SD028150380 (150K) for Power Sequence tuning
	2011/11/29	No.41	V			Page36, Modify C2316 P/N from SE042104K80 (0.1U) to SE080105K80 (1U) for Power Sequence tuning
	2011/11/29	No.42	V			Page19, Modify R1450 P/N from SD028150380 (150K) to SD028130380 (130K) for Power Sequence tuning
	2011/11/29	No.43	V			Page19, Modify C1478 P/N from SE042104K80 (0.1U) to SE080105K80 (1U) for Power Sequence tuning
	2011/11/30	No.44	V			Page13, Modify U4 P/N from SA000041P00 (MXIC) to SA00003K800 (Winbond) for ROM Part Issue
	2011/11/30	No.45	V			Page19, Modify C1470 P/N from SE080105K80 (1U) to SE042104K80 (0.1U) for Power Sequence tuning
	2011/11/30	No.46	V			Page19, Modify R1450 P/N from SD028150380 (130K) to SD028200280 (20K) for Power Sequence tuning
	2011/11/30	No.47	V			Page19, Modify R1449 P/N from SD028200280 (20K) to SD028330380 (330K) for Power Sequence tuning
	2011/11/30	No.48	V			Page35, unmount R2482 and mount R2481 for LID SW function implement when SMT
	2011/11/30	No.49	V			Page29, unmount R1140 because 14" is no need to select mainstream and retail
	2011/12/02	No.50	V			Page12, Modify C129 P/N from SE071150J80 (15P) to SE071220J80 (22P) For Crystal Clock Tuning
	2011/12/02	No.51	V			Page12, Modify C130 P/N from SE071150J80 (15P) to SE071270J80 (27P) For Crystal Clock Tuning
	2011/12/02	No.52	V			Page12, Modify C131,C134 P/N from SE071270J80 (27P) to SE071330J80 (33P) For Crystal Clock Tuning
	2011/12/02	No.53	V			Page18, Modify C1445,C1446 P/N from SE071120J80 (12P) to SE071200J80 (20P) For Crystal Clock Tuning
	2011/12/05	No.54	V			Page26, Modify C2144,C2145 BOM Structure to @ for DMIC no function issue
MEMO	2011/12/09	No.55	V			Page35, unmount R2482 and mount R2481 for LID SW function implement when SMT
	2011/12/09	power				power schematics 20110208.dsn

<http://hobi-elektronika.net>

Security Classification		Compal Secret Data		Compal Electronics, Inc.	
Issued Date	2008/08/10	Deciphered Date	2011/03/04	Title	
				EE modify list	
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.				Size	Document Number
				Custom	LA-7121P
				Date	Monday, January 16, 2012
				Sheet	49 of 50
				Rev	0.4

Phase	Date	No.	BOM	Sch	Layout	Description
SIT	2012/01/03	No.1	V	V	V	Page31, Add R2228 connect from MAINPWON_R to MAINPWON for Power Circuit update
	2012/01/03	No.2	V	V	V	Page31, Modify R2236 BOM Structure from POP to 0 for +3VS Power Leakage Issue
	2012/01/04	No.3	V	V	V	Page7, delete Q9, short and remove 0 ohm: R45&R48
	2012/01/04	No.4	V	V	V	Page7,9,13, short and remove R64&R68, change Page13 net name ML_VGA_HPD, change page7 net name LVDS_HPD
	2012/01/04	No.5	V	V	V	Page15, Modify +VDDAN_11_USB power source from +1.1VALW to +1.1V_FCH for reduce power consumption
	2012/01/04	No.6	V	V	V	Page15, Modify +VDDCR_11V_USB power source from +1.1VALW to +1.1V_FCH for reduce power consumption
	2012/01/04	No.7	V	V	V	Page15, Modify +VDDAN_11_SSUSB & +VDDCR_11_SSUSB power source from +1.1VALW to +1.1V_FCH for reduce power consumption
	2012/01/04	No.8	V	V	V	Page15, Modify +VDDIO_33 power source from +3V_FCH to +3VALW for reduce power consumption
	2012/01/04	No.9	V	V	V	Page15, Modify +VDDXL_3.3V power source from +3V_FCH to +3VALW for reduce power consumption
	2012/01/04	No.10	V	V	V	Page15, Modify +VDDPL_11_SYS_S power source from +1.1VALW to +1.1V_FCH for reduce power consumption
	2012/01/04	No.11	V	V	V	Page15, Modify +VDDAN_11_HMM power source from +3V_FCH to +3VALW for reduce power consumption
	2012/01/04	No.12	V	V	V	Page34, Modify R1914, R2318, R2320, R2311 BOM Structure from 0 to POP for Reduce Power Consumption
	2012/01/04	No.13	V	V	V	Page36, Add Q2313, Q2314, U2304, C2309, C2312, C2321, R2323, R2310, R2324 for +3VALW to +3V_FCH Circuit (Reduce Power Consumption)
	2012/01/04	No.14	V	V	V	Page36, Add Q2316, Q2309, U2303, C2317, C2320, C2318, C2319, R2322, R2317 for +1.1VALW to +1.1V_FCH Circuit (Reduce Power Consumption)
	2012/01/04	No.15	V	V	V	Page17, Remove R207 for component part reduce
	2012/01/04	No.16	V	V	V	Page29, Remove R471 & R472 for component part reduce
	2012/01/04	No.17	V	V	V	Page29, Remove R1106, R1107, R1119, R1134, R1109 for component part reduce
	2012/01/04	No.18	V	V	V	Page35, Remove R2465, R2466 for component part reduce
	2012/01/04	No.19	V	V	V	Page33, Reserve R2485 & R2485 to connect EC_SMB_CK2 & EC_SMB_DA2 for Lenovo Multi-Touch function
	2012/01/04	No.20	V	V	V	Modify R2201 netname from Q1L to Q1L for component part reduce
	2012/01/04	No.21	V	V	V	Page26, Del R2176 to connect to EC_INVFWM for common QILEX
	2012/01/05	No.22	V	V	V	Page14, Add R146 & R148 for component part reduce
	2012/01/05	No.23	V	V	V	Modify +VDDAN_11_USB power source from +1.1V_FCH to +1.1V_FCH for component part reduce
	2012/01/05	No.24	V	V	V	Page36, Modify +1.1V_FCH netname to +1.1V_FCH for component part reduce
	2012/01/05	No.25	V	V	V	Page15, Modify +VDDAN_11_USB_S power source from +1.1V_FCH to +1.1V_FCH for reduce power consumption
	2012/01/05	No.26	V	V	V	Page15, Modify +VDDCR_11V_USB power source from +1.1V_FCH to +1.1V_FCH for reduce power consumption
	2012/01/05	No.27	V	V	V	Page15, Modify +VDDAN_11_SSUSB & +VDDCR_11_SSUSB power source from +1.1V_FCH to +1.1V_FCH for reduce power consumption
	2012/01/05	No.28	V	V	V	Page15, Modify +VDDIO_33 power source from +3VALW to +3VS_FCH for reduce power consumption
	2012/01/05	No.29	V	V	V	Page15, Modify +VDDIO_33_S power source from +3VALW to +3VS_FCH for reduce power consumption
	2012/01/05	No.30	V	V	V	Page15, Modify +VDDXL_3.3V power source from +3VALW to +3VS_FCH for reduce power consumption
	2012/01/05	No.31	V	V	V	Page15, Modify +VDDPL_11_SYS_S power source from +1.1V_FCH to +1.1V_FCH for reduce power consumption
	2012/01/05	No.32	V	V	V	Page15, Modify +VDDAN_33_HMM power source from +3VALW to +3VS_FCH for reduce power consumption
	2012/01/05	No.33	V	V	V	Page29, Remove R1108, R1135, R1110, C1127 for component part reduce
	2012/01/05	No.34	V	V	V	Page31, Remove Pin25 EC_INVF_PWM for Circuit Common
	2012/01/05	No.35	V	V	V	Page31, Modify EC_U2200 I1Pin from +3VALW_EC to +3VLP for S4 LID Function (common QILEX)
	2012/01/05	No.36	V	V	V	Modify +VDDAN_11_USB power source from +1.1V_FCH to +1.1V_FCH for component part reduce
	2012/01/05	No.37	V	V	V	Page15, Modify +VDDAN_33_USB power source from +3VS_FCH to +3V_FCH for reduce power consumption
	2012/01/05	No.38	V	V	V	Page15, Modify +VDDPL_33_SSUSB_S power source from +3VS_FCH to +3V_FCH for reduce power consumption
	2012/01/05	No.39	V	V	V	Page15, Modify +VDDPL_33_USB_S power source from +3VS_FCH to +3V_FCH for reduce power consumption
	2012/01/05	No.40	V	V	V	Page15, Modify +VDDIO_33_S power source from +3V_FCH to +3VALW for reduce power consumption
	2012/01/05	No.41	V	V	V	Page15, Modify +VDDAN_33_HMM power source from +3V_FCH to +3VALW for reduce power consumption
	2012/01/05	No.42	V	V	V	Page36, Add R2302 from +1.1VALW to +1.1V_FCH for reduce power consumption
	2012/01/05	No.43	V	V	V	Page36, Modify U2304 Power source from +3V_FCH to +3V for reduce power consumption
	2012/01/05	No.44	V	V	V	Page36, Add J2303 from +3VALW to +3V for reduce power consumption
	2012/01/05	No.45	V	V	V	Page36, Modify U2303 Power source from +1.1V_FCH to +1.1V for reduce power consumption
	2012/01/05	No.46	V	V	V	Page36, Modify J2302 From +1.1V_FCH to +1.1V for reduce power consumption
	2012/01/05	No.47	V	V	V	Page15, Modify +VDDAN_11_USB_S power source from +1.1V_FCH to +1.1V for reduce power consumption
	2012/01/05	No.48	V	V	V	Page15, Modify +VDDCR_11V_USB power source from +1.1V_FCH to +1.1V for reduce power consumption
	2012/01/05	No.49	V	V	V	Page15, Modify +VDDAN_11_SSUSB & +VDDCR_11_SSUSB power source from +1.1V_FCH to +1.1V for reduce power consumption
	2012/01/05	No.50	V	V	V	Page15, Modify +VDDPL_11_SYS_S power source from +1.1V_FCH to +1.1V for reduce power consumption
	2012/01/05	No.51	V	V	V	Page15, Modify +VDDAN_33_USB power source from +3V_FCH to +3V for reduce power consumption
	2012/01/05	No.52	V	V	V	Page15, Modify +VDDPL_33_SSUSB_S power source from +3V_FCH to +3V for reduce power consumption
	2012/01/05	No.53	V	V	V	Page15, Modify +VDDPL_33_USB_S power source from +3V_FCH to +3V for reduce power consumption
	2012/01/05	No.54	V	V	V	Page15, Modify +VDDIO_33_S power source from +3VALW to +3V_FCH for reduce power consumption
	2012/01/05	No.55	V	V	V	Page15, Modify +VDDAN_33_HMM power source from +3VALW to +3V_FCH for reduce power consumption
	2012/01/06	No.56	V	V	V	Page15, Modify +VDDXL_3.3V power source from +3V_FCH to +3V for reduce power consumption
	2012/01/09	No.57	V	V	V	Page33, Add R2493, R2492, R2491, R2494, Q2403, Q2400, C2494, C2493 for AOAC Power Circuit
	2012/01/09	No.58	V	V	V	Page31, U2200 add netname FCH_PWR_EN# on Pin70 for +3V & +1.1V Power Control
	2012/01/09	No.59	V	V	V	Page36, Add R2325 from FCH_PWR_EN# to FCH_PWR_EN# for +3V & +1.1V Power Control
	2012/01/09	No.60	V	V	V	Page36, Add FCH_PWR_EN#_R on Q2313.2, Q2314.2, Q2315.2, Q2309.2 for +3V & +1.1V Power Control Enable Option
	2012/01/09	No.61	V	V	V	Page33, Modify JMIN11 pin1 from FCH_PCIE_WAKE# to WLAN_WAKE# for AOAC Function
	2012/01/09	No.62	V	V	V	Page31, Modify U2200 Pin26 from EAPD_R to WLAN_WAKE# for AOAC Function
	2012/01/09	No.63	V	V	V	Page31, Add U2200 Pin19 from NC to EAPD_R for Audio Function
	2012/01/09	No.64	V	V	V	Page31, Add U2200 Pin91 from NC to AOAC_WLAN for AOAC Function
	2012/01/10	No.65	V	V	V	Page31, Modify U2200 Pin19 net name from ODD_DA# to WL_OFF_EC# for Circuit common with Intel
	2012/01/10	No.66	V	V	V	Page30, Del R2435 for component reduce
	2012/01/10	No.67	V	V	V	Page33, Add R2496 & reserve R2495 for RF_OFF# source option
	2012/01/10	No.68	V	V	V	Page33, Modify JMIN11 Pin20 net name from WL_OFF# to RF_OFF# for Circuit common with Intel
	2012/01/10	No.69	V	V	V	Page31, Modify R2205 BOM Structure to 0 for Common Circuit with Intel
	2012/01/10	No.70	V	V	V	Page31, Modify R2232, R2230 from 10K to 100K & Modify R2202, R2230, R2232 pull up from +3VALW_EC to +3VALW for Common Circuit with Intel
	2012/01/11	No.71	V	V	V	Page31, Modify L2200.1 Power Source from +3VALW to +3VALW_EC for EC_AVCC Power Leakage Issue
	2012/01/11	No.72	V	V	V	Page31, BRDID Table update for SIT Build
	2012/01/11	No.73	V	V	V	Page31, Modify R2209 from 18K to 33K for FVT BRDID update
	2012/01/11	No.74	V	V	V	Page26, Modify R2166 P/N from SD028330080 (33ohm) to SD034499180 (4.99K) for logo led brightness fine tune
	2012/01/11	No.75	V	V	V	Page35, Remove R2469 for logo led brightness fine tune

MEMO	2012/01/11	No.76	V	V	V	Page18, Modify C1445, C1446 P/N from SE071200JN0 to SE071200J80 for FVT SMT Memo
	2012/01/11	No.77	V	V	V	Page36, Modify C2316 P/N from SE080105K80 to SE0000069L0 for FVT SMT Memo
	2012/01/11	No.78	V	V	V	Page26, Add C2144, C2145 P/N SE071220J80 (22P) for FVT SMT Memo
	2012/01/11	No.79	V	V	V	Page36, Add Q2317 to Replace U2303 for +1.1V Power Mos layout space not enough issue
	2012/01/11	No.80	V	V	V	Page36, Add Q2318 to Replace U2304 for +3V Power Mos layout space not enough issue
	2012/01/11	No.81	V	V	V	Page29, Modify R1102, R1104, R1105 BOM Structure to 0 for Vendor suggestion
	2012/01/12	No.82	V	V	V	Page36, Modify R2323.1 & R2322.1 from +VSB to +5VALW for VGS over spec issue
	2012/01/12	No.83	V	V	V	Page36, Modify Q2317 & Q2318 P/N: from SB0000L0000 to SB923050030 for VGS over spec issue
	2012/01/12	No.84	V	V	V	Page31,35 Modify U2200 Pin70 Net name from FCH_PWR_EN# to FCH_PWR_EN# for +3V & +1.1V power control solution change
	2012/01/12	No.85	V	V	V	Page36, Modify R2325 to POP from FCH_PWR_EN to FCH_PWR_EN# for +3V & +1.1V Power Control
	2012/01/12	No.86	V	V	V	Page36, Delete R2314, R2318, R2320, Q2311 for Reduce Power Consumption
	2012/01/16	No.87	V	V	V	Page31, Modify R2230 BOM Structure from POP to 0 for double pull up error
	2012/01/16	No.88	V	V	V	Page31, Modify R2208 BOM Structure from POP to 0 for internal pull high solution

<http://hobi-elektronika.net>

Security Classification		Compal Secret Data		Compal Electronics, Inc.	
Issued Date	2008/08/10	Deciphered Date	2011/03/04	Title	
				EE modify list	
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.					
Size	Document Number			Rev	0.4
Custom	LA-7121P				
Date:	Monday, January 16, 2012	Sheet	50	of	50